

SYSTEM DC/DC APL5916KAI 48		CPU DC/DC NCP6131S52MNR 42-43	
INPUTS	OUTPUTS	INPUTS	OUTPUTS
1D05V_PWR	0D85V_S0	DCBATOUT	VCC_CORE

SYSTEM DC/DC UP6128PQDD 45	
INPUTS	OUTPUTS
DCBATOUT	1D05V_VTT

SYSTEM DC/DC UP6183PQAG 41	
INPUTS	OUTPUTS
DCBATOUT	5V_AUX_S5 3D3V_AUX_S5 5V_S5 3D3V_S5

SYSTEM DC/DC UP6165BQKF 46	
INPUTS	OUTPUTS
DCBATOUT	1D5V_S3 0D75V_S0 DDR_VREF_S3

SYSTEM DC/DC NCP5911MNTBG 44	
INPUTS	OUTPUTS
DCBATOUT	VCC_GFXCORE_PWR

VGA RT8208BGQW 92	
INPUTS	OUTPUTS
DCBATOUT	VGA_CORE

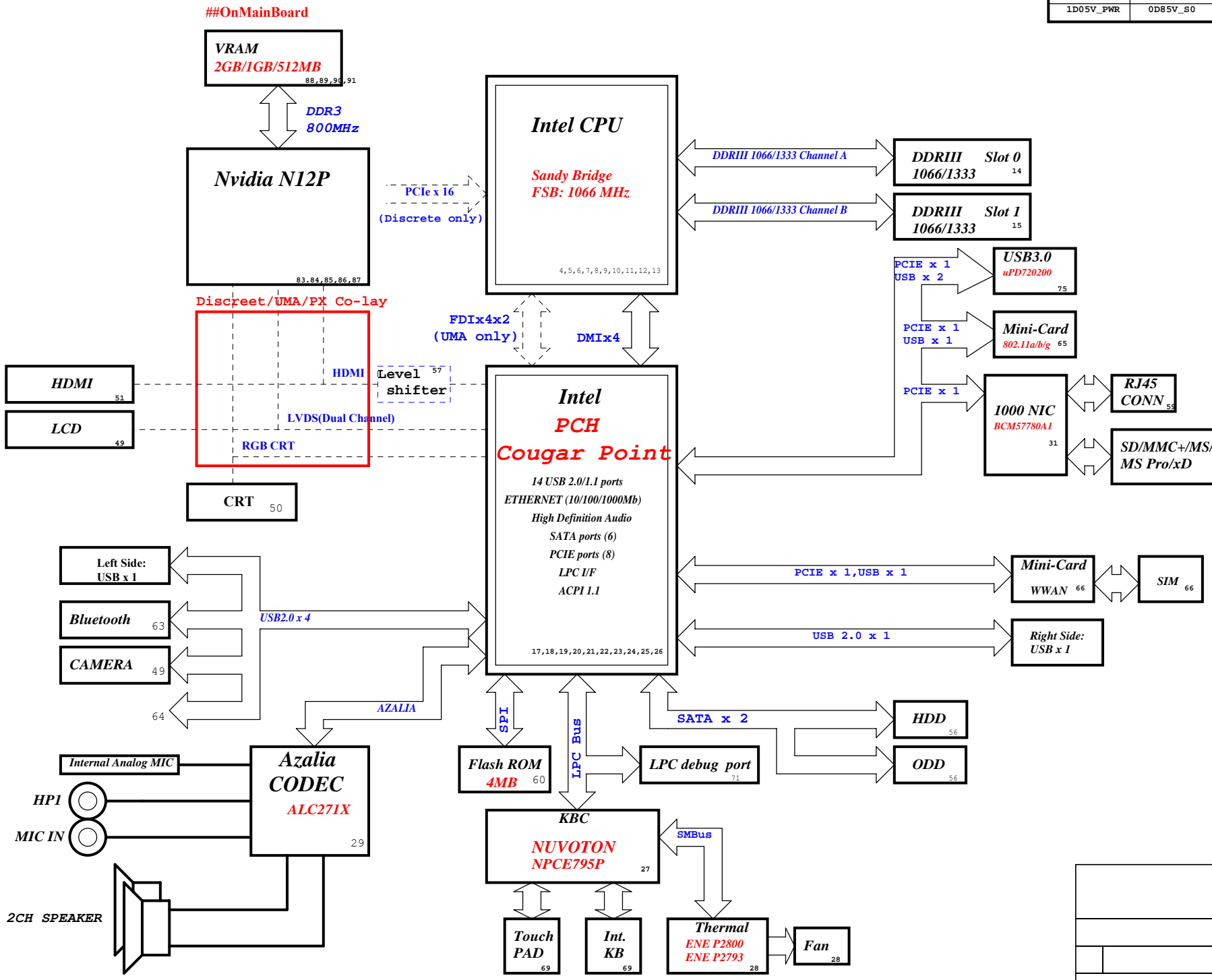
TI CHARGER BQ24745RHDR 40	
INPUTS	OUTPUTS
DCBATOUT	BT+

SYSTEM DC/DC RT9025 47	
INPUTS	OUTPUTS
3D3V_S0	1D8V_S0

SYSTEM DC/DC RT9025-25PSP 93	
INPUTS	OUTPUTS
1D5V_S3	1V_VGA_S0
3D3V_S5	1D8V_VGA_S0

Switches	
INPUTS	OUTPUTS
1D5V_S3	1D5V_VGA_S0
3D3V_S0	3D3V_VGA_S0

PCB LAYER			
L1:Top	L4:Signal	L2:VCC	L5:GND
L3:Signal	L6:Bottom		



Name	Schematics Notes
SPKR	Reboot option at power-up Default Mode: Internal weak Pull-down. No Reboot Mode with TCO Disabled: Connect to Vcc3_3 with 8.2-kΩ - 10-kΩ weak pull-up resistor.
INIT3_3V#	Weak internal pull-up. Leave as "No Connect".
GNT3#/GPIO55 GNT2#/GPIO53 GNT1#/GPIO51	GNT[3:0]# functionality is not available on Mobile. Mobile: Used as GPIO only Pull-up resistors are not required on these signals. If pull-ups are used, they should be tied to the Vcc3_3power rail.
SPI_MOSI	Enable Danbury: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable Danbury: Left floating, no pull-down required.
NV_ALE	Enable Danbury: Connect to +NVRAM_VCCQ with 8.2-kohm weak pull-up resistor [CRB has it pulled up with 1-kohm no-stuff resistor] Disable Danbury: Leave floating (internal pull-down)
NC_CLE	DMI termination voltage. Weak internal pull-up. Do not pull low.
HAD_DOCK_EN# /GPIO[33]	Low (0) - Flash Descriptor Security will be overridden. Also, when this signals is sampled on the rising edge of PWROK then it will also disable Intel ME and its features. High (1) - Security measure defined in the Flash Descriptor will be enabled. Platform design should provide appropriate pull-up or pull-down depending on the desired settings. If a jumper option is used to tie this signal to GND as required by the functional strap, the signal should be pulled low through a weak pull-down in order to avoid asserting HDA_DOCK_EN# inadvertently. Note: CRB recommends 1-kohm pull-down for FD Override. There is an internal pull-up of 20 kohm for DA_DOCK_EN# which is only enabled at boot/reset for strapping functions.
HDA_SDO	Weak internal pull-down. Do not pull high. Sampled at rising edge of RSMRST#.
HDA_SYNC	Weak internal pull-down. Do not pull high. Sampled at rising edge of RSMRST#.
GPIO15	Low (1) - Intel ME Crypto Transport Layer Security (TLS) cipher suite with no confidentiality High (1) - Intel ME Crypto Transport Layer Security (TLS) cipher suite with confidentiality Note : This is an un-muxed signal. This signal has a weak internal pull-down of 20 kohm which is enabled when PWROK is low. Sampled at rising edge of RSMRST#. CRB has a 1-kohm pull-up on this signal to +3.3VA rail.
GPIO8	GPIO8 on PCH is the Integrated Clock Enable strap and is required to be pulled-down using a 1k +/- 5% resistor. When this signal is sampled high at the rising edge of RSMRST#, Integrated Clocking is enabled, When sampled low, Buffer Through Mode is enabled.
GPIO27	Default = Do not connect (floating) High(1) = Enables the internal VccVRM to have a clean supply for analog rails. No need to use on-board filter circuit. Low (0) = Disables the VccVRM. Need to use on-board filter circuits for analog rails.

USB Table

Pair	Device
0	Touch Panel / 3G SIM
1	USB Ext. port 1 (HS)
2	Fingerprint
3	BLUETOOTH
4	Mini Card2 (WWAN)
5	CARD READER
6	X
7	X
8	USB Ext. port 4 / E-SATA / USB CHARGER
9	USB Ext. port 2
10	EDP CAMERA
11	Mini Card1 (WLAN)
12	CAMERA
13	New Card

SATA Table

SATA	
Pair	Device
0	HDD1
1	HDD2
2	N/A
3	N/A
4	ODD
5	ESATA

PCIE Routing

LANE1	Mini Card2(WWAN)
LANE2	Mini Card1(WLAN)
LANE3	Card Reader
LANE4	Onboard LAN
LANE5	USB3.0
LANE6	Intel GBE LAN
LANE7	Dock
LANE8	New Card

Pin Name	Strap Description	Configuration (Default value for each bit is 1 unless specified otherwise)	Default Value
CFG[2]	PCI-Express Static Lane Reversal	1: Normal Operation. 0: Lane Numbers Reversed 15 -> 0, 14 -> 1, ...	1
CFG[4]		Disabled - No Physical Display Port attached to Embedded DisplayPort. 1: Embedded DisplayPort. Enabled - An external Display Port device is connect to the EMBEDDED display Port	0
CFG[6:5]	PCI-Express Port Bifurcation Straps	11 : x16 - Device 1 functions 1 and 2 disabled 10 : x8, x8 - Device 1 function 1 enabled ; function 2 disabled 01 : Reserved - (Device 1 function 1 disabled ; function 2 enabled) 00 : x8, x4, x4 - Device 1 functions 1 and 2 enabled	11
CFG[7]	PEG DEFER TRAINING	1: PEG Train immediately following xxRESETB de assertion 0: PEG Wait for BIOS for training	1

POWER PLANE	VOLTAGE	Voltage Rails	
		ACTIVE IN	DESCRIPTION
5V_S0 3D3V_S0 1D8V_S0 1D5V_S0 1D05V_VTF 0D85V_S0 0D75V_S0 VCC_CORE VCC_GFXCORE 1D8V_VGA_S0 3D3V_VGA_S0 1V_VGA_S0	5V 3.3V 1.8V 1.5V 1.05V 0.95 - 0.85V 0.75V 0.35V to 1.5V 0.4 to 1.25V 1.8V 3.3V 1V	S0	CPU Core Rail Graphics Core Rail
5V_USBX_S3 1D5V_S3 DDR_VREF_S3	5V 1.5V 0.75V	S3	
BT+ DCBATOUT 5V_S5 5V_AUX_S5 3D3V_S5 3D3V_AUX_S5	6V-14.1V 6V-14.1V 5V 5V 3.3V 3.3V	All S states	AC Brick Mode only
3D3V_LAN_S5	3.3V	WOL_EN	Legacy WOL
3D3V_AUX_KBC	3.3V	DSW, Sx	ON for supporting Deep Sleep states
3D3V_AUX_S5	3.3V	G3, Sx	Powered by Li Coin Cell in G3 and +V3ALW in Sx

SMBus ADDRESSES

I ² C / SMBus Addresses		Ref Des	HURON RIVER ORB	
Device	Address	Hex	Bus	
EC SMBus 1 Battery CHARGER	BAT_SCL/BAT_SDA BAT_SCL/BAT_SDA BAT_SCL/BAT_SDA			
EC SMBus 2 PCH eDP	SML1_CLK/SML1_DATA SML1_CLK/SML1_DATA SML1_CLK/SML1_DATA			
PCH SMBus SO-DIMMA (SPD) SO-DIMMB (SPD) Digital Pot G-Sensor MINI	PCH_SMBDATA/PCH_SMBCLK PCH_SMBDATA/PCH_SMBCLK PCH_SMBDATA/PCH_SMBCLK PCH_SMBDATA/PCH_SMBCLK PCH_SMBDATA/PCH_SMBCLK PCH_SMBDATA/PCH_SMBCLK			

4

3

2

1

Note:
Intel DMI supports both Lane Reversal and polarity inversion but only at PCH side. This is enabled via a soft strap.

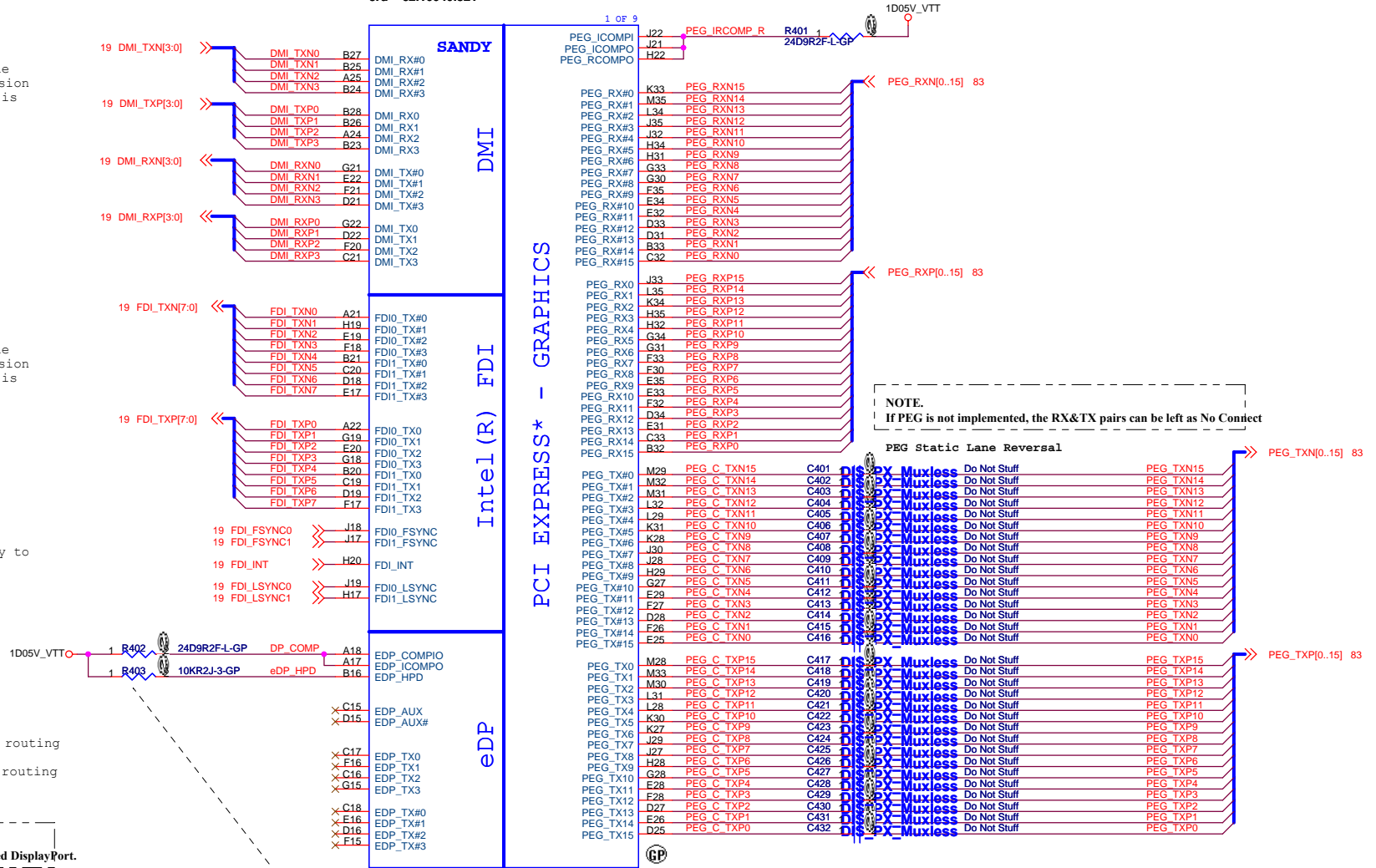
Note:
Intel FDI supports both Lane Reversal and polarity inversion but only at PCH side. This is enabled via a soft strap.

Note:
Lane reversal does not apply to FDI sideband signals.

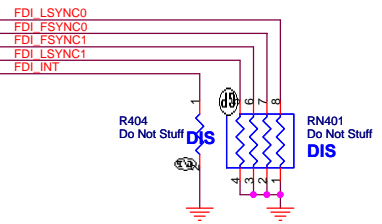
Signal Routing Guideline:
EDP_ICOMPO keep W/S=12/15 mils and routing length less than 500 mils.
EDP_COMPIO keep W/S=4/15 mils and routing length less than 500 mils.

CPU1A
SANDY
62.10055.421
Change:62.10053.611
2nd = 62.10055.321
3rd = 62.10040.821

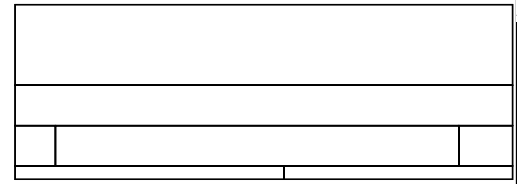
Signal Routing Guideline:
PEG_ICOMPO keep W/S=12/15 mils and routing length less than 500 mils.
PEG_ICOMPI & PEG_RCOMPO keep W/S=4/15 mils and routing length less than 500 mils.

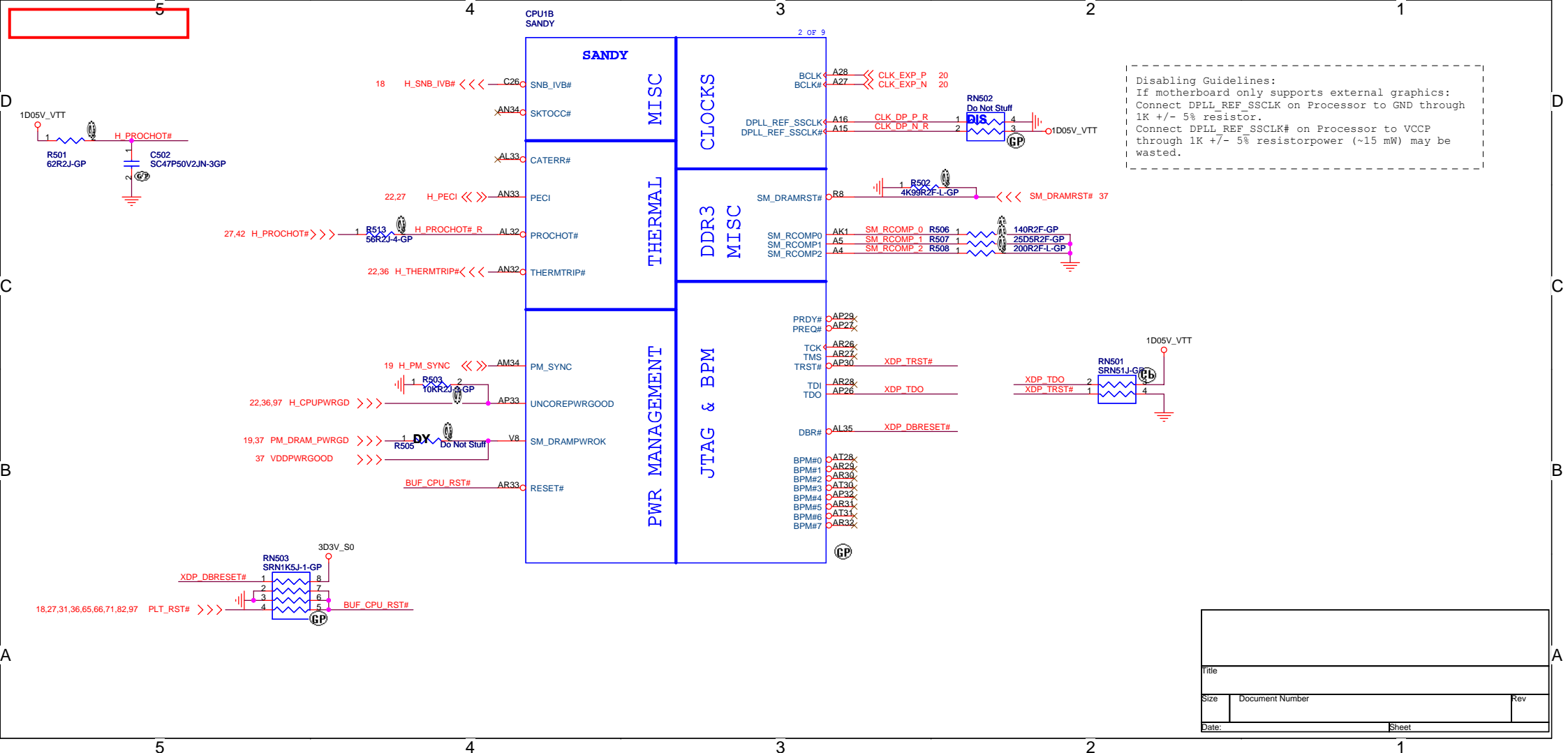


Stuff to disable internal graphics function for power saving.



NOTE:
Select a Fast FET similar to 2N7002E whose rise/fall time is less than 6 ns. If HPD on eDP interface is disabled, connect it to CPU VCCIO via a 10-kΩ pull-Up resistor on the motherboard.





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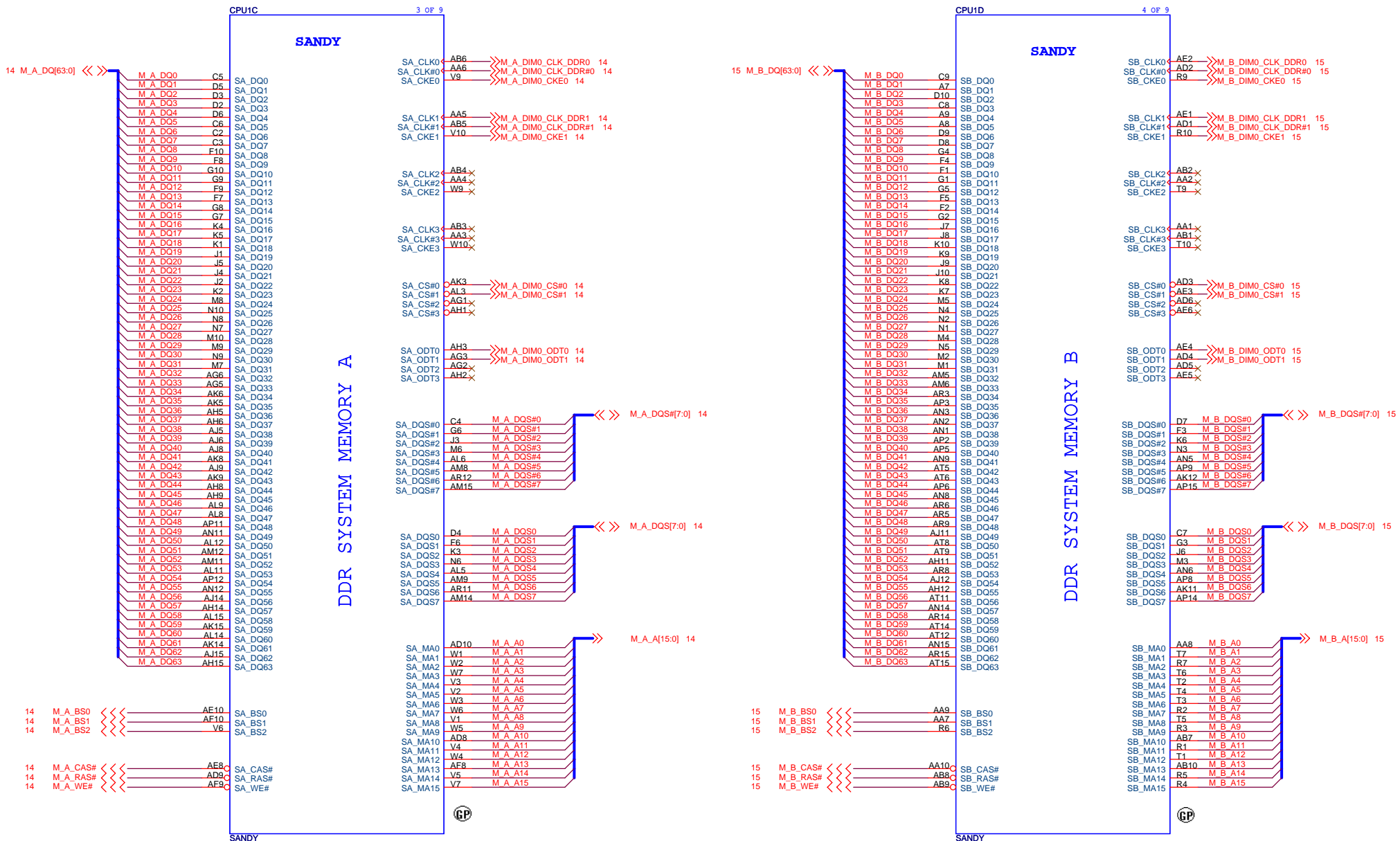
5

4

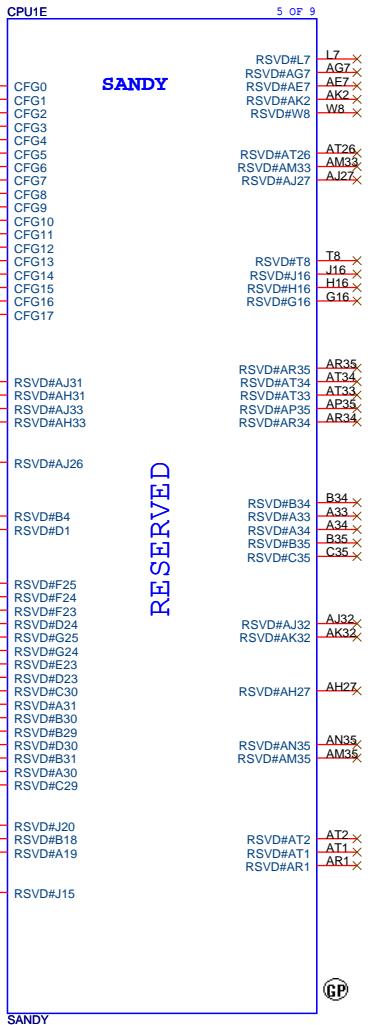
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2

1



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PEG Static Lane Reversal

CFG2	1: Normal Operation; Lane # definition matches socket pin map definition
	<u>0: Lane Reversed</u>

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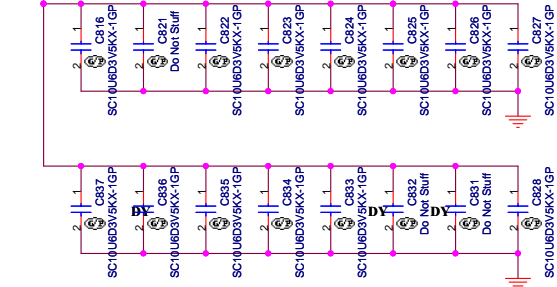
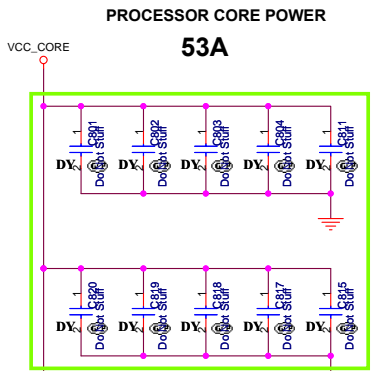
POWER

PEG AND DDR

CORE SUPPLY

SVID

SENSE LINES

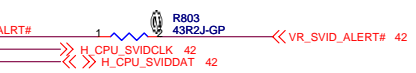
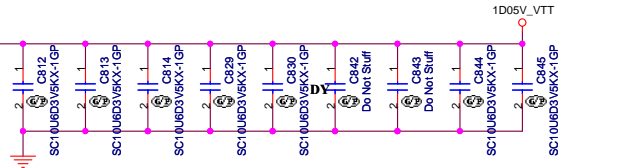
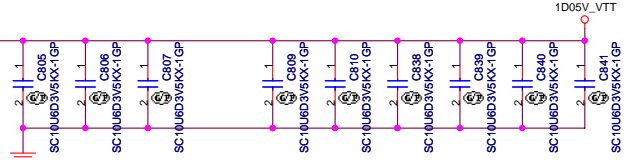


VCC_CORE

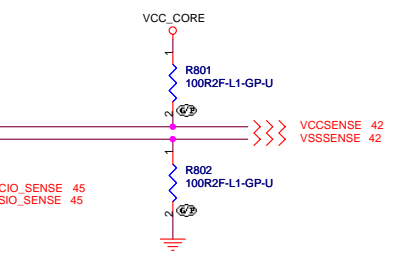
- AG35 VCC
- AG34 VCC
- AG33 VCC
- AG32 VCC
- AG31 VCC
- AG30 VCC
- AG29 VCC
- AG28 VCC
- AG27 VCC
- AG26 VCC
- AE35 VCC
- AF34 VCC
- AF33 VCC
- AF32 VCC
- AF31 VCC
- AF30 VCC
- AF29 VCC
- AF28 VCC
- AF27 VCC
- AF26 VCC
- AD35 VCC
- AD34 VCC
- AD33 VCC
- AD32 VCC
- AD31 VCC
- AD30 VCC
- AD29 VCC
- AD28 VCC
- AD27 VCC
- AD26 VCC
- AC35 VCC
- AC34 VCC
- AC33 VCC
- AC32 VCC
- AC31 VCC
- AC30 VCC
- AC29 VCC
- AC28 VCC
- AC27 VCC
- AC26 VCC
- AA35 VCC
- AA34 VCC
- AA33 VCC
- AA32 VCC
- AA31 VCC
- AA30 VCC
- AA29 VCC
- AA28 VCC
- AA27 VCC
- AA26 VCC
- Y35 VCC
- Y34 VCC
- Y33 VCC
- Y32 VCC
- Y31 VCC
- Y30 VCC
- Y29 VCC
- Y28 VCC
- Y27 VCC
- Y26 VCC
- V34 VCC
- V33 VCC
- V32 VCC
- V31 VCC
- V30 VCC
- V29 VCC
- V28 VCC
- V27 VCC
- V26 VCC
- U34 VCC
- U33 VCC
- U32 VCC
- U31 VCC
- U30 VCC
- U29 VCC
- U28 VCC
- U27 VCC
- U26 VCC
- R35 VCC
- R34 VCC
- R33 VCC
- R32 VCC
- R31 VCC
- R30 VCC
- R29 VCC
- R28 VCC
- R27 VCC
- R26 VCC
- P35 VCC
- P34 VCC
- P33 VCC
- P32 VCC
- P31 VCC
- P30 VCC
- P29 VCC
- P28 VCC
- P27 VCC
- P26 VCC

SANDY

- VCCIO AH13
- VCCIO AH10
- VCCIO AG10
- VCCIO Y10
- VCCIO U10
- VCCIO P10
- VCCIO L10
- VCCIO J14
- VCCIO J13
- VCCIO J12
- VCCIO J11
- VCCIO H14
- VCCIO H12
- VCCIO H11
- VCCIO G14
- VCCIO G13
- VCCIO F14
- VCCIO F13
- VCCIO F12
- VCCIO F11
- VCCIO F14
- VCCIO F12
- VCCIO E11
- VCCIO D14
- VCCIO D13
- VCCIO D12
- VCCIO D11
- VCCIO C14
- VCCIO C13
- VCCIO C12
- VCCIO C11
- VCCIO B14
- VCCIO B12
- VCCIO A14
- VCCIO A13
- VCCIO A12
- VCCIO A11
- VCCIO J23



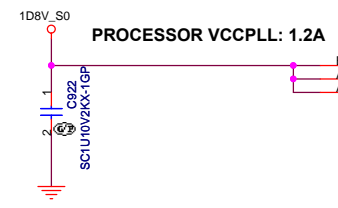
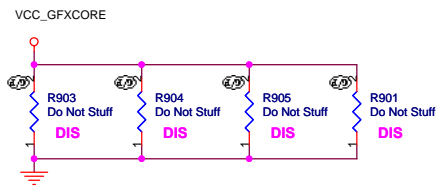
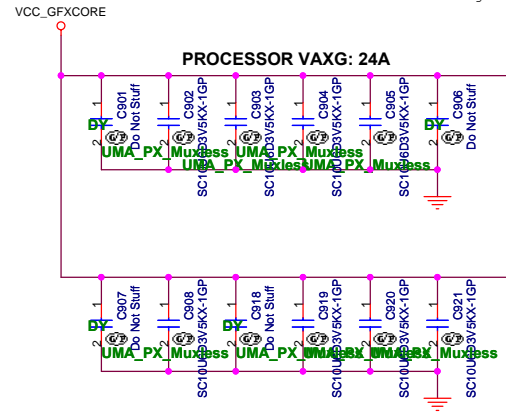
For CRB VIDSOUT need to pull high 130 ohm close to CPU and IMVP7
 For CRB VIDALERT# need to pull high 75 ohm close to CPU



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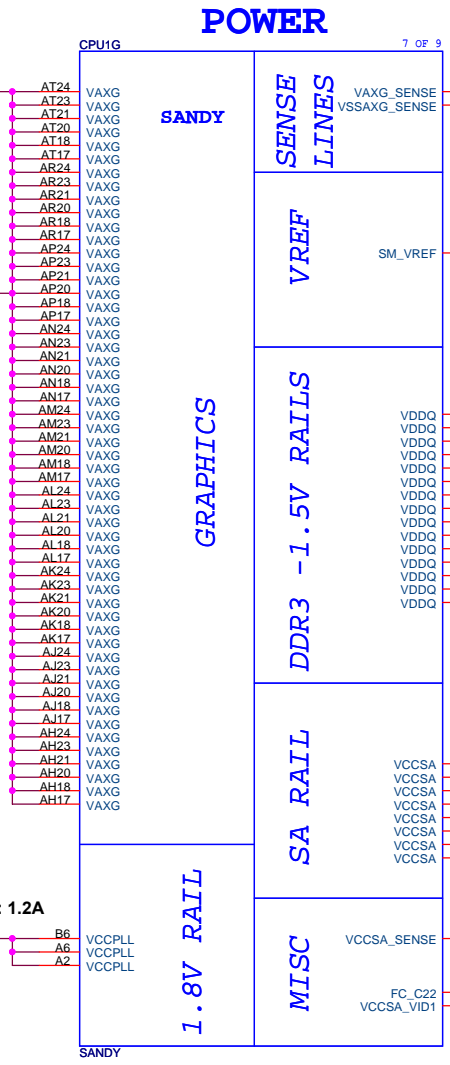
VAXG Output Decoupling Recommendation:
 2 x 470 uF at Bottom Socket Edge
 2 x 22 uF at Top Socket Cavity
 4 x 22 uF at Top Socket Edge
 2 x 22 uF at Bottom Socket Cavity
 4 x 22 uF at Bottom Socket Edge

R906,R907 close to CPU



VCCPLL Output Decoupling Recommendation:
 1 x 330 uF
 2 x 1 uF
 1 x 10 uF

Disabling Guidelines for External Graphics Designs:
 Can connect to GND if motherboard only supports external graphics and if GFX VR is not stuffed.
 Can be left floating (Gfx VR keeps VAXG rail from floating) if the VR is stuffed



POWER

SENSE LINES

VREF

GRAPHICS

DDR3 - 1.5V RAILS

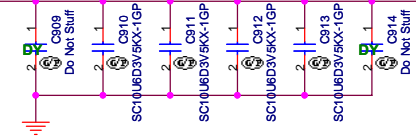
SA RAIL

1.8V RAIL

VAXG_SENSE AK35
 VSSAXG_SENSE AK34
 VCC_AXG_SENSE 42
 VSS_AXG_SENSE 42
 Refer to the latest Huron River Mainstream PDG (Doc# 436735) for more details on s3 power reduction implementation.
 +V_SM_VREF_CNT should have 10 mil trace width

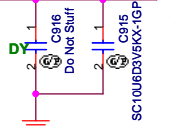
Routing Guideline:
 Power from DDR VREF_S3 and +V_SM_VREF_CNT should have 10 mils trace width.

PROCESSOR VDDQ: 10A



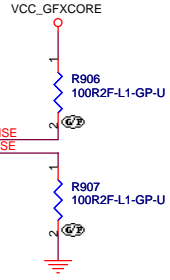
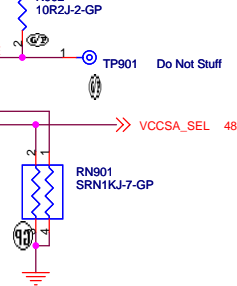
VDDQ Output Decoupling Recommendation:
 1 x 330 uF
 6 x 10 uF

PROCESSOR VCCSA: 6A

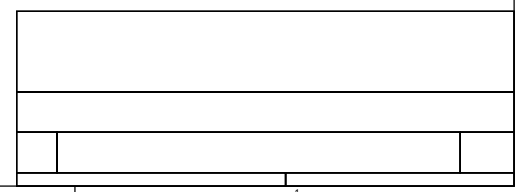
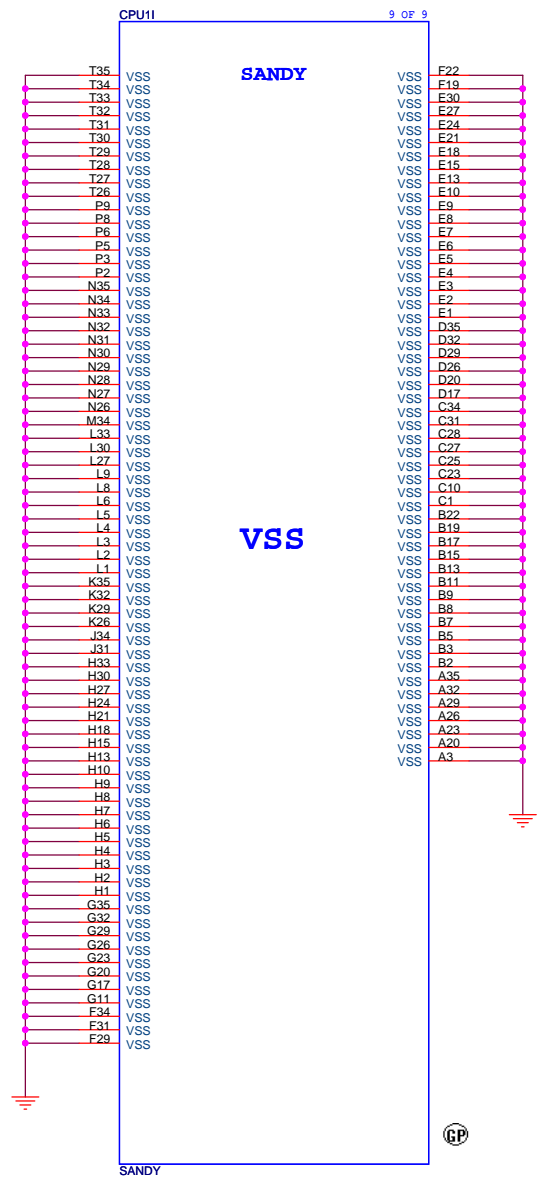
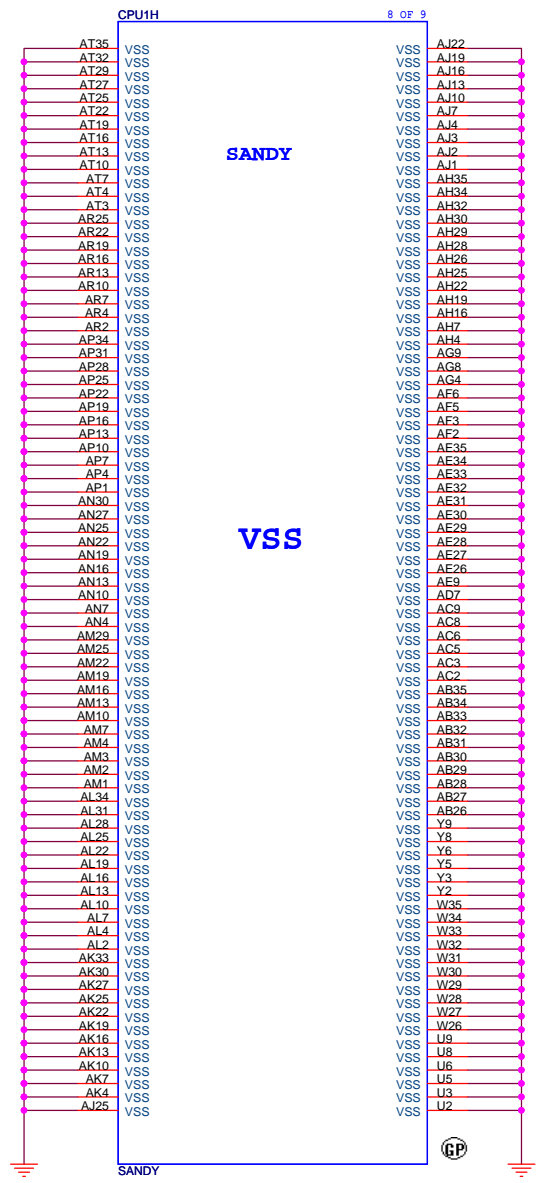


VCCSA Output Decoupling Recommendation:
 1 x 330 uF
 2 x 10 uF at Bottom Socket Cavity
 1 x 10 uF at Bottom Socket Edge

R902 need be close to pin H23.



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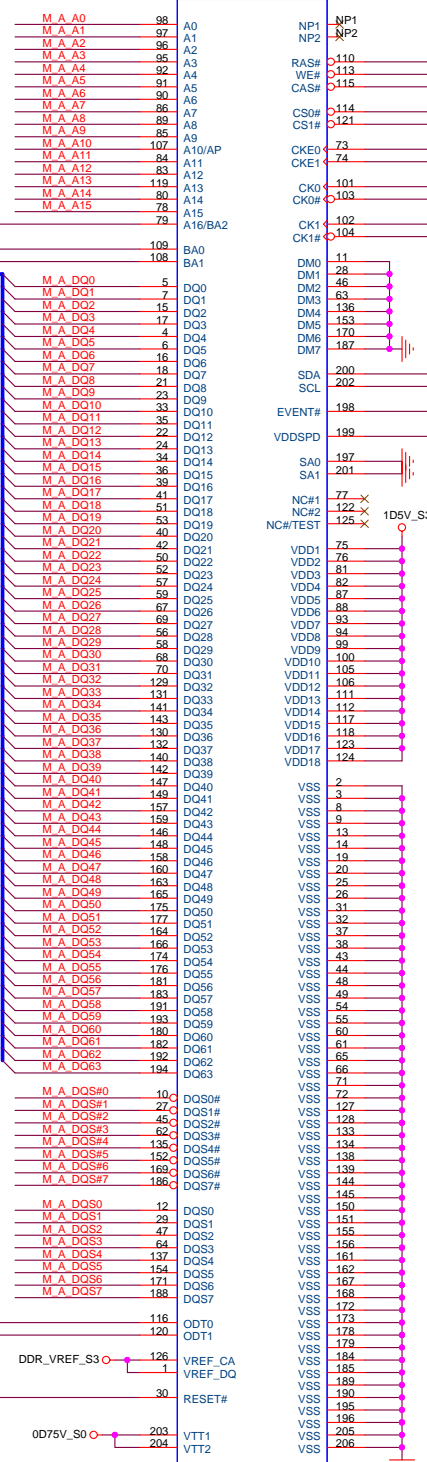
6 M_A_A[15:0] >>>

6 M_A_BS2 >>>
6 M_A_BS0 >>>
6 M_A_BS1 >>>
6 M_A_DQ[63:0] >>>

6 M_A_DQS[7:0] >>>
6 M_A_DQS[7:0] >>>

6 M_A_DIM0_ODT0 >>>
6 M_A_DIM0_ODT1 >>>

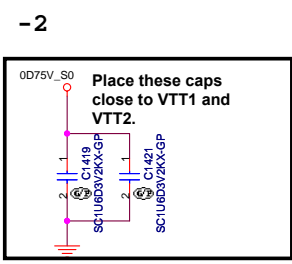
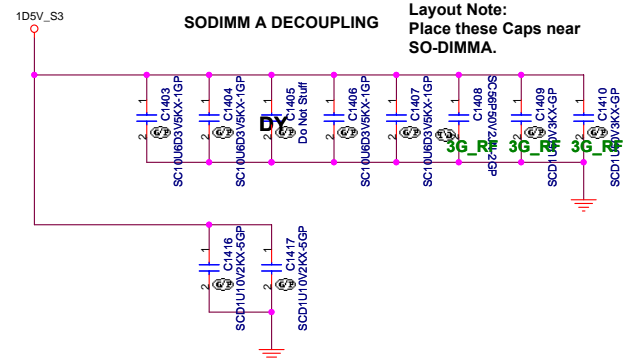
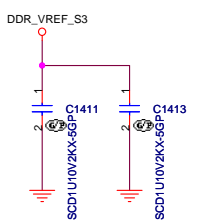
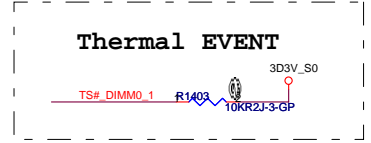
15.37 DDR3_DRAMRST# >>>



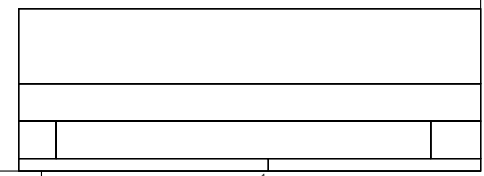
DM1
DDR3-204P-122-GP
62.10017.Z51
2nd = 62.10017.V51
3rd = 62.10017.M51
4th = 62.10017.X41

Note:
If SA0_DIM0 = 0, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA0
SO-DIMMA TS Address is 0x30

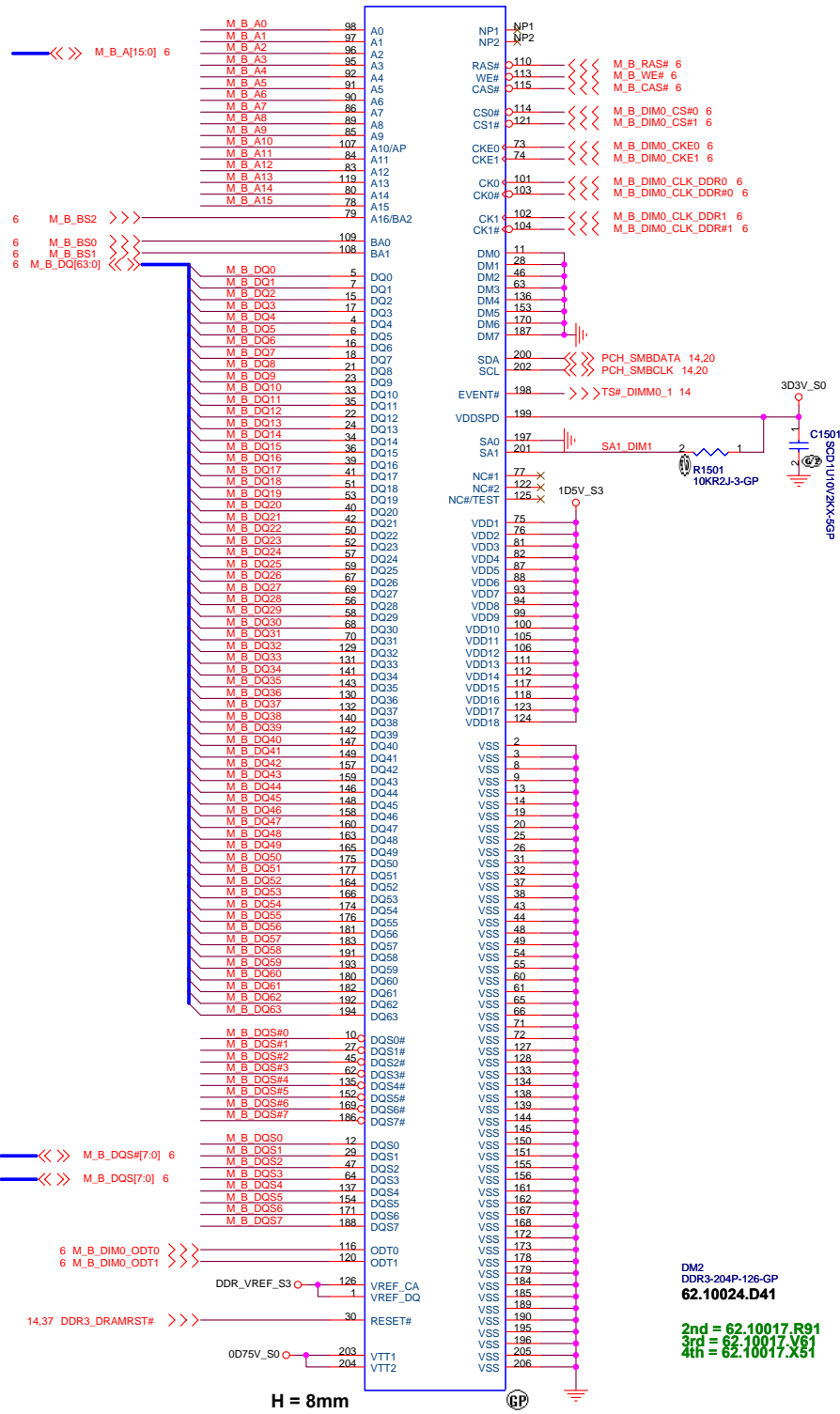
If SA0_DIM0 = 1, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA2
SO-DIMMA TS Address is 0x32



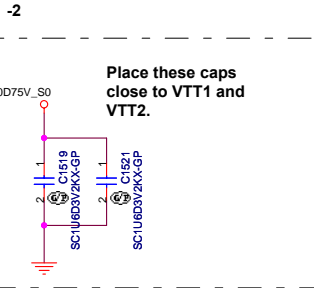
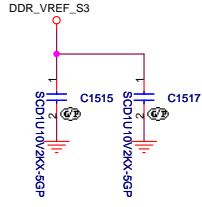
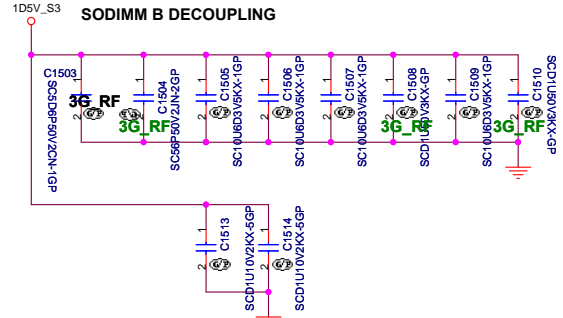
PART NUMBER	Height	TYPE



SSID = MEMORY



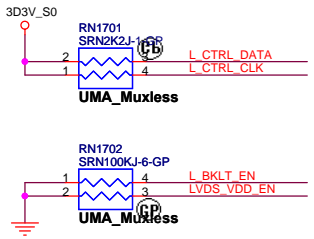
Layout Note:
Place these caps near SO-DIMMB.



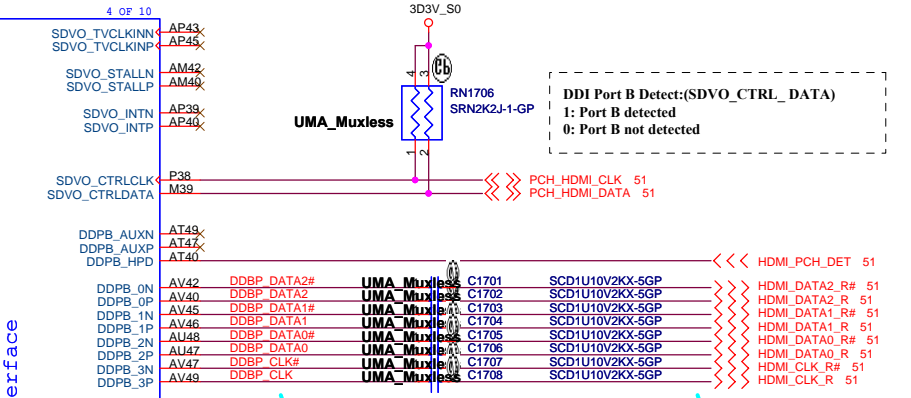
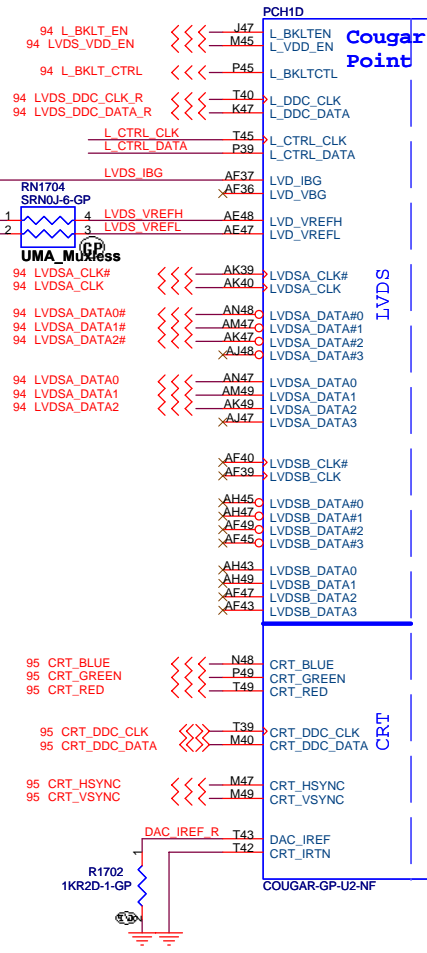
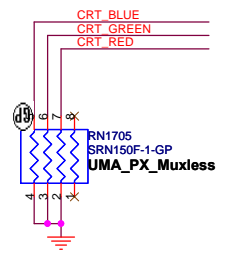
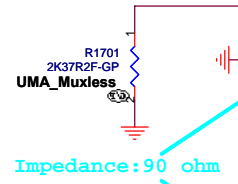
DM2
DDR3-204P-126-GP
62.10024.D41
2nd = 62.10017.R91
3rd = 62.10017.V61
4th = 62.10017.X51

H = 8mm

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L_DDC_DATA(PAGE17):
 This signal is on the LVDS interface.
 This signal needs to be left NC if eDP is
 used for the local flat panel display



DDI Port B Detect:(SDVO_CTRL_DATA)
 1: Port B detected
 0: Port B not detected

Close to PCH side

Impedance:100 ohm

Configuration Pin Mapping for DDI Ports (Sheet 1 of 2)

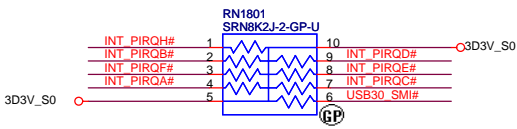
PORT	DDI PCH Pin Names	SDVO Mapping	Display Port Mapping	HDMI/DVI Mapping
PORT-B	DDPB_[0]P	SDVO_RED	DDPB_[0]P	TMDSB_DATA2
	DDPB_[0]N	SDVO_RED#	DDPB_[0]N	TMDSB_DATA2#
	DDPB_[1]P	SDVO_GREEN	DDPB_[1]P	TMDSB_DATA1
	DDPB_[1]N	SDVO_GREEN#	DDPB_[1]N	TMDSB_DATA1#
	DDPB_[2]P	SDVO_BLUE	DDPB_[2]P	TMDSB_DATA0
	DDPB_[2]N	SDVO_BLUE#	DDPB_[2]N	TMDSB_DATA0#
	DDPB_[3]P	SDVO_CLK	DDPB_[3]P	TMDSB_CLK
	DDPB_[3]N	SDVO_CLK#	DDPB_[3]N	TMDSB_CLK#
	DDPB_AUXP	NA	DDPB_AUXP	NA
	DDPB_AUXN	NA	DDPB_AUXN	NA
	DDPB_HPDP	NA	DDPB_HPDP	HDMI_B_HPDP
	SDVO_CTRLCLK	SDVO_CTRLCLK	NA	HDMI_B_CTRLCLK
SDVO_CTRLDATA	SDVO_CTRLDATA	NA	HDMI_B_CTRLDATA	

Title: _____

Size: _____ Document Number: _____ Rev: _____

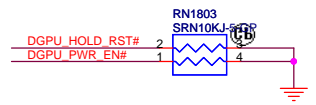
Date: _____ Sheet: _____

SSID = PCH



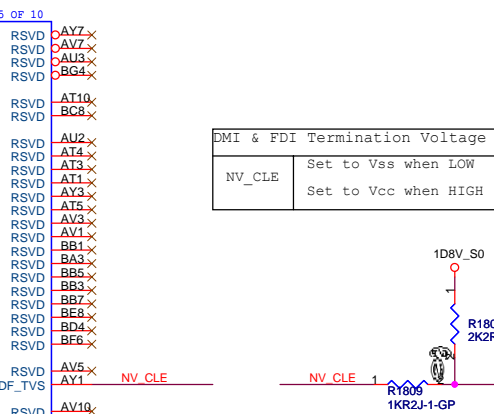
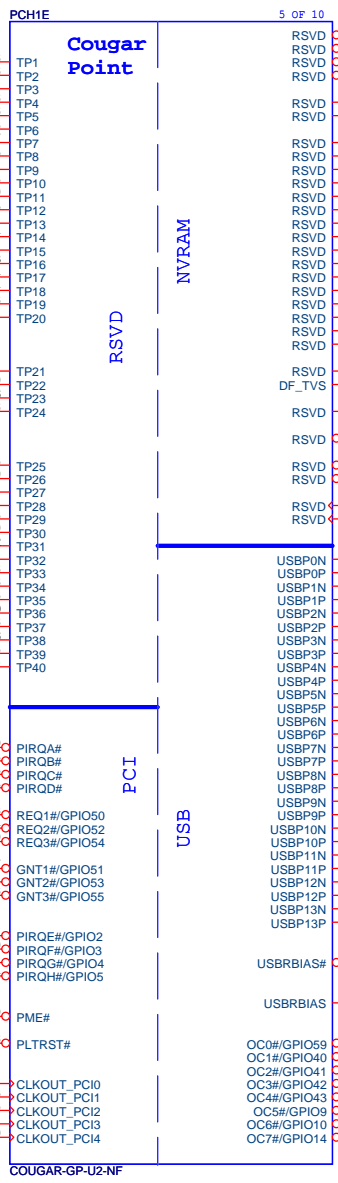
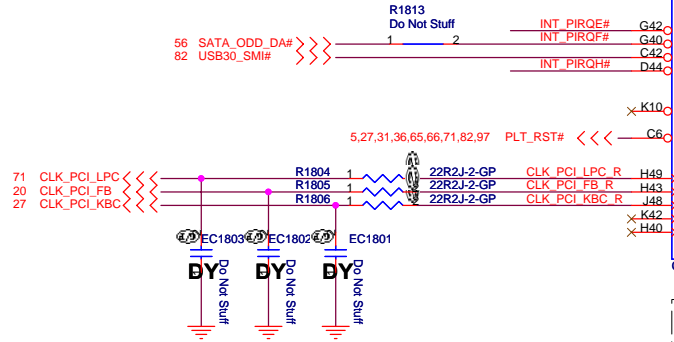
Al6 swap override Strap/Top-Block Swap Override jumper

PCI_GNT#3	Low = Al6 swap override/Top-Block Swap Override enabled High = Default
-----------	---------------------------------------------------------------------------



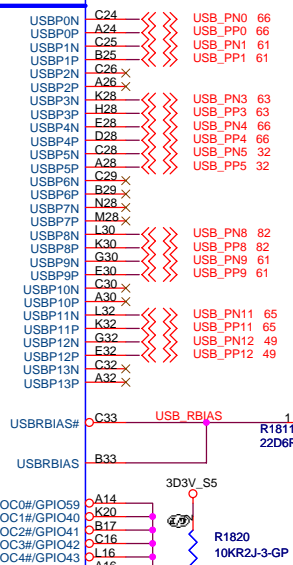
BOOT BIOS Strap

GNT1#/GPIO51	SATA1GP/GPIO19	BOOT BIOS Location
0	0	LPC
0	1	Reserved
		SPI(Default)



USB Ext. port 1 (HS) External debug port use on Huron river platform USB Table

Pair	Device
0	Touch Panel / 3G SIM
1	USB Ext. port 1 (HS)
2	Fingerprint
3	BLUETOOTH
4	Mini Card2 (WWAN)
5	CARD READER(DY)
6	X
7	X
8	USB Ext. port 4 / E-SATA / USB CHARGER
9	USB Ext. port 2
10	EDP CAMERA
11	Mini Card1 (WLAN)
12	CAMERA
13	New Card



USB 2.0 Overcurrent Pin Default Usage

Pin	Default Port Mapping	Pin	Default Port Mapping
OC0#	Port 0, Port 1	OC4#	Port 8, Port 9
OC1#	Port 2, Port 3	OC5#	Port 10, Port 11
OC2#	Port 4, Port 5	OC6#	Port 12, Port 13
OC3#	Port 6, Port 7	OC7#	Not Used

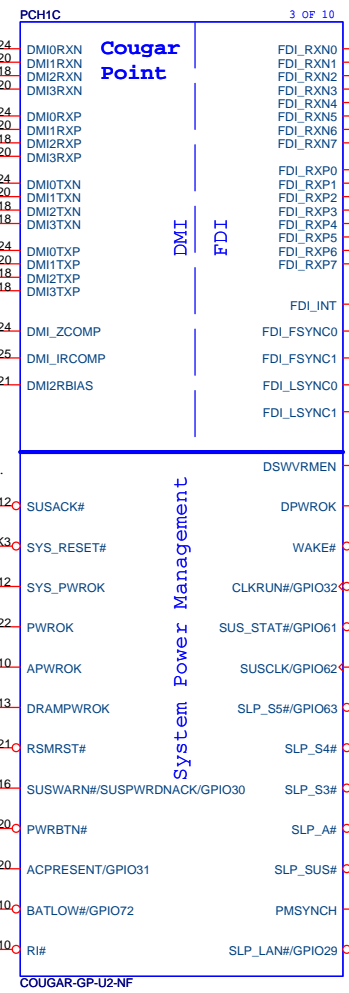
OC[3:0]# for Device 29 (Ports 0-7)
OC[7:4]# for Device 26 (Ports 8-13)

Title: _____

Size: Document Number _____ Rev _____

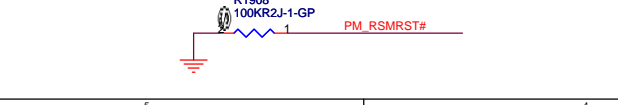
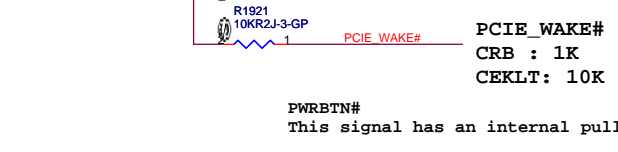
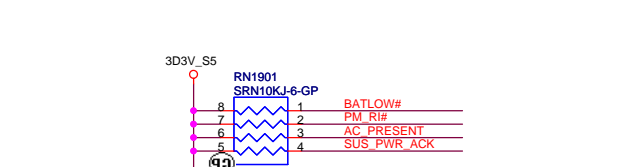
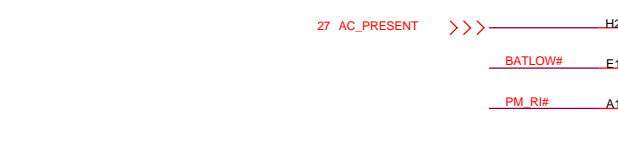
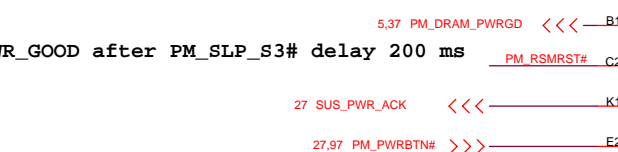
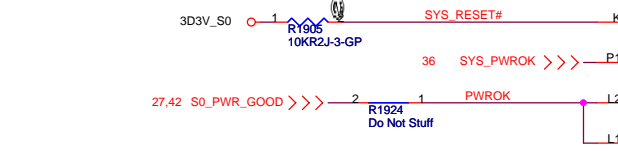
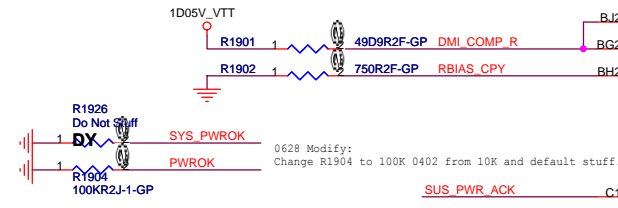
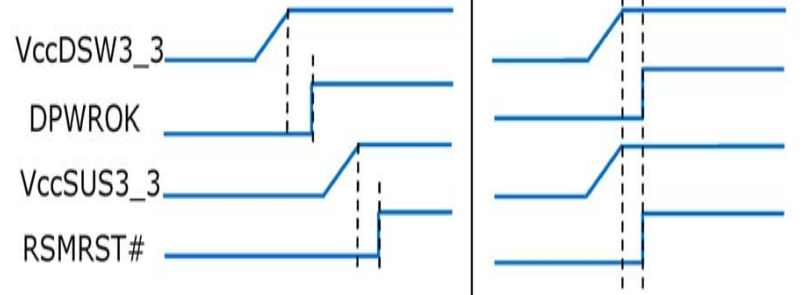
Date: _____ Sheet _____

SSID = PCH



Deep S4/S5 Supported

Deep S4/S5 Not Supported

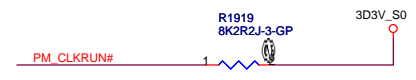


DSWODVREN - On Die DSW VR Enable

HIGH	Enabled (DEFAULT)
LOW	Disabled

SB modify

R1917 330KR2J-L1-GP
 R1918 Do Not Stuff



Title		
Size	Document Number	Rev
Date:		Sheet

65 PCIE_RXN2
65 PCIE_RXP2
65 PCIE_TXN2
65 PCIE_TXP2

31 PCIE_RXN4
31 PCIE_RXP4
31 PCIE_TXN4
31 PCIE_TXP4

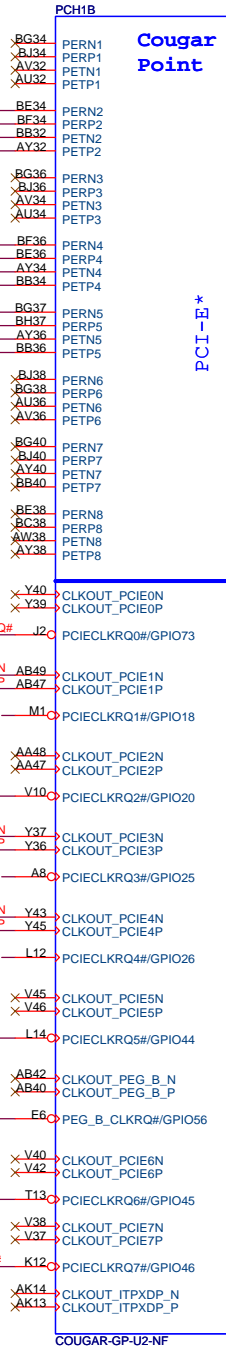
82 PCIE_RXN5
82 PCIE_RXP5
82 PCIE_TXN5
82 PCIE_TXP5

65 CLK_PCIE_WLAN#
65 CLK_PCIE_WLAN

31 CLK_PCIE_LAN#
31 CLK_PCIE_LAN

82 CLK_PCIE_USB3#
82 CLK_PCIE_USB3

PCIE_CLK_REQ2#
CLK_PCIE_WLAN_REQ#

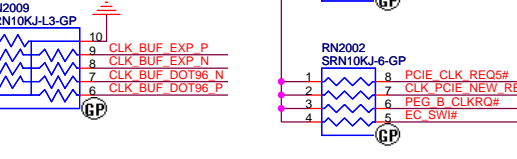
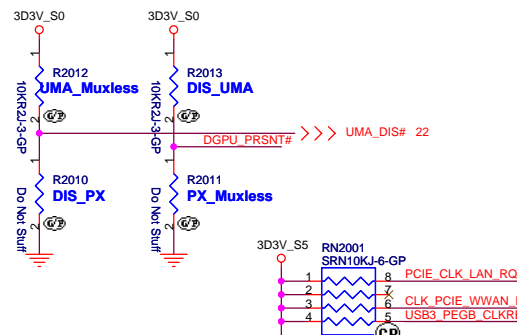
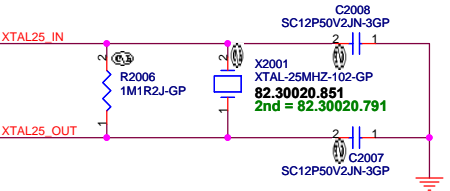
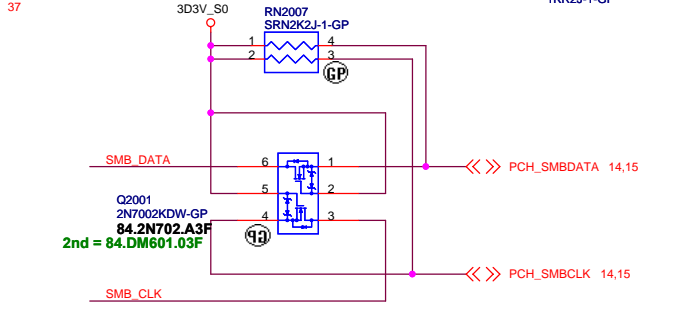
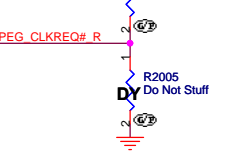
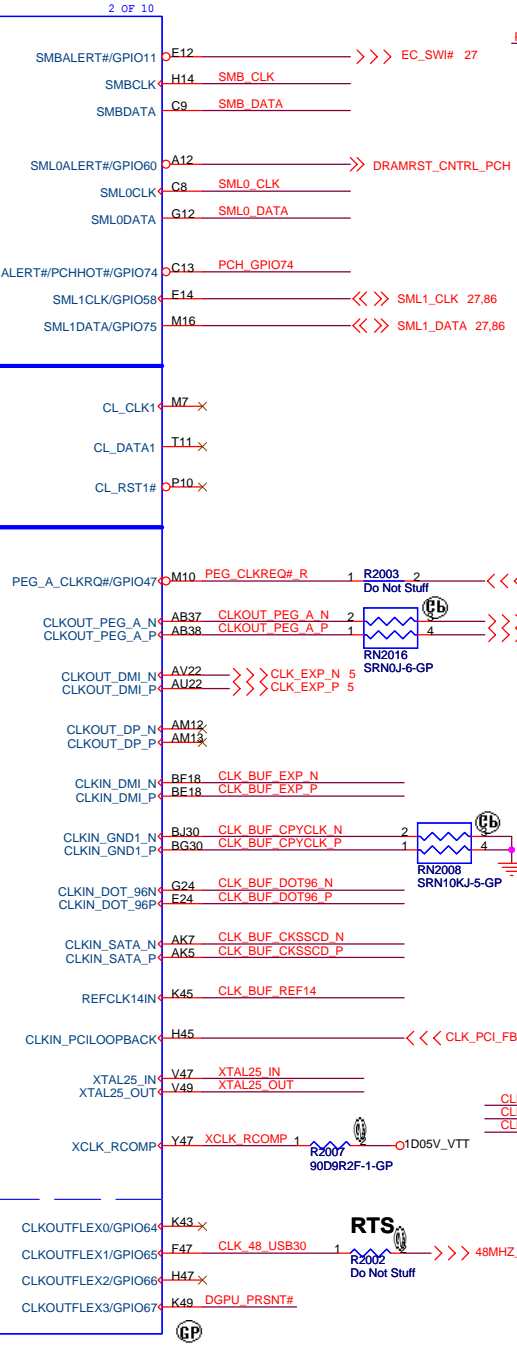


SMBUS

Controller Link

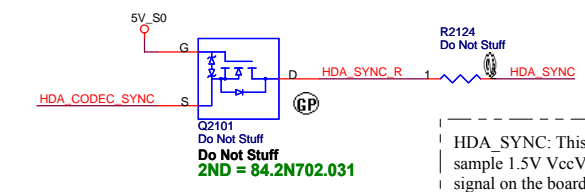
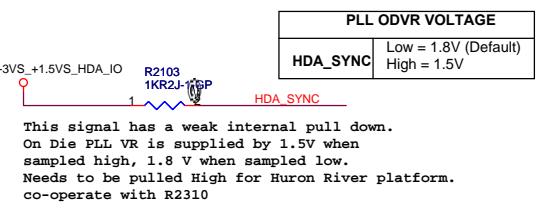
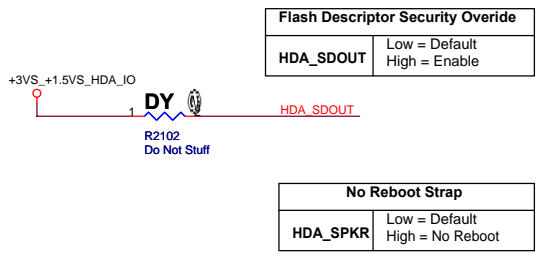
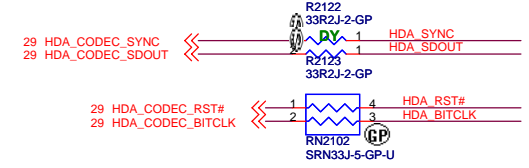
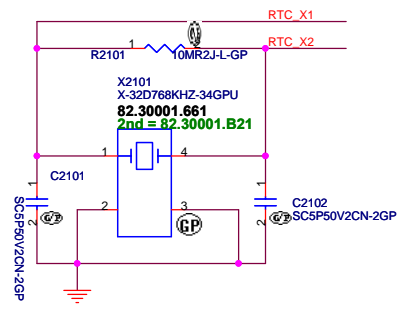
CLOCKS

FLEX CLOCKS

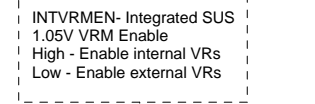
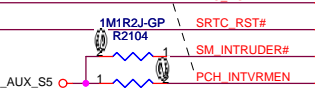
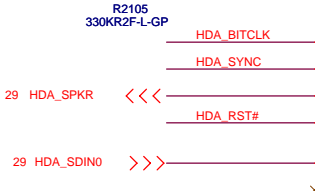
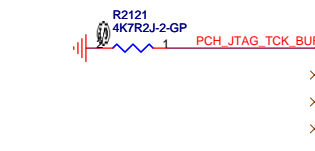
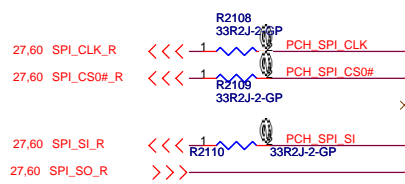
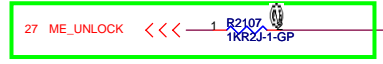
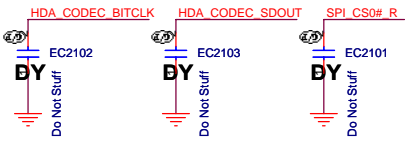


Title		
Size	Document Number	Rev
Date:	Sheet	

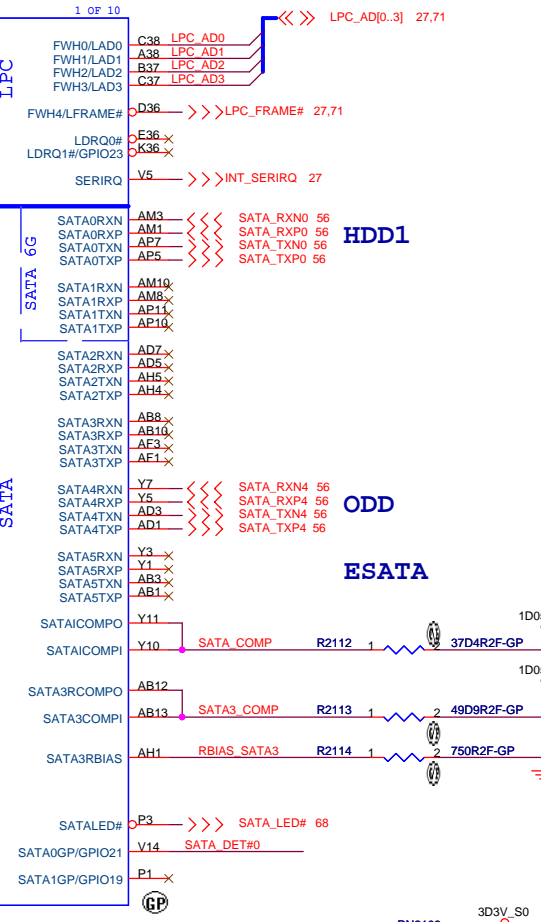
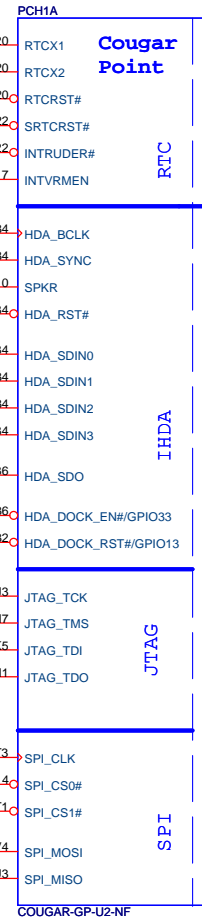
SSID = PCH



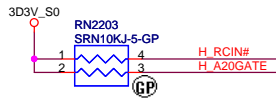
HDA_SYNC: This strap is sampled on rising edge of RSMRST# and is used to sample 1.5V VccVRM supply mode. 1K external pull-up resistor is required on this signal on the board. Signal may have leakage paths via powered off devices (Audio Codec) and hence contend with the external pull-up. A blocking FET is recommended in such a case to isolate HDA_SYNC from the Audio Codec device until after the Strap sampling is complete.



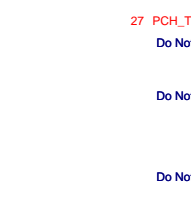
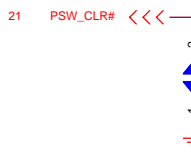
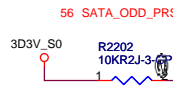
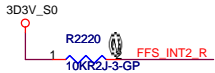
INTVRMEN- Integrated SUS
1.05V VRM Enable
High - Enable internal VRs
Low - Enable external VRs



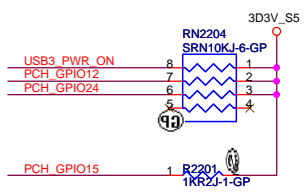
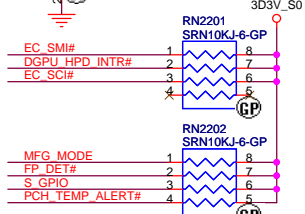
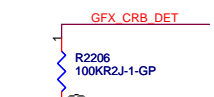
Title		
Size	Document Number	Rev
Date:		Sheet



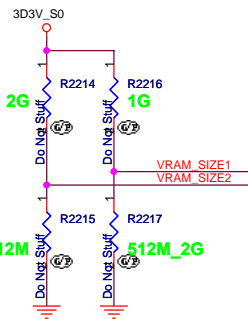
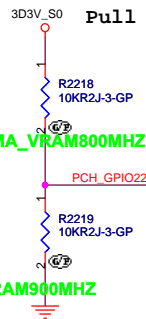
Note:
For PCH debug with XDP, need to NO STUFF R2218



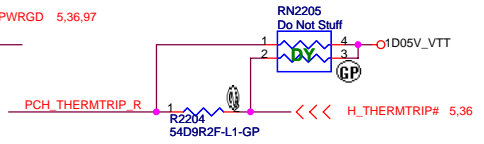
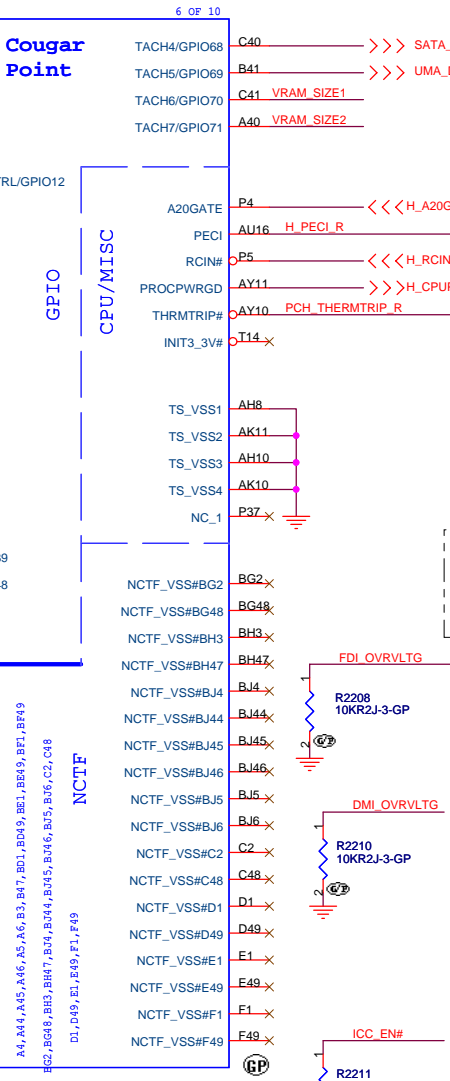
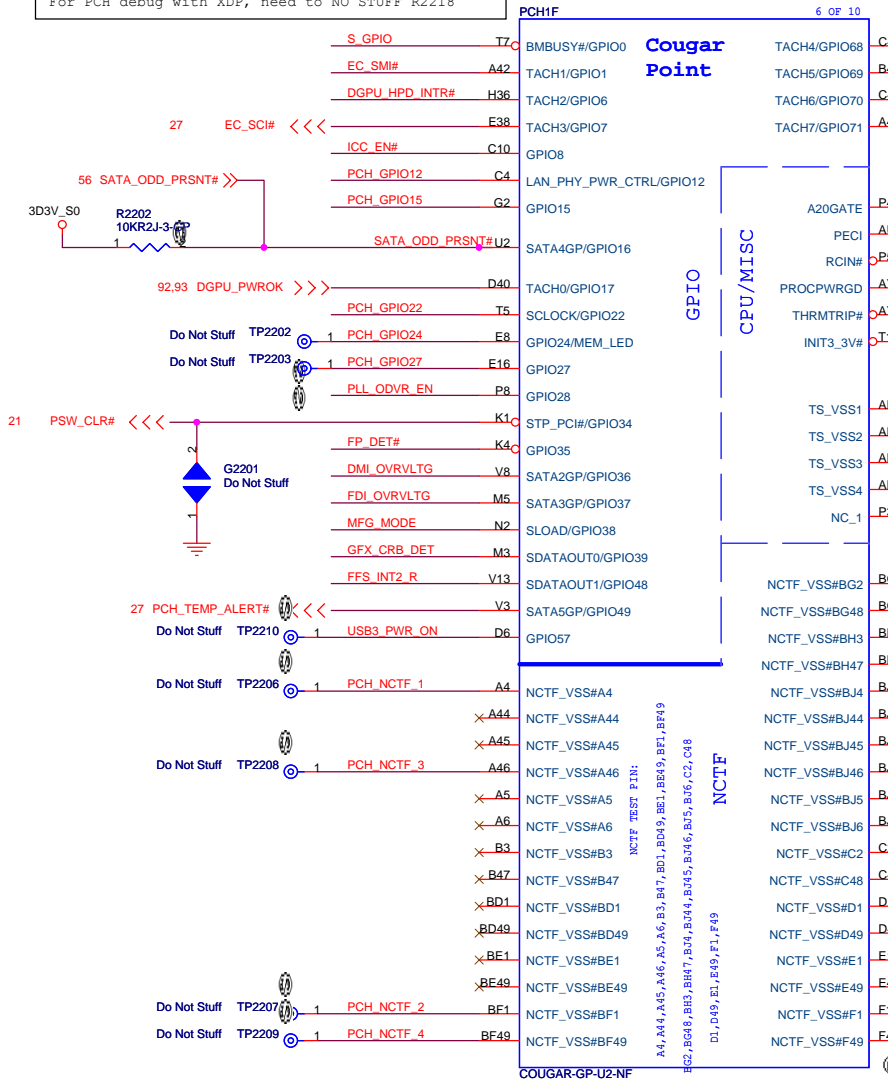
	INTERNAL GFX	EXTERNAL GFX
R2205	DY	10K
R2206	100K	DY



VRAM Frequency
Pull high: 800MHZ
Pull low :900MHZ



PLL ON DIE VR ENABLE
NOTE: This signal has a weak internal pull-up 20K
ENABLED -- HIGH (R2212 UNSTUFFED) DEFAULT
DISABLED -- LOW (R2212 STUFFED)



TS Signal Disable Guideline:
TS_VSS1, TS_VSS2, TS_VSS3 and TS_VSS4
should not float on the motherboard. They should
be tied to GND directly.

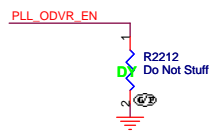
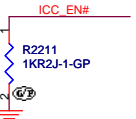
FDI TERMINATION VOLTAGE OVERRIDE	
GPIO37 (FDI_OVRVLTG)	LOW - Tx, Rx terminated to same voltage (DC Coupling Model DEFAULT)

DMI TERMINATION VOLTAGE OVERRIDE	
GPIO36 (DMI_OVRVLTG)	LOW - Tx, Rx terminated to same voltage (DC Coupling Model DEFAULT)

Integrated Clock Enable functionality is achieved via soft-strap. The default is integrated clock enable.

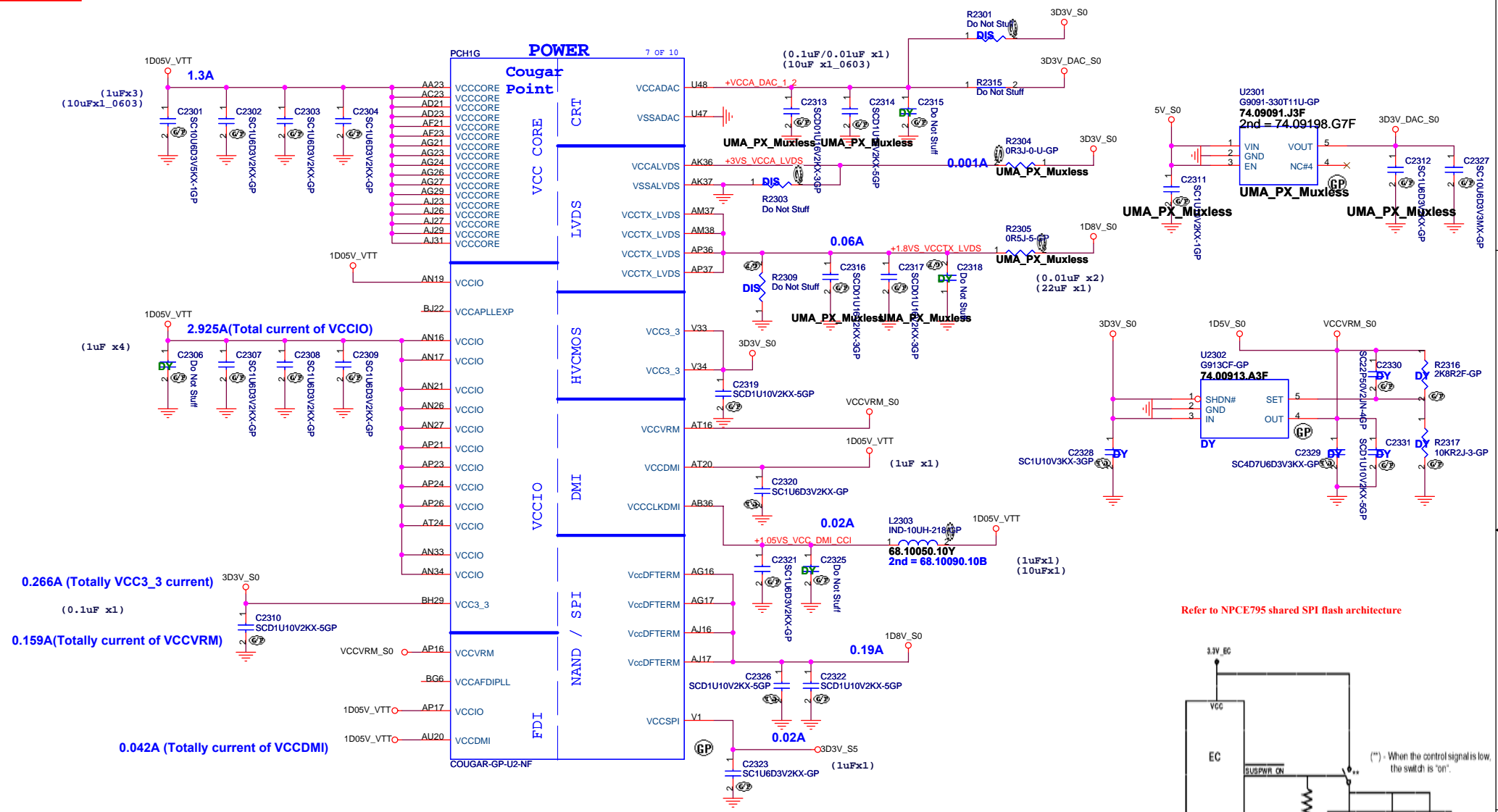
Integrated Clock Chip Enable	
ICC_EN#	HIGH (R2211 DY) - DISABLED [DEFAULT]
	LOW (R2211) - ENABLED

GPIO8 has a weak[20K] internal pull up.
Integrated Clock Enable functionality is achieved via soft-strap. The default is integrated clock enable.

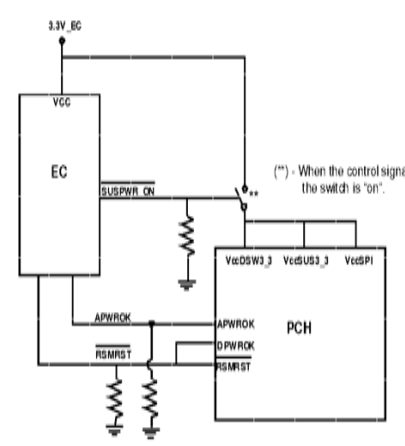


Title		
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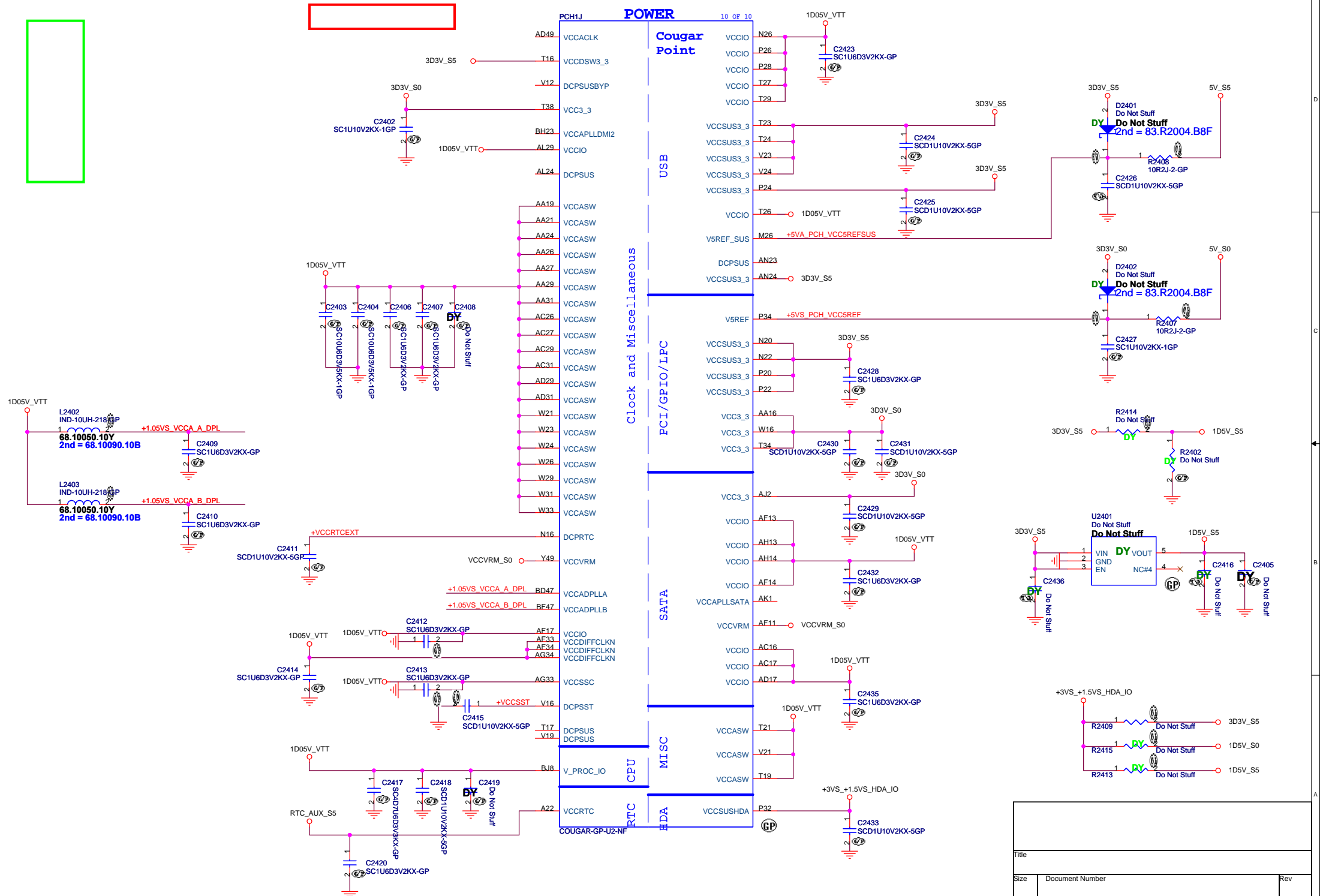
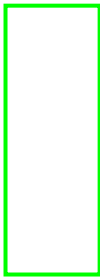
SSID = PCH



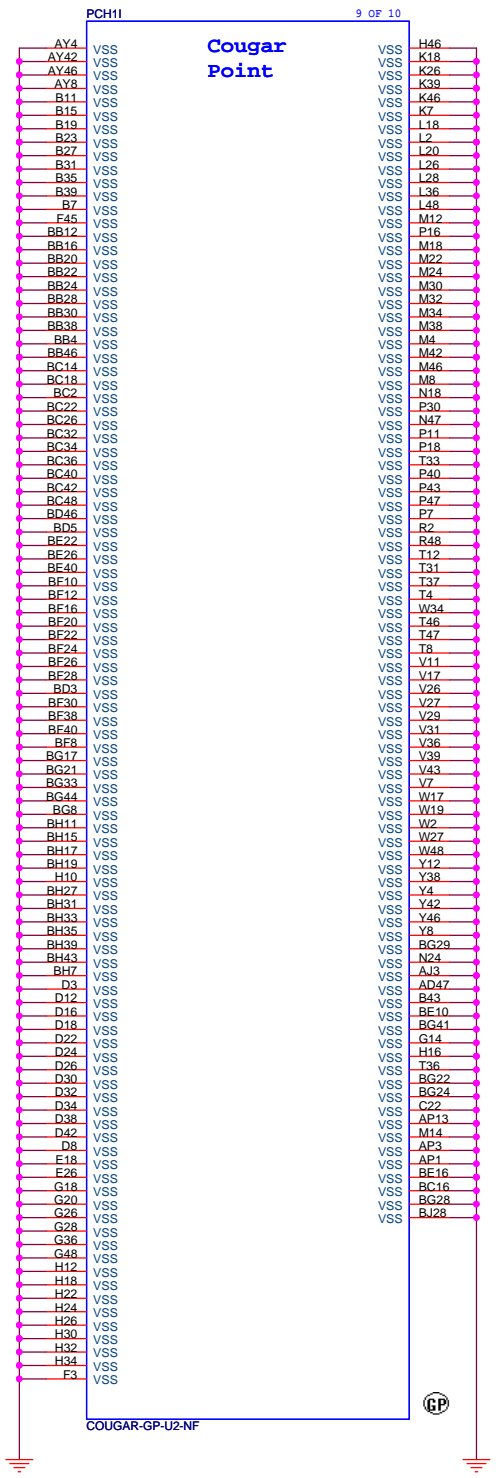
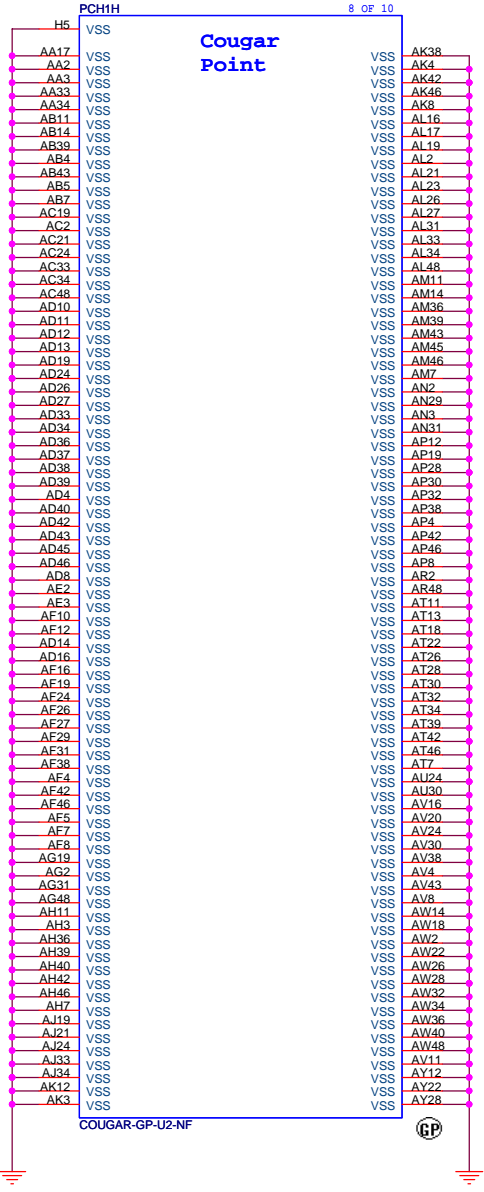
Refer to NPCE795 shared SPI flash architecture



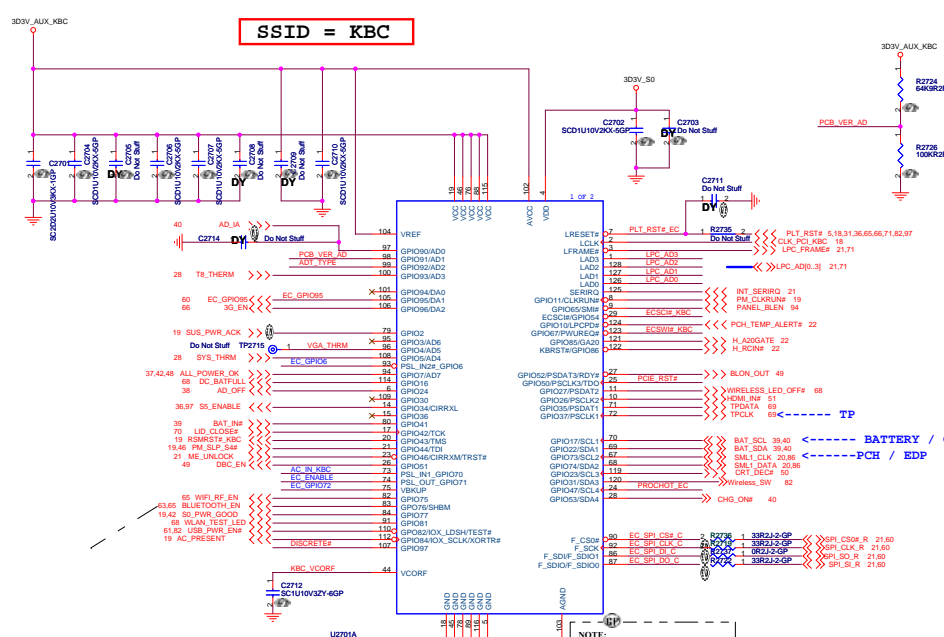
Title		
Size	Document Number	Rev
Date:		Sheet



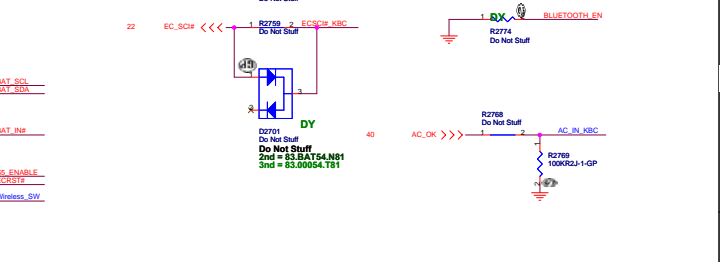
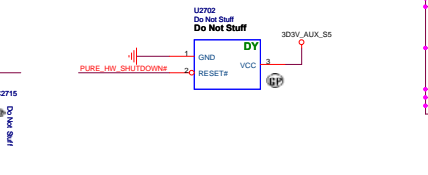
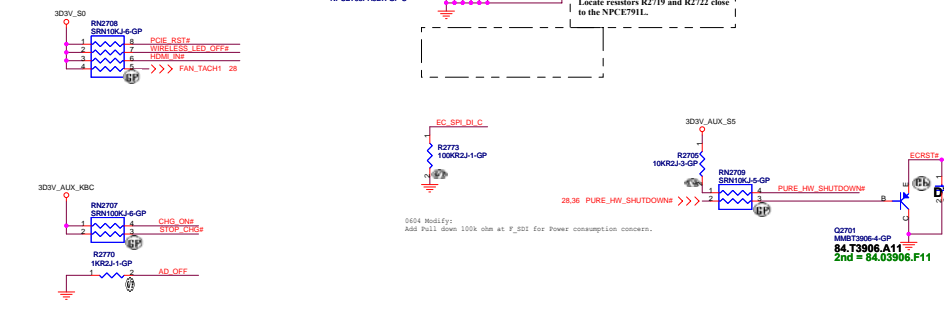
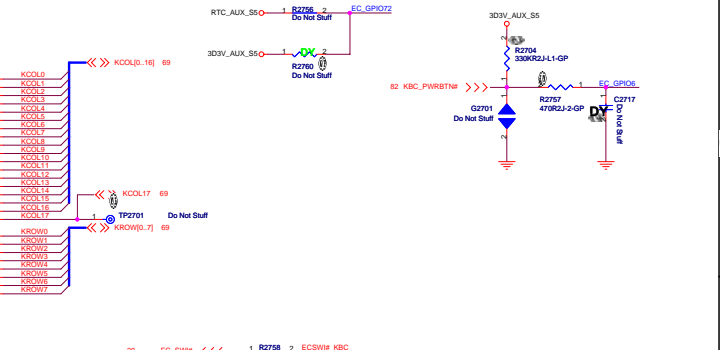
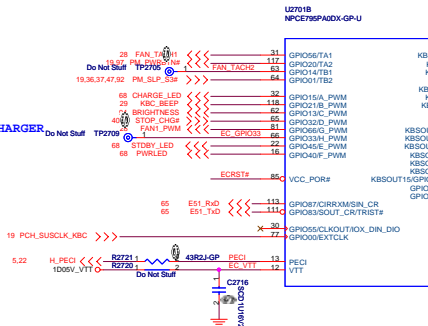
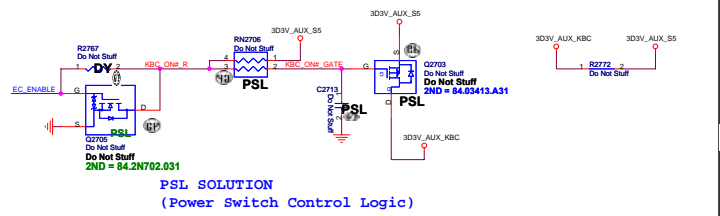
Title		
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Title		
Size	Document Number	Rev
Date:		Sheet



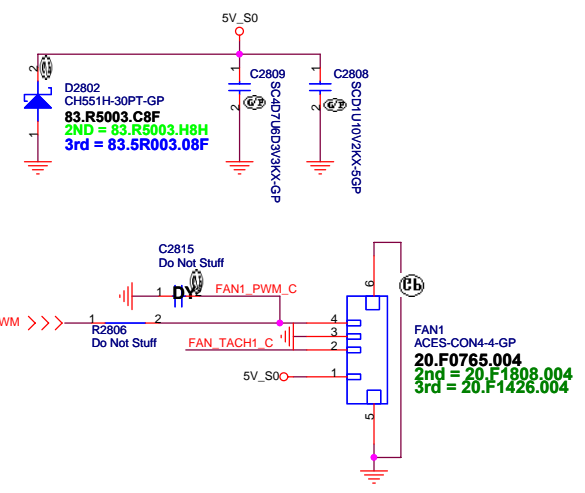
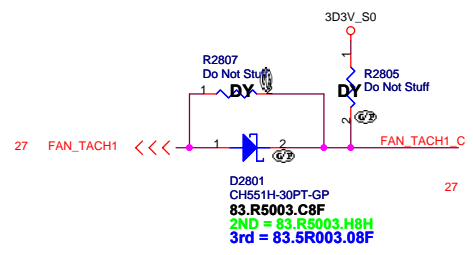
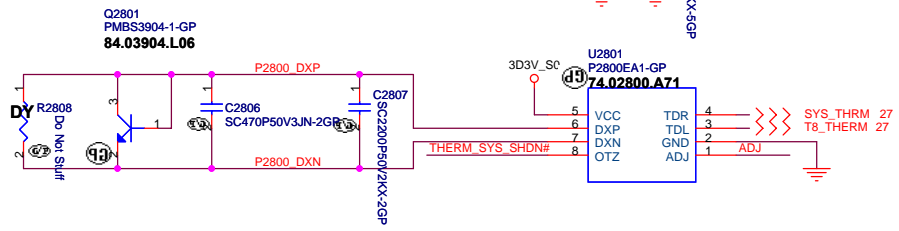
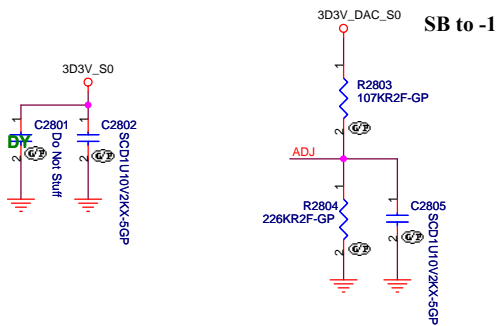
PCB VERSION A/D(PIN#)	PULL-LOW RESISTOR	PULL-HIGH RESISTOR	VOLTAGE
SA	100.0K		3.0V
SB			2.75V
Reserved		47.0K	
Reserved		64.9K	
Reserved		76.8	
Reserved			1.65V



ADT_TYPE A/D(PIN#)	PULL-LOW RESISTOR	PULL-HIGH RESISTOR	VOLTAGE
65W	N/A	100.0K	3.3V
90W	100.0K	N/A	0V
30W	10.0K	100.0K	0.3V
40W	20.0K		0.55V
120W	33.0K		0.55V
	47.0K		0.55V
	64.9K	100.0K	1.65V

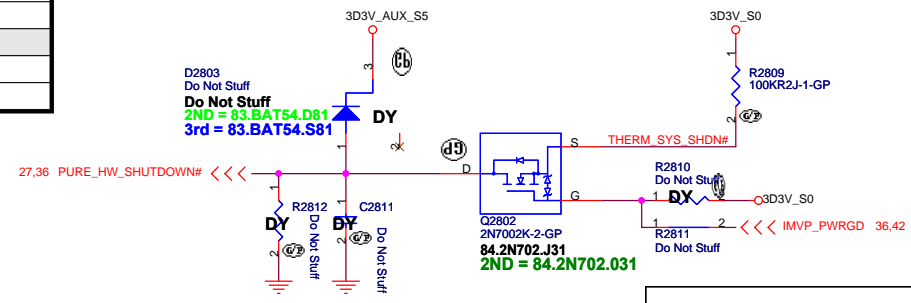
65W 90W#
High: 65W / Low 90W
DISCRETE#
High: UNA / Low: Discrete

File	Doc Number	Rev

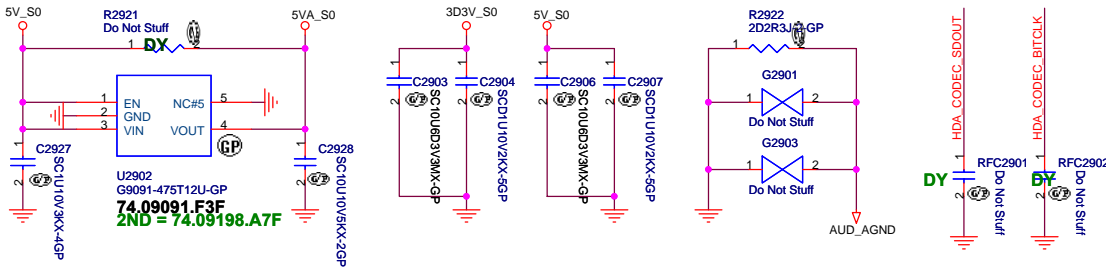


ADJ Table (Reference to SYNTON-TECH Metal Film Resistor E-96 ±1% Series)

RADJ1 (KΩ)	RADJ2 (KΩ)	VADJ (v)	OTZ Threshold Temperature (°C)
124	226	2.13	101
118	226	2.17	96.3
113	226	2.20	92.1
110	226	2.22	89.6
107	226	2.24	87
105	226	2.25	85.3
100	226	2.29	80.9

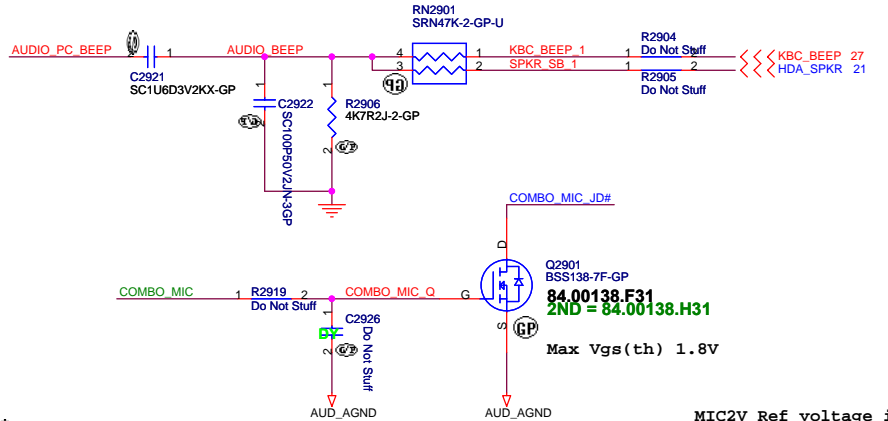
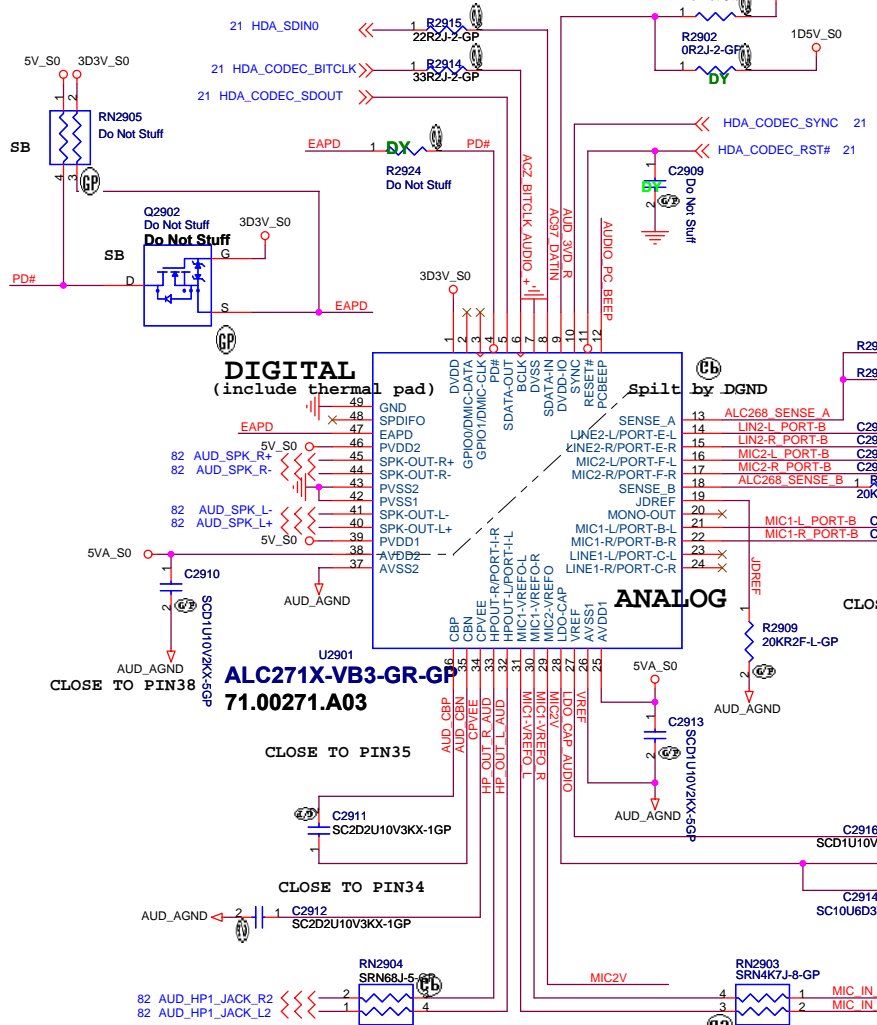


Title		
Size	Document Number	Rev
Date:	Sheet	

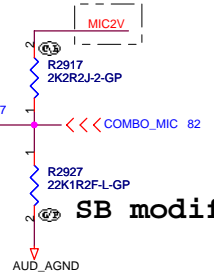


CLOSE TO PIN39 and 46

-1 PVDD timing 需要比 AVDD晚, 使用PW 74.00545.079 去開
vensor suggest, 需要導入嗎

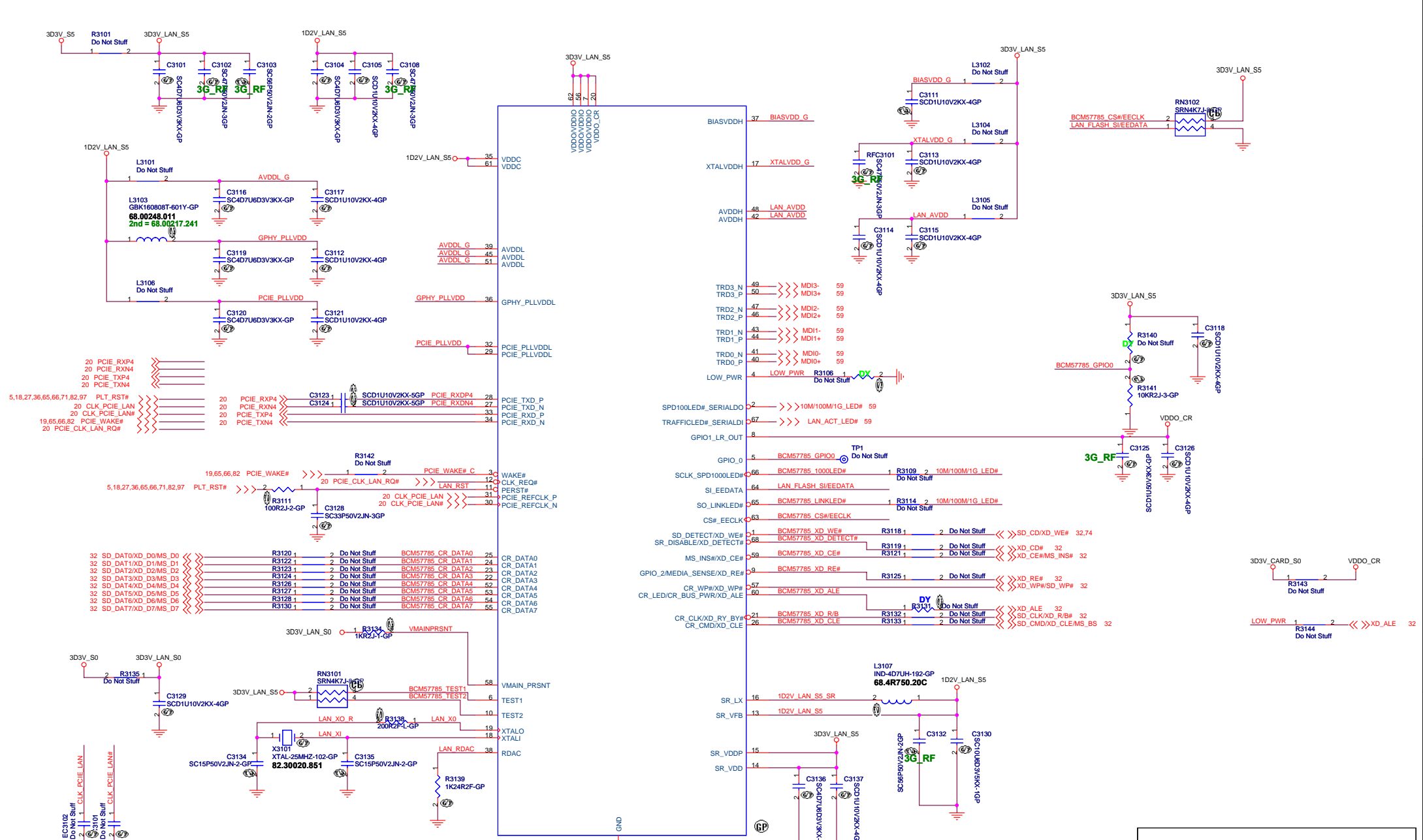


MIC2V Ref voltage is 2.5V because Vgs(th) concern can't use 2N702 for desing



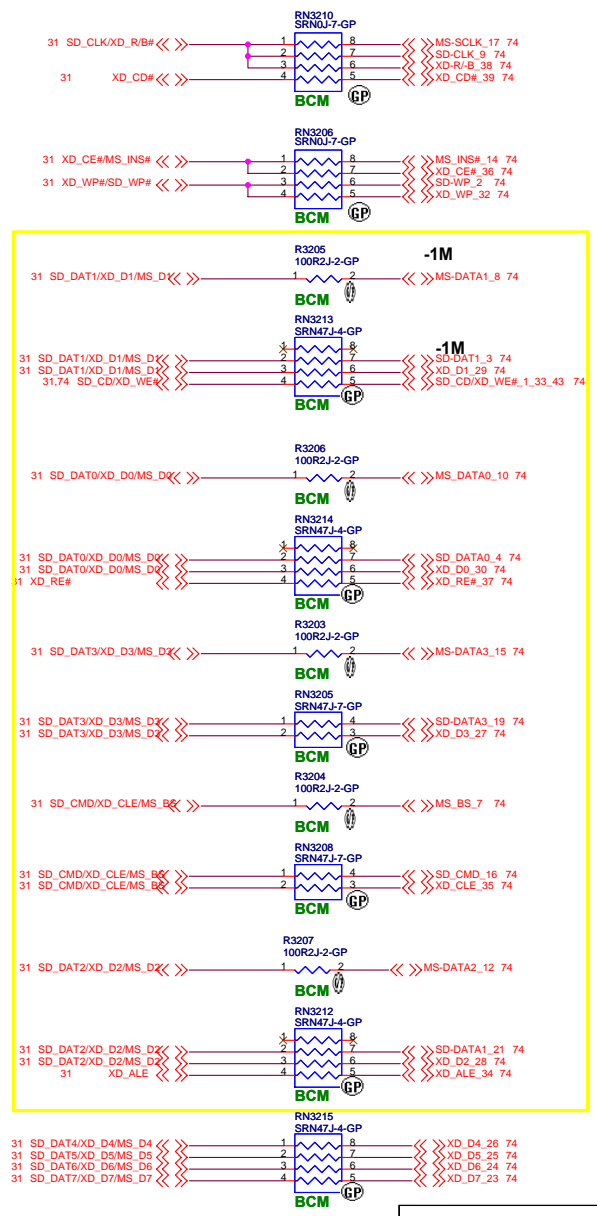
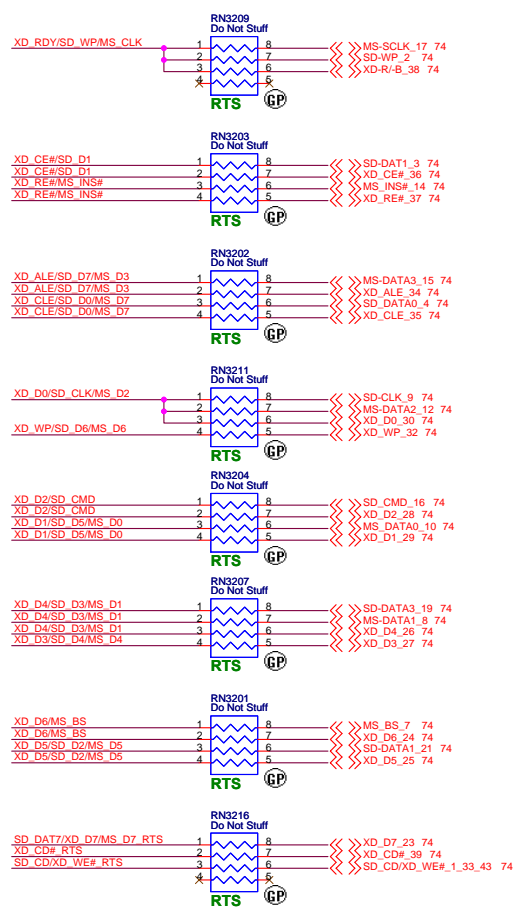
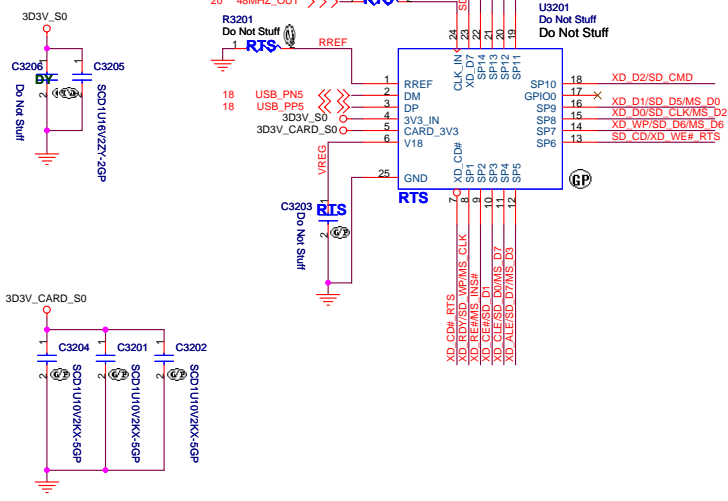
SB modify

Title		
Size	Document Number	Rev
Date:	Sheet	



Title		
Size	Document Number	Rev
Date:	Sheet	

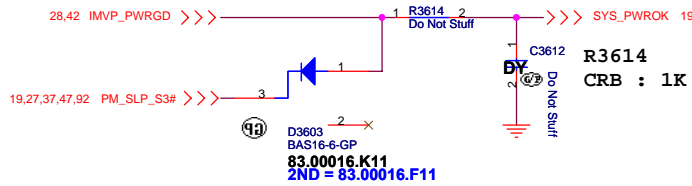
U3101
BCM57785XA0KMLG-GP
71.57785.M02
Change:71.57785.M03



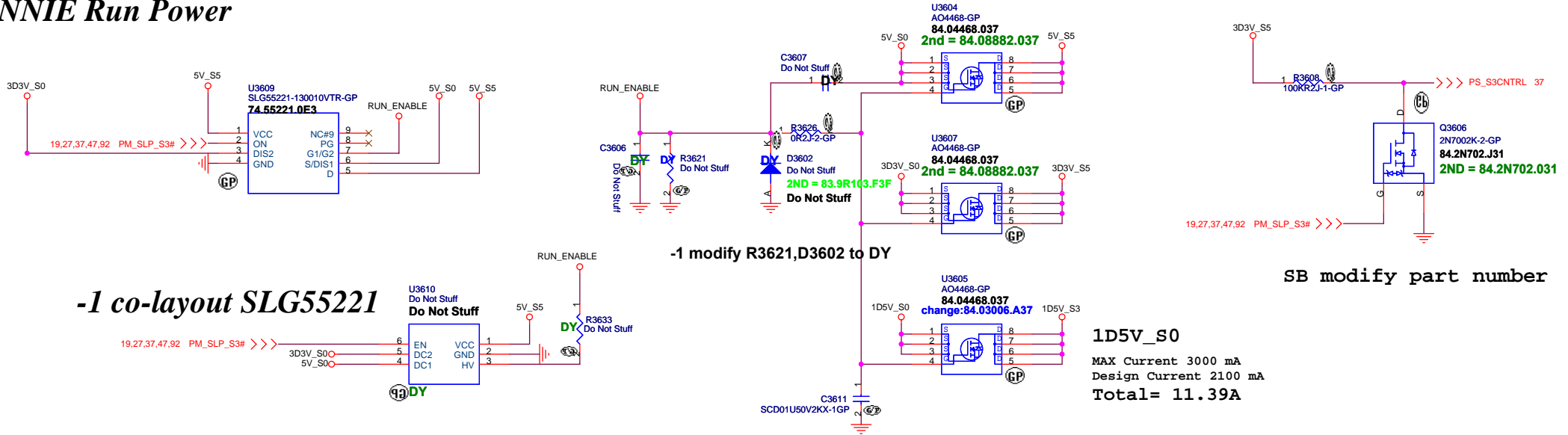
-1M

Title		
Size	Document Number	Rev
Date:	Sheet	

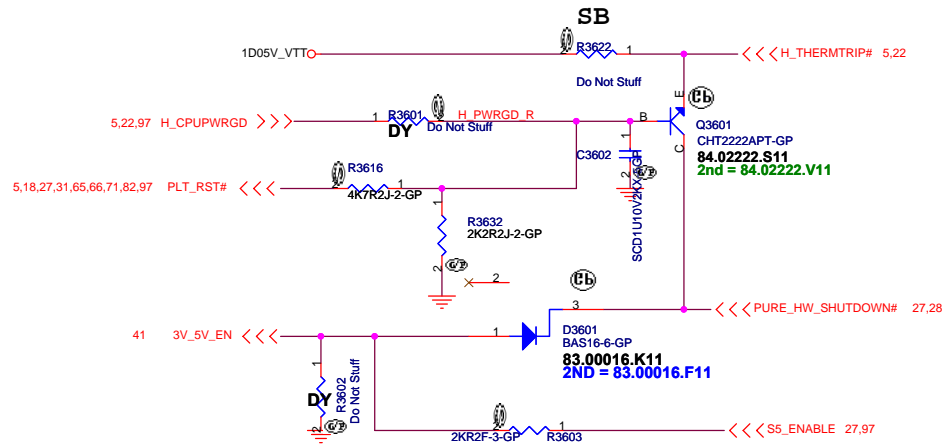
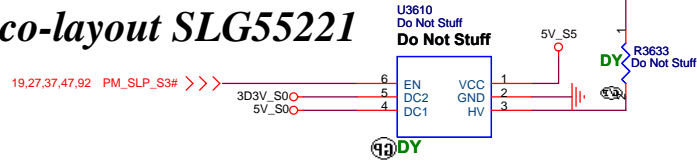
Power Sequence



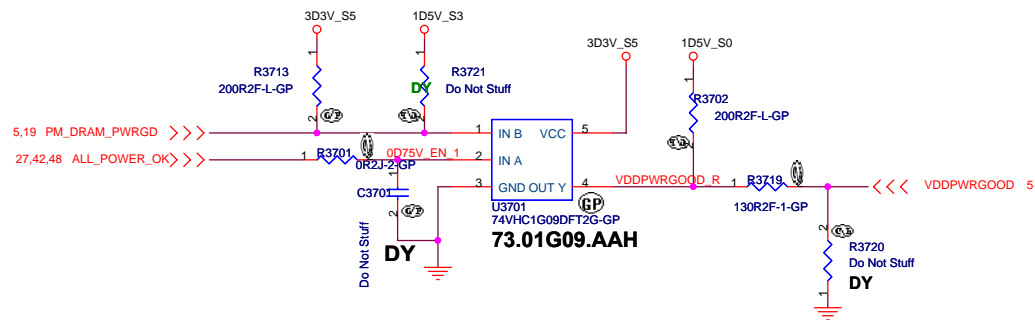
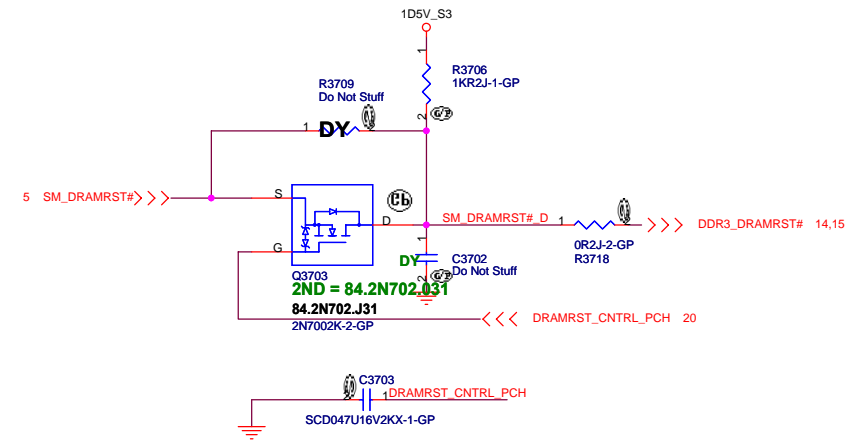
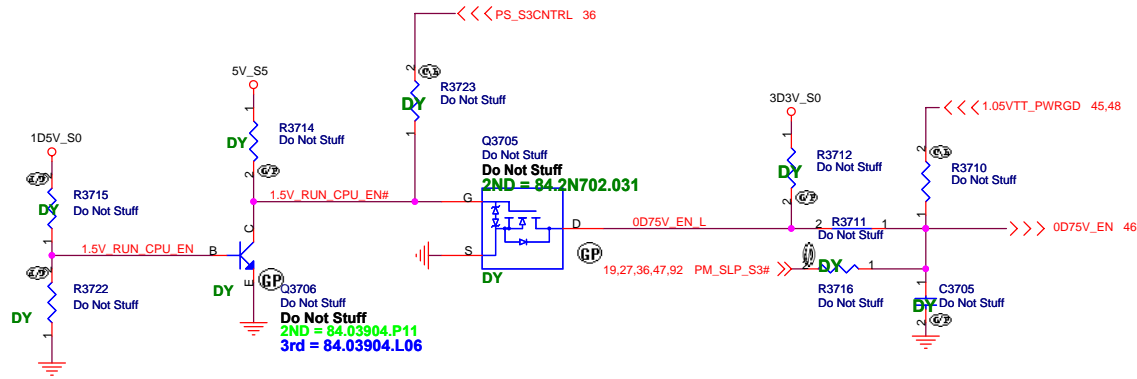
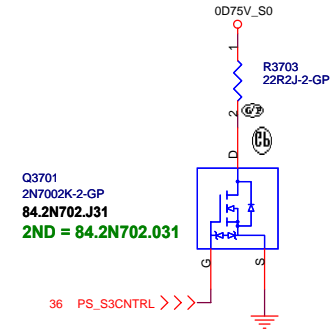
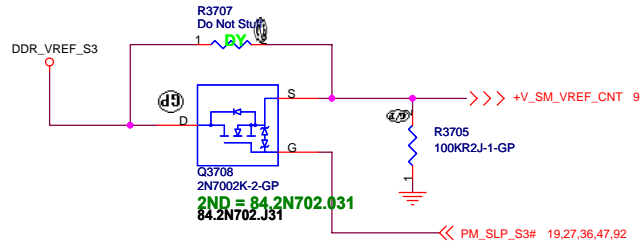
ANNIE Run Power



-1 co-layout SLG55221

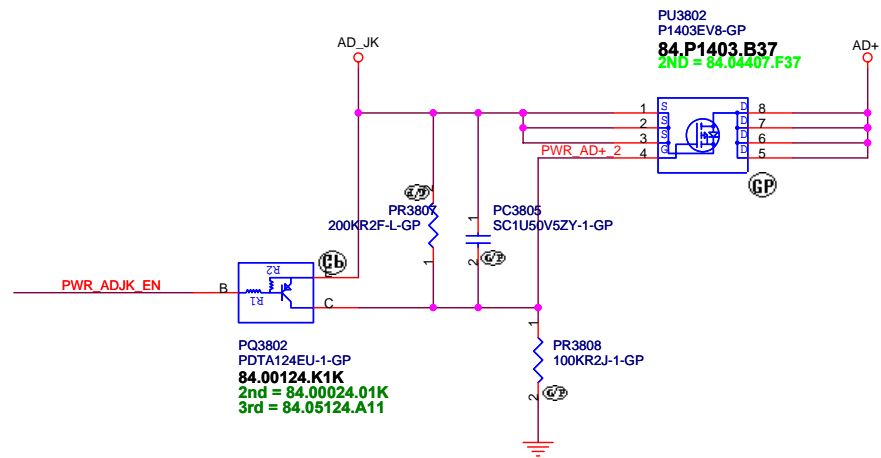
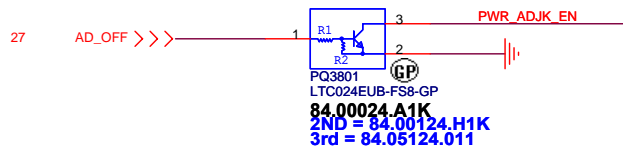
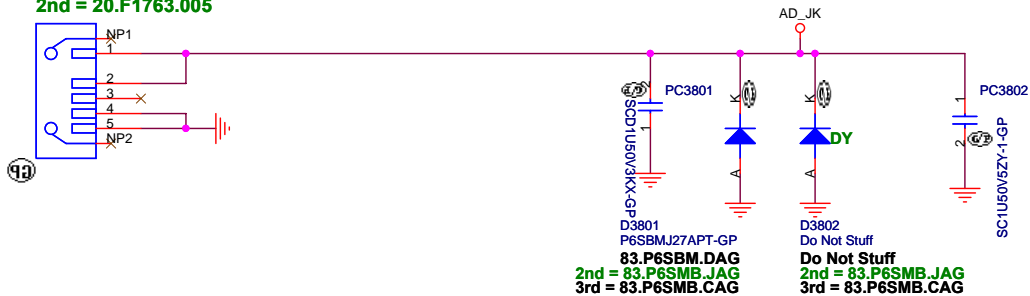


Title		
Size	Document Number	Rev
Date:	Sheet	

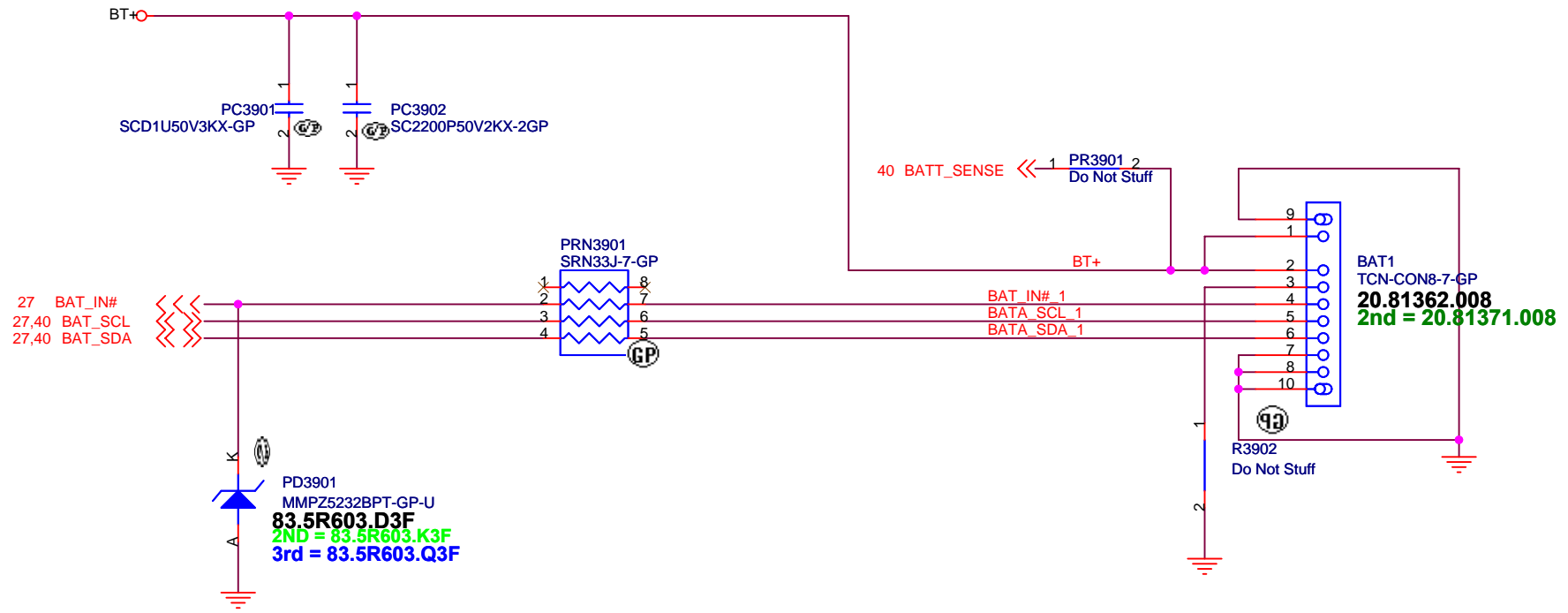


Title		
Size	Document Number	Rev
Date:		Sheet

DCIN1
ACES-CON5-14-GP
20.F1701.005
2nd = 20.F1763.005

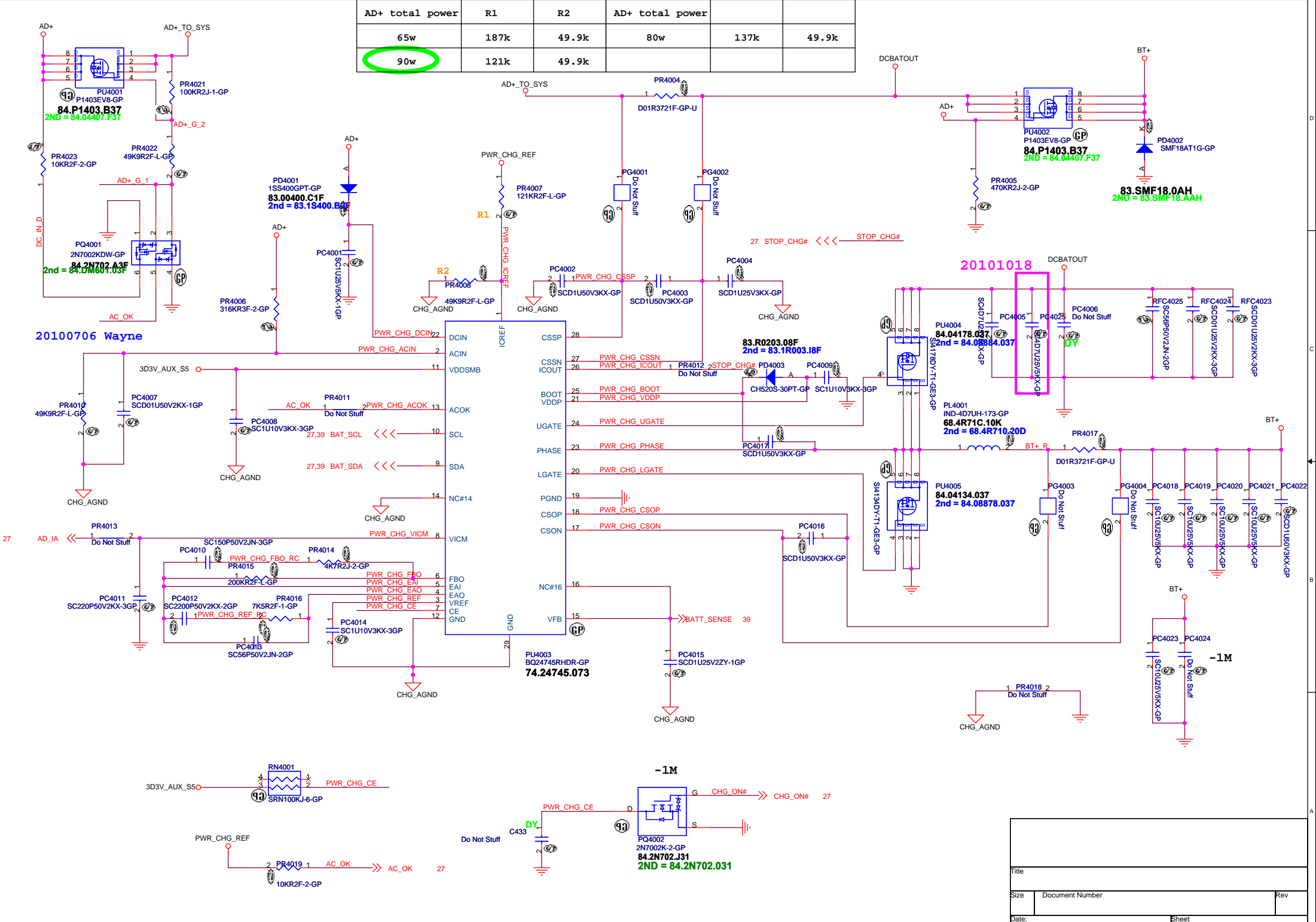


Title		
Size	Document Number	Rev
Date:	Sheet	

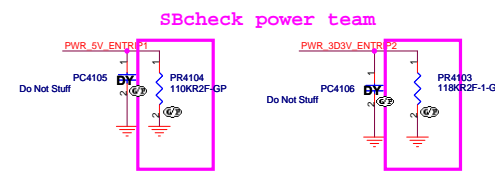
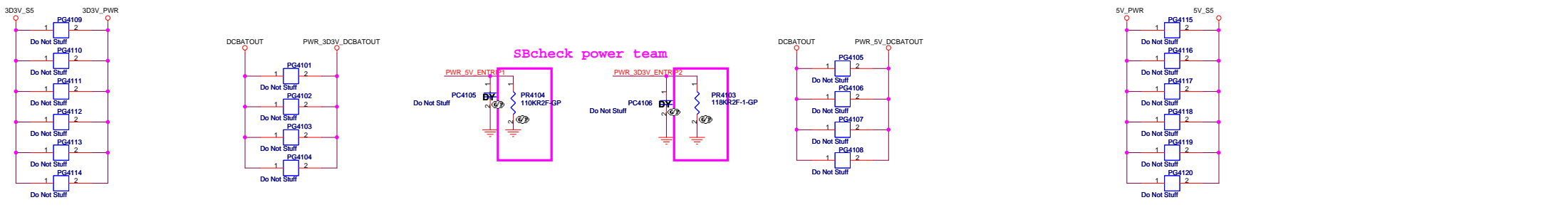


Title		
Size	Document Number	Rev
Date:	Sheet	

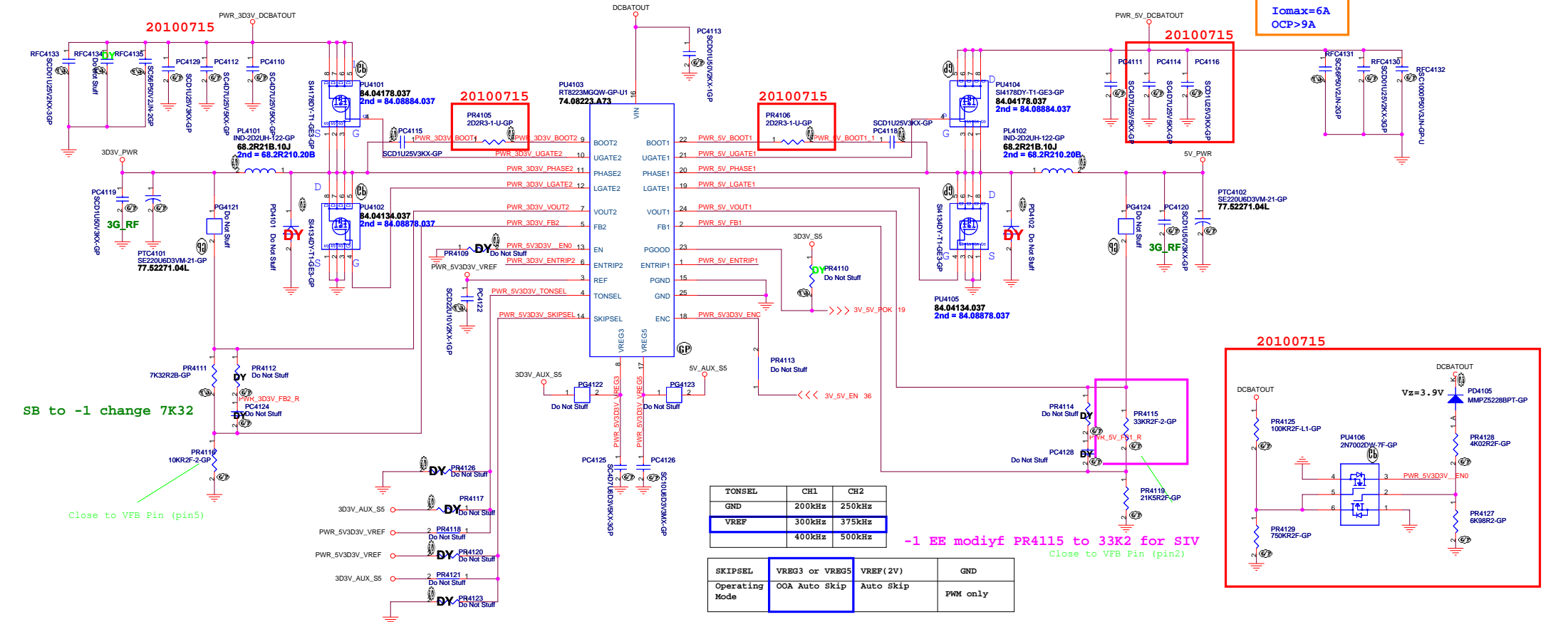
AD+ total power	R1	R2	AD+ total power		
65w	187k	49.9k	80w	137k	49.9k
90w	121k	49.9k			



Title		
Size	Document Number	Rev
Date:		Sheet



I_{max}=6A
OCP>9A



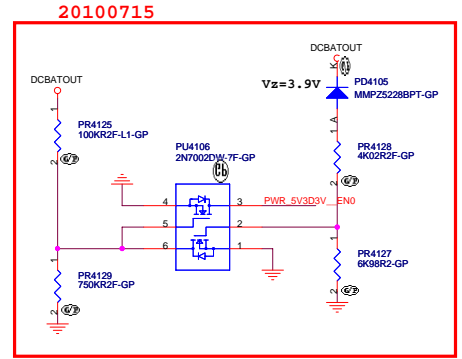
SB to -1 change 7K32

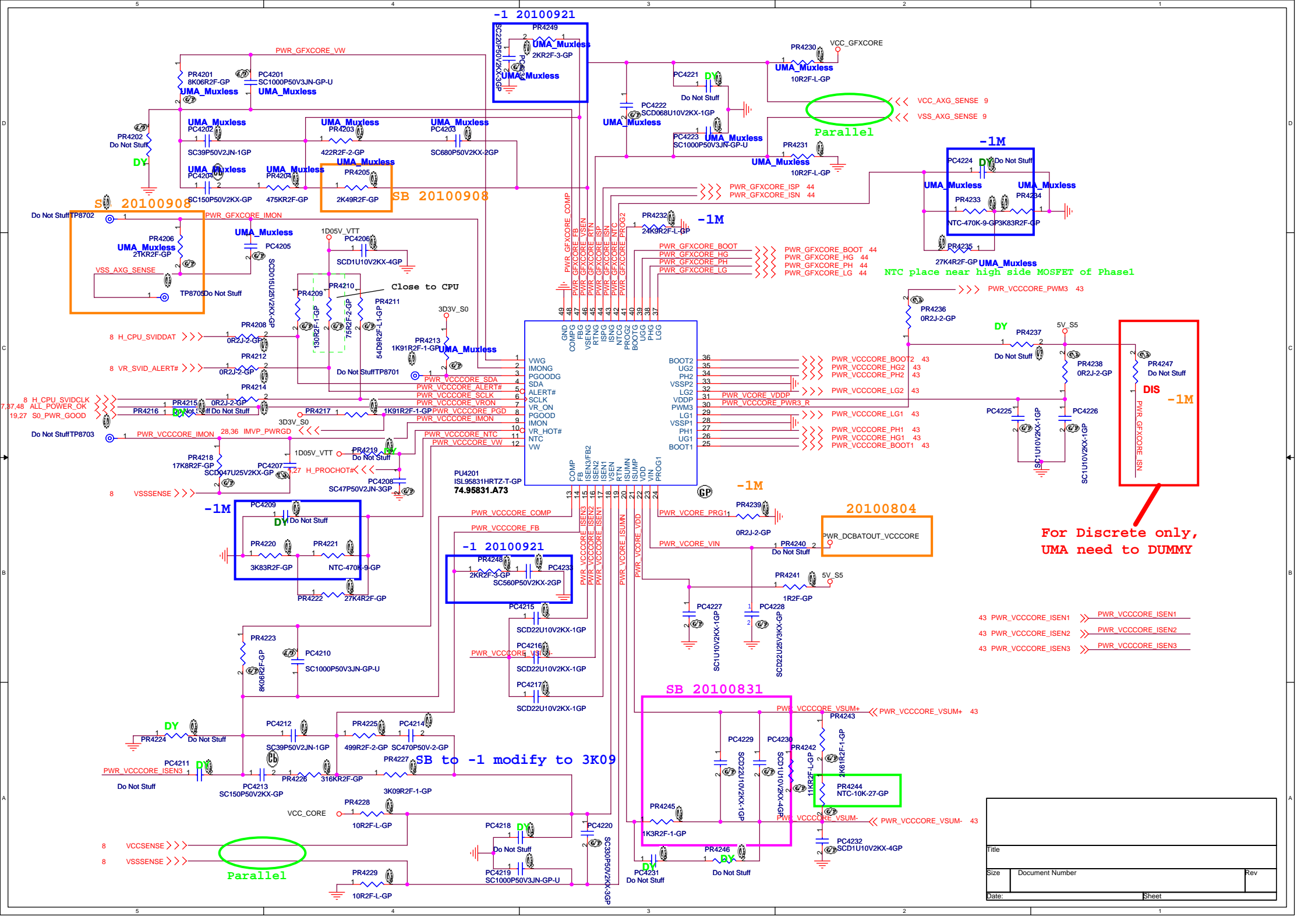
Close to VFB Pin (pin5)

TONSEL	CH1	CH2
GND	200kHz	250kHz
VREF	300kHz	375kHz
	400kHz	500kHz

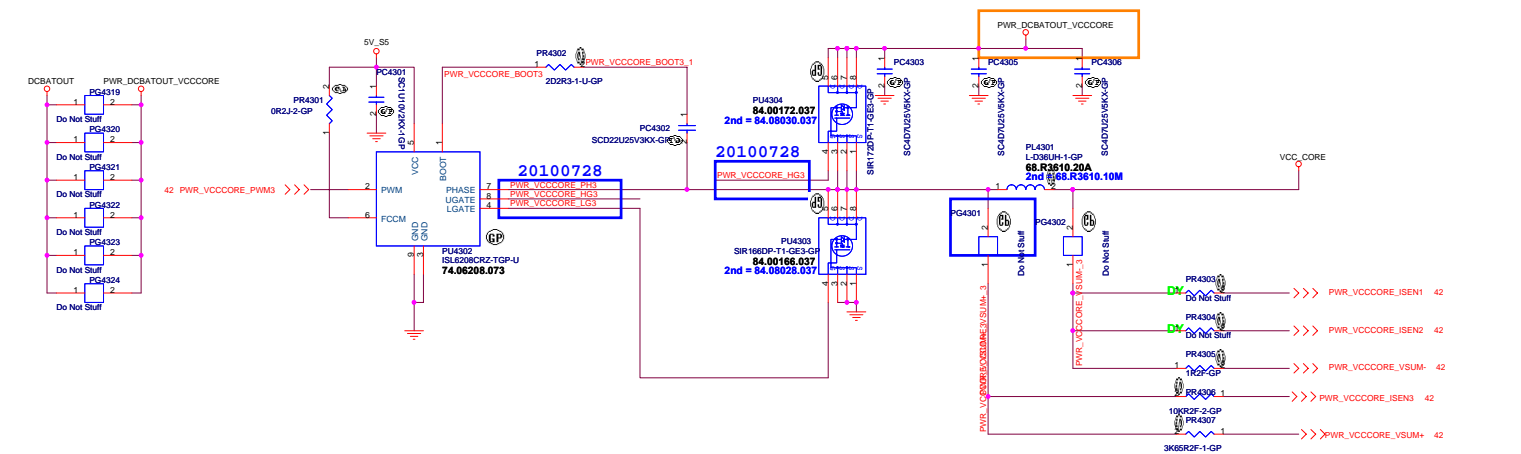
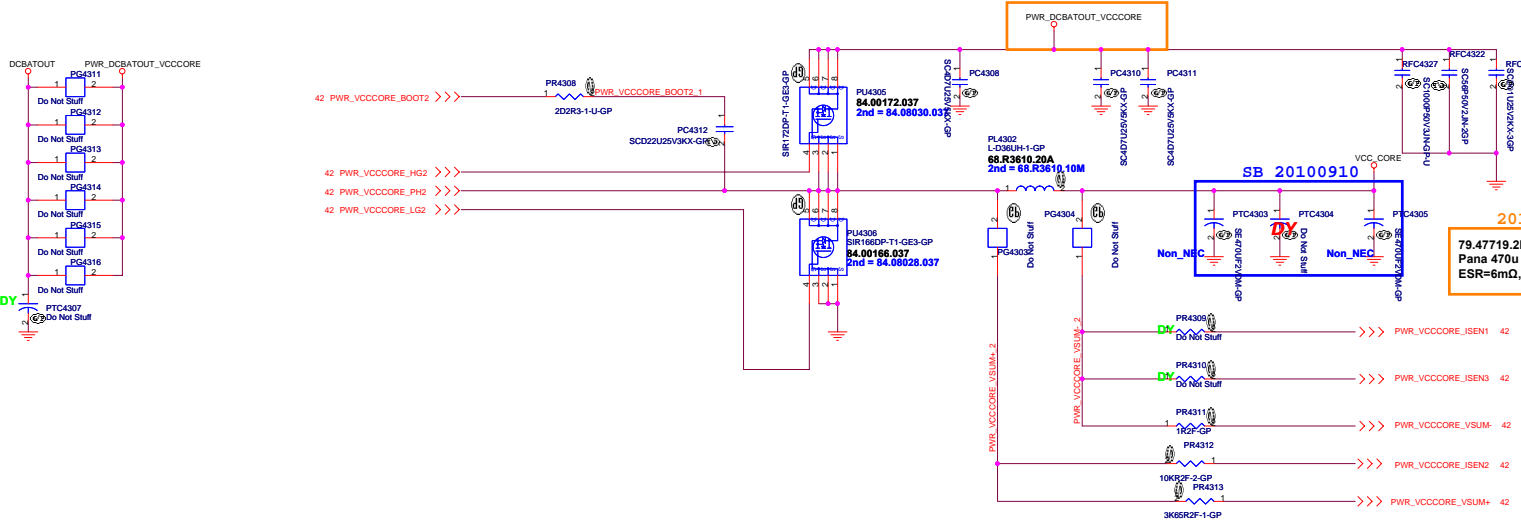
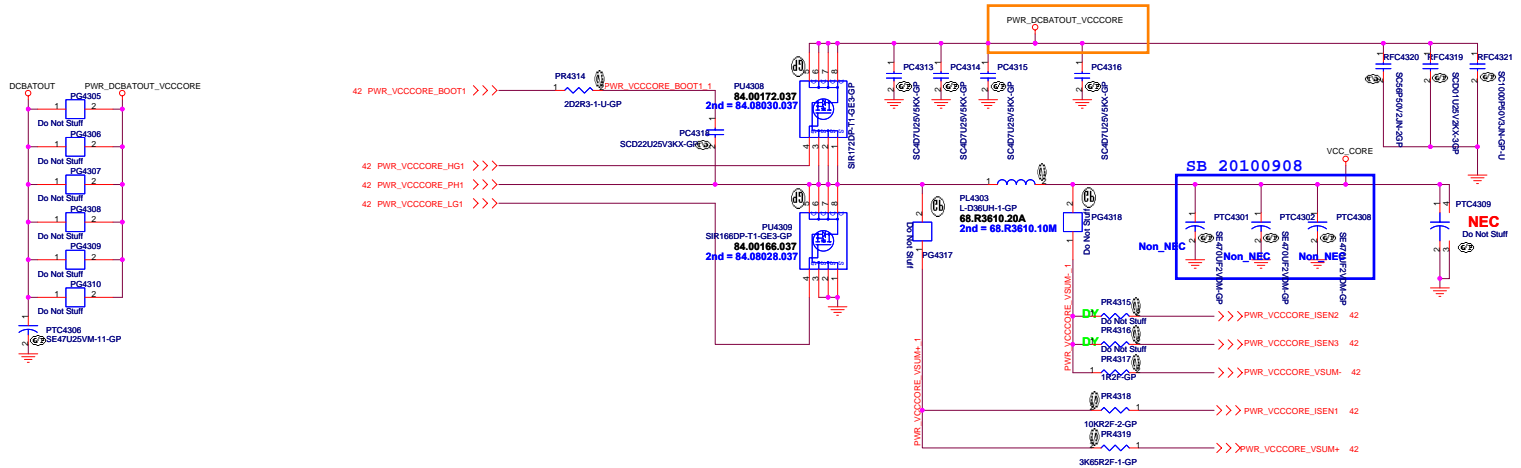
SKIPSEL	VREG3 or VREG5	VREF(2V)	GND
Operating Mode	OOA Auto skip	Auto skip	PWM only

-1 EB modiyf PR4115 to 33K2 for SIV
Close to VFB Pin (pin2)





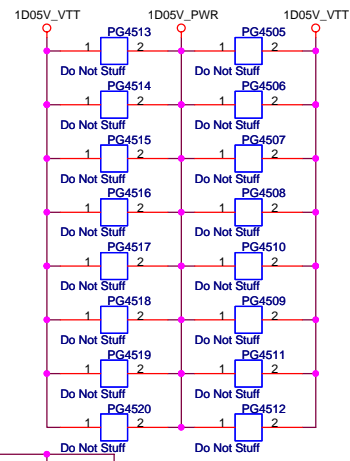
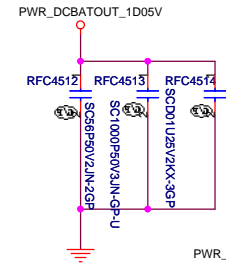
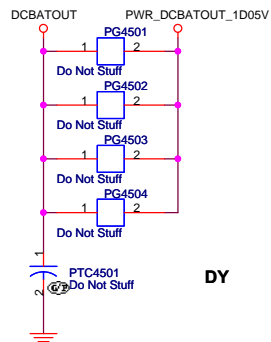
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20100804
79.47719.2BL
Pana 470u, 2V
ESR=6mΩ, Irripple=3.5A

Title		
Size	Document Number	Rev
Date	Sheet	

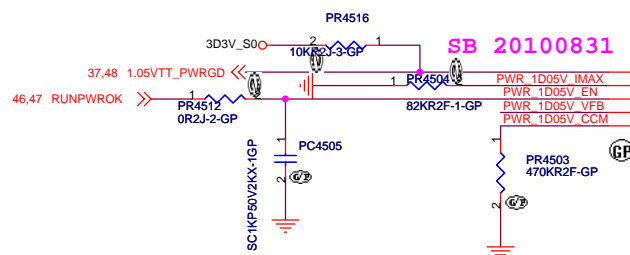
TPS51218D for 1D05V



2nd source 還未導入 74.08237.073

20100728
 $I_d=12.9A$
 $Q_g=9.8-15nC$
 $R_{dson}=10.3-12.4m\Omega$

Freq=360KHz

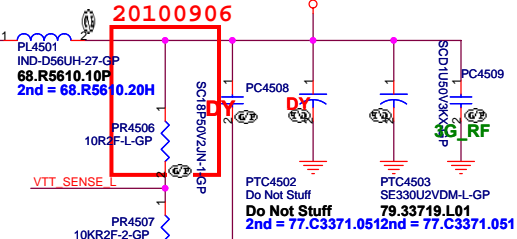


PC4504
PC4506
PC4507
PC4511

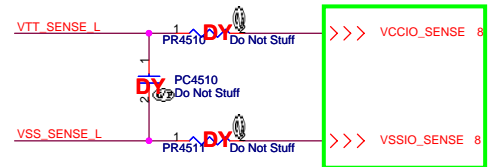
SC1D1U25V5KX-GP
SC1D1U25V5KX-GP
SC1D1U25V5KX-GP
SC1D1U25V3KX-GP

Mag. 0.56uH 10*10*4
 $DCR=1.6-1.8m\Omega$
 $I_{dc}=25A, I_{sat}=40A$

$I_{omax}=14A$
 $OCP>21A$



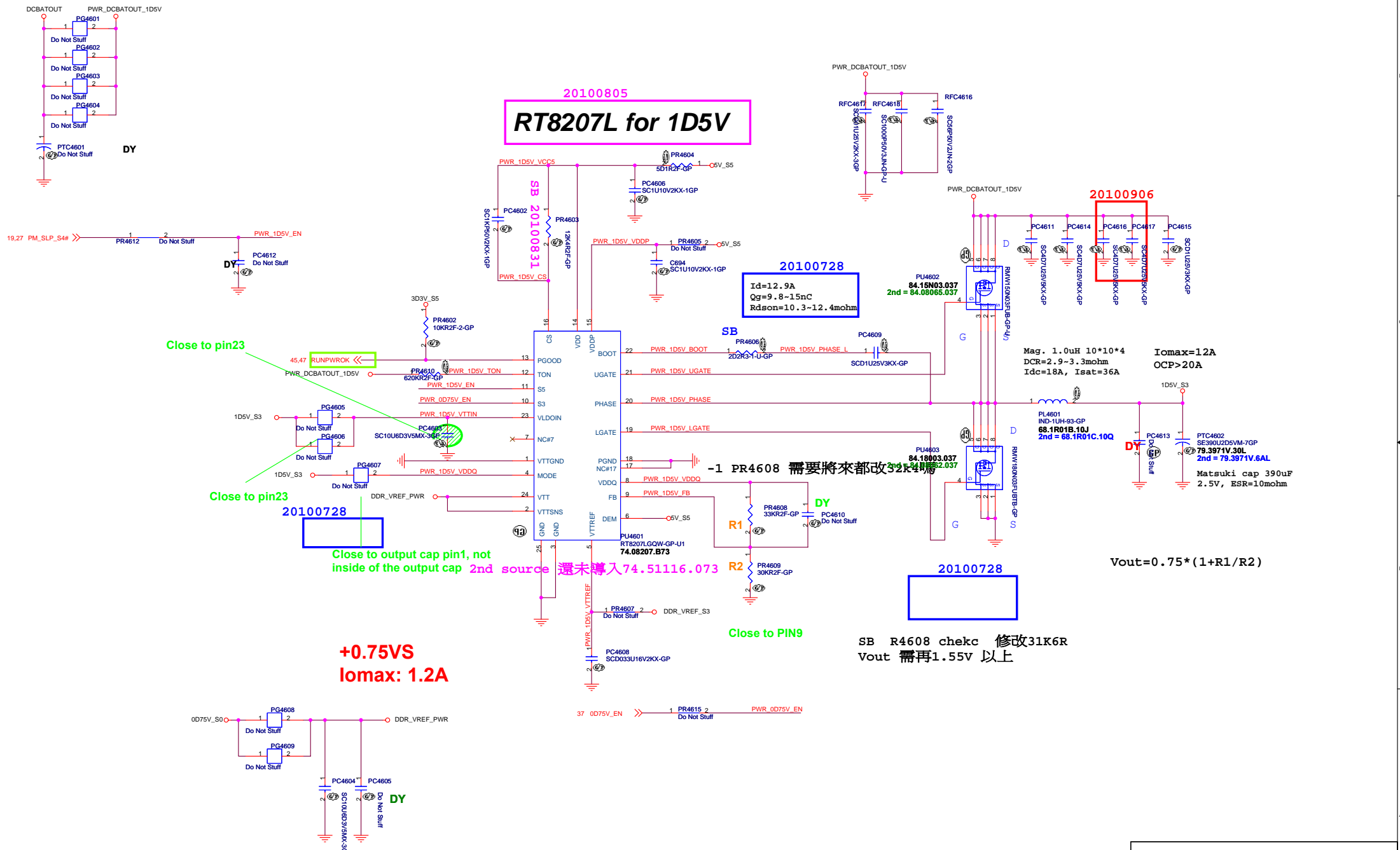
20100728
 $I_d=19.4A$
 $Q_g=16.8-25.5nC$
 $R_{dson}=4.9-6.1m\Omega$



20100728
 $V_{out}=0.704 * (1+R1/R2)$

Title		
Size	Document Number	Rev
Date:	Sheet	

SSID = PWR.Plane.Regulator_1p5v0p75v



20100728
Id=12.9A
Qg=9.8-15nC
Rdson=10.3-12.4mohm

20100906

Close to pin23

Close to pin23

Close to output cap pin1, not inside of the output cap 2nd source 還未導入 74.51116.073

+0.75VS
Iomax: 1.2A

-1 PR4608 需要將來都改32K4碼

Close to PIN9

SB R4608 chekc 修改31K6R
Vout 需再1.55V 以上

Mag. 1.0uH 10*10*4
DCR=2.9-3.3mohm
Idc=18A, Isat=36A

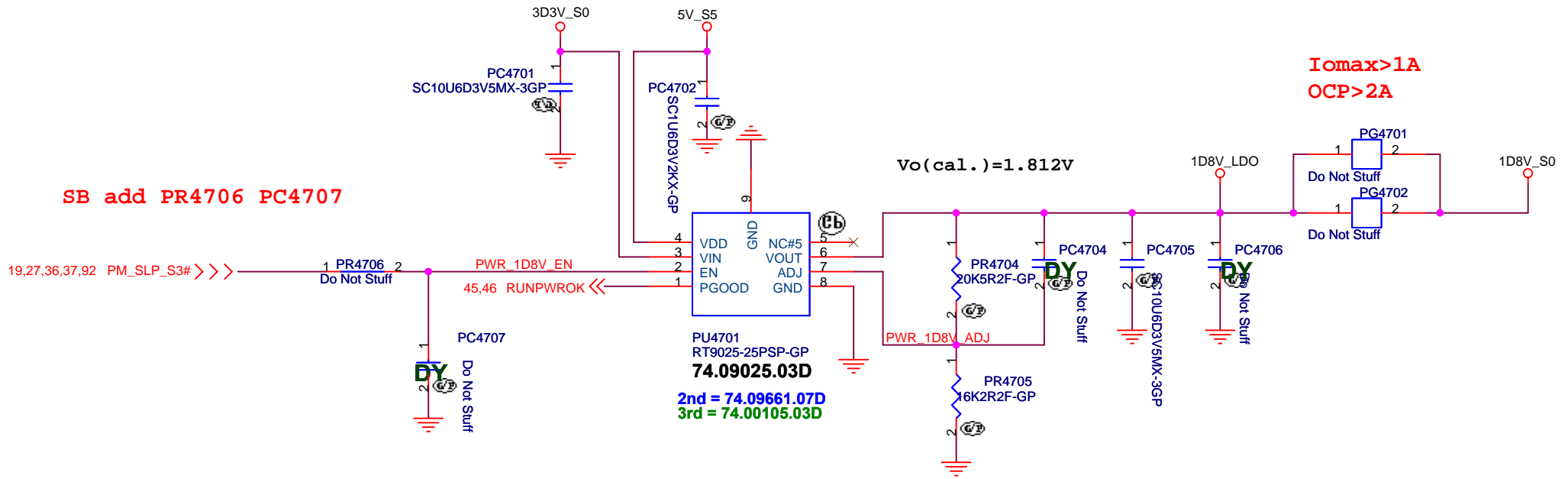
Iomax=12A
OCP>20A

$$V_{out} = 0.75 * (1 + R1/R2)$$

Title		
Size	Document Number	Rev
Date:	Sheet	

SSID = PWR.Plane.Regulator_1p8v

RT9025 for 1D8V_S0

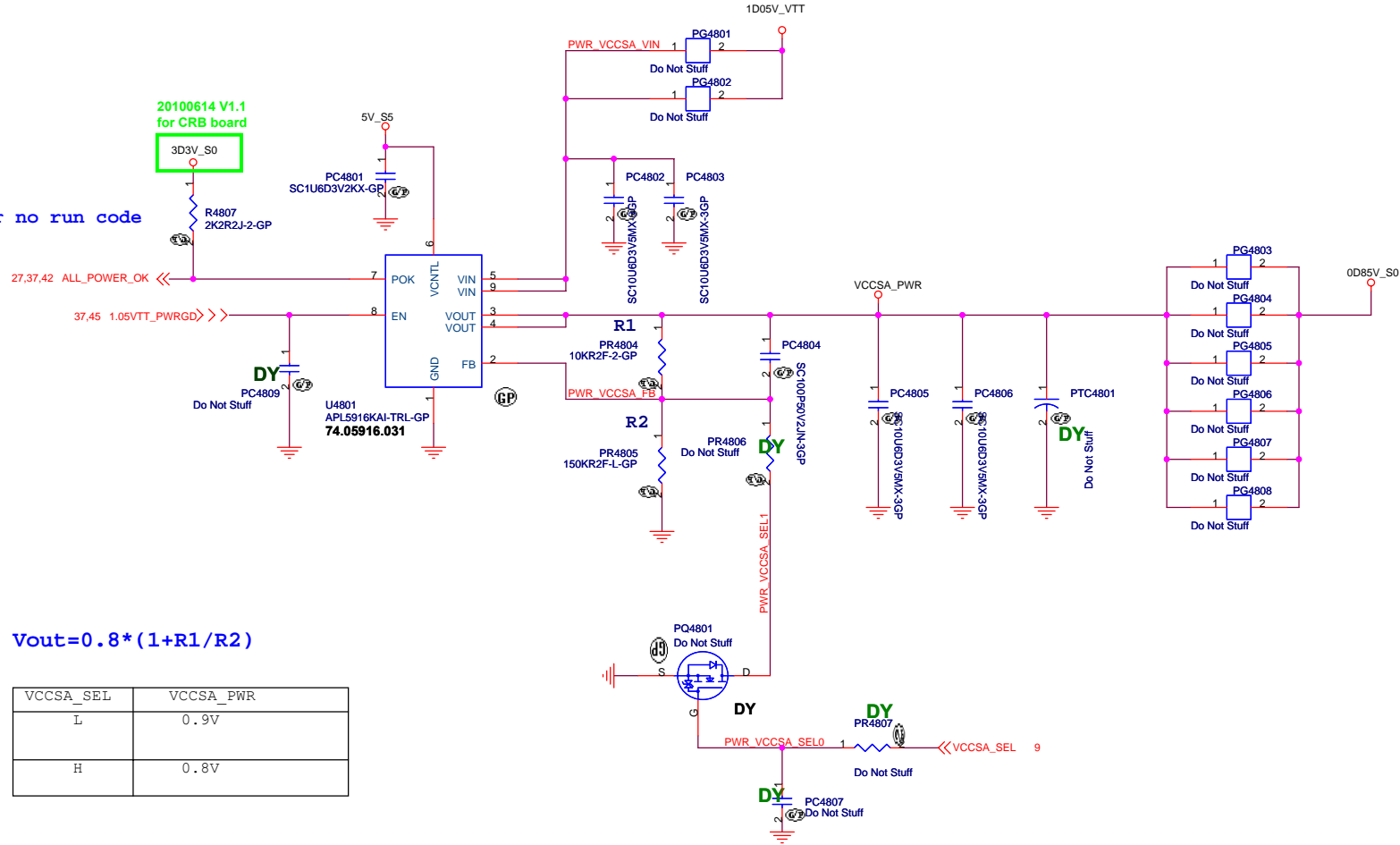


Title		
Size	Document Number	Rev
Date:	Sheet 1	

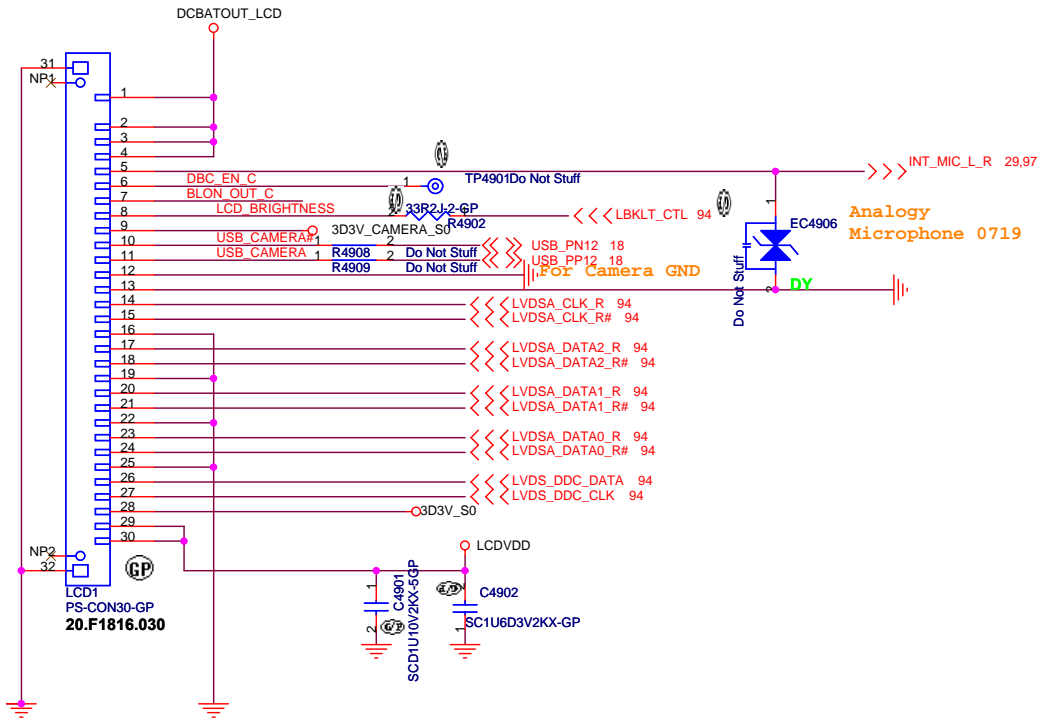
APL5916 for VCCSA

20100614 V1.1
for CRB board

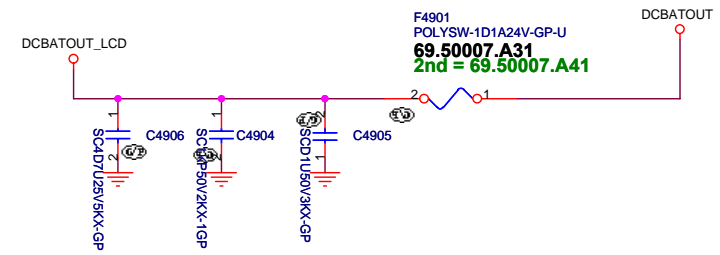
SB modify 2K2 for no run code



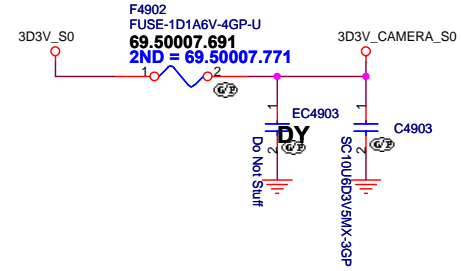
LVDS CONNECTOR



INVERTER POWER

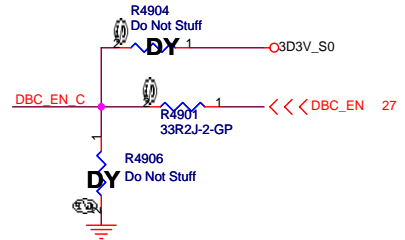
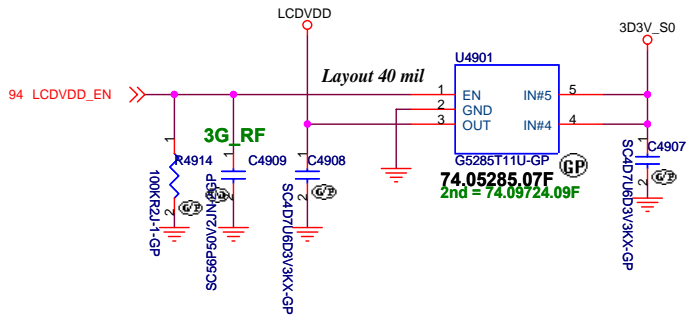


Camera Power

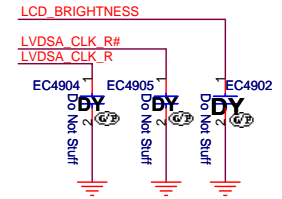


SSID = VIDEO

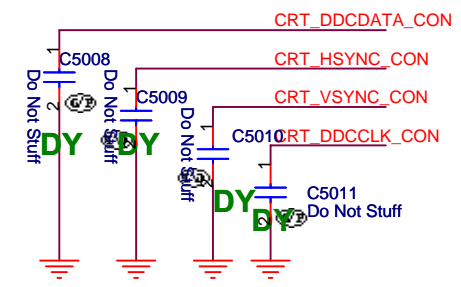
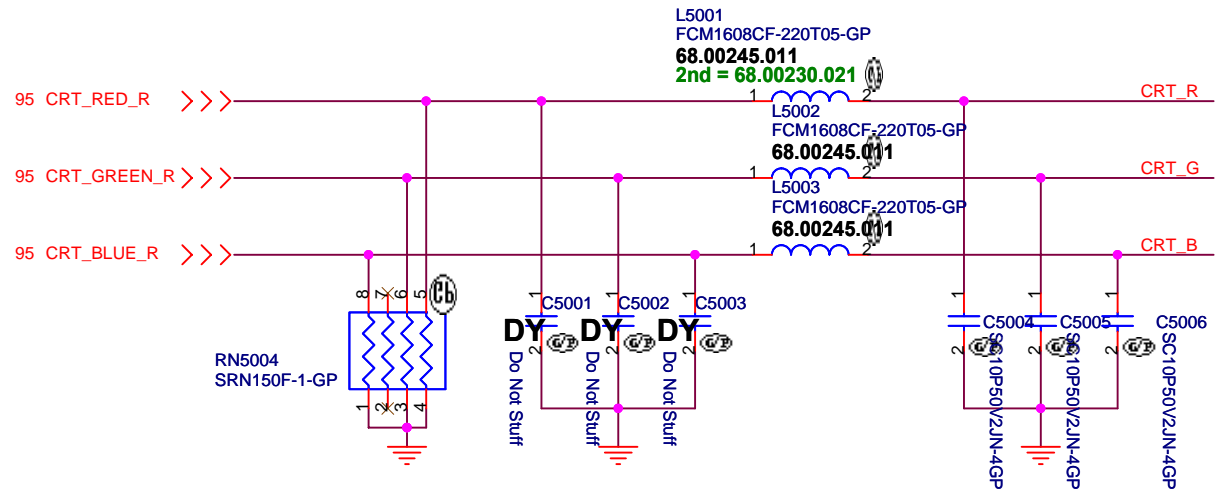
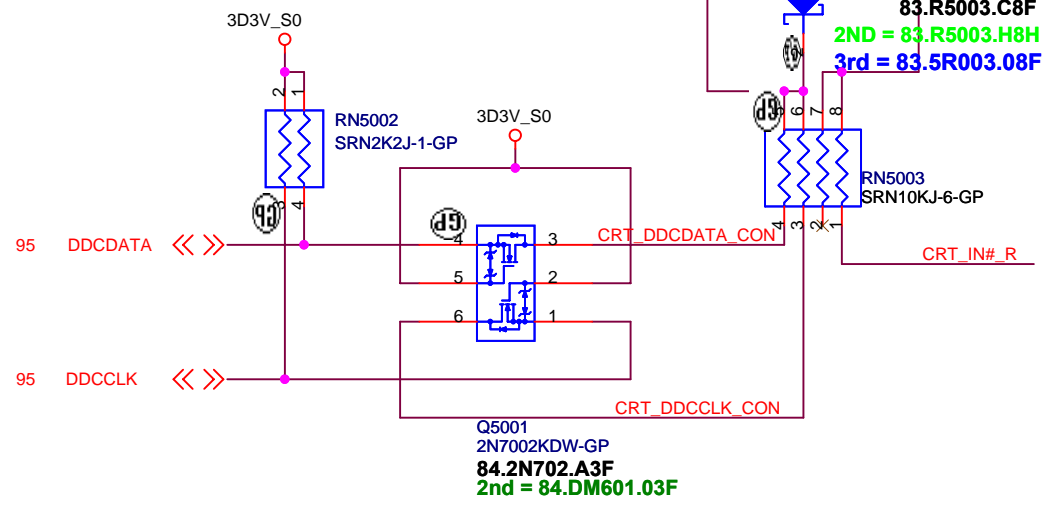
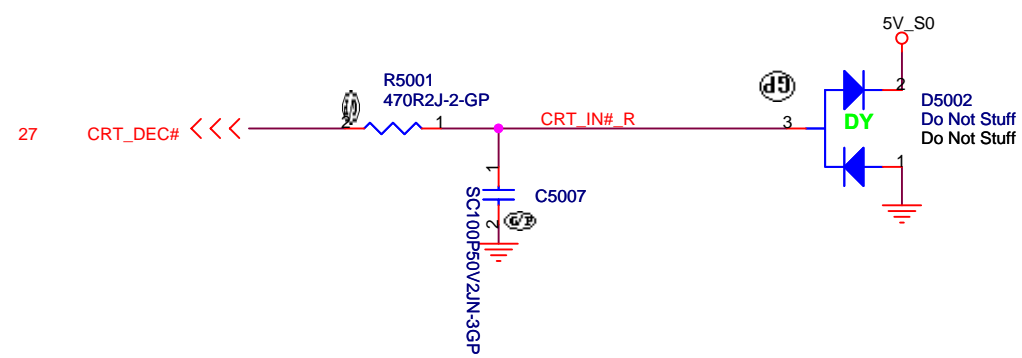
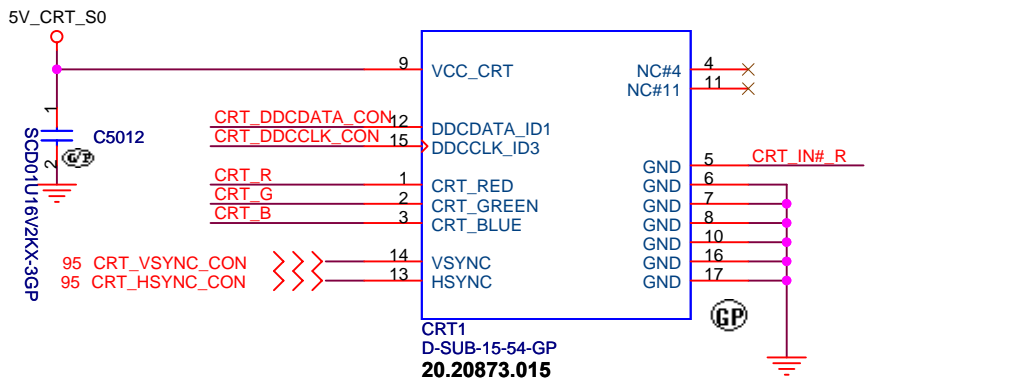
LCD POWER for ANNIE



For EMI request
Close to LVDS connector



Title		
Size	Document Number	Rev
Date:	Sheet	



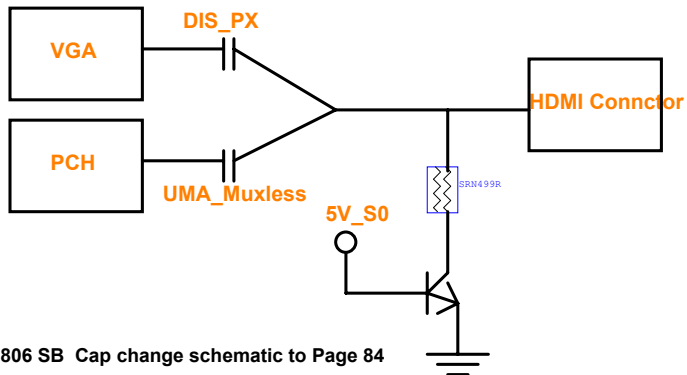
Title		
Size	Document Number	Rev
Date:	Sheet	

HDMI Level Shifter & CONNECTOR

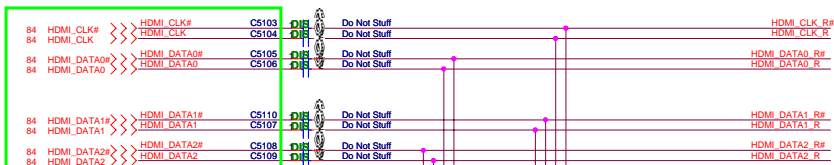
HDMI CONN

UMA_Muxless : default setting used PS8101. if don't used PS8101 please change C5103-C5110 to 0 ohm resistor

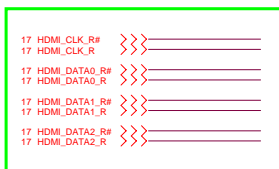
HDMI DISCRETE/ UMA Co-lay



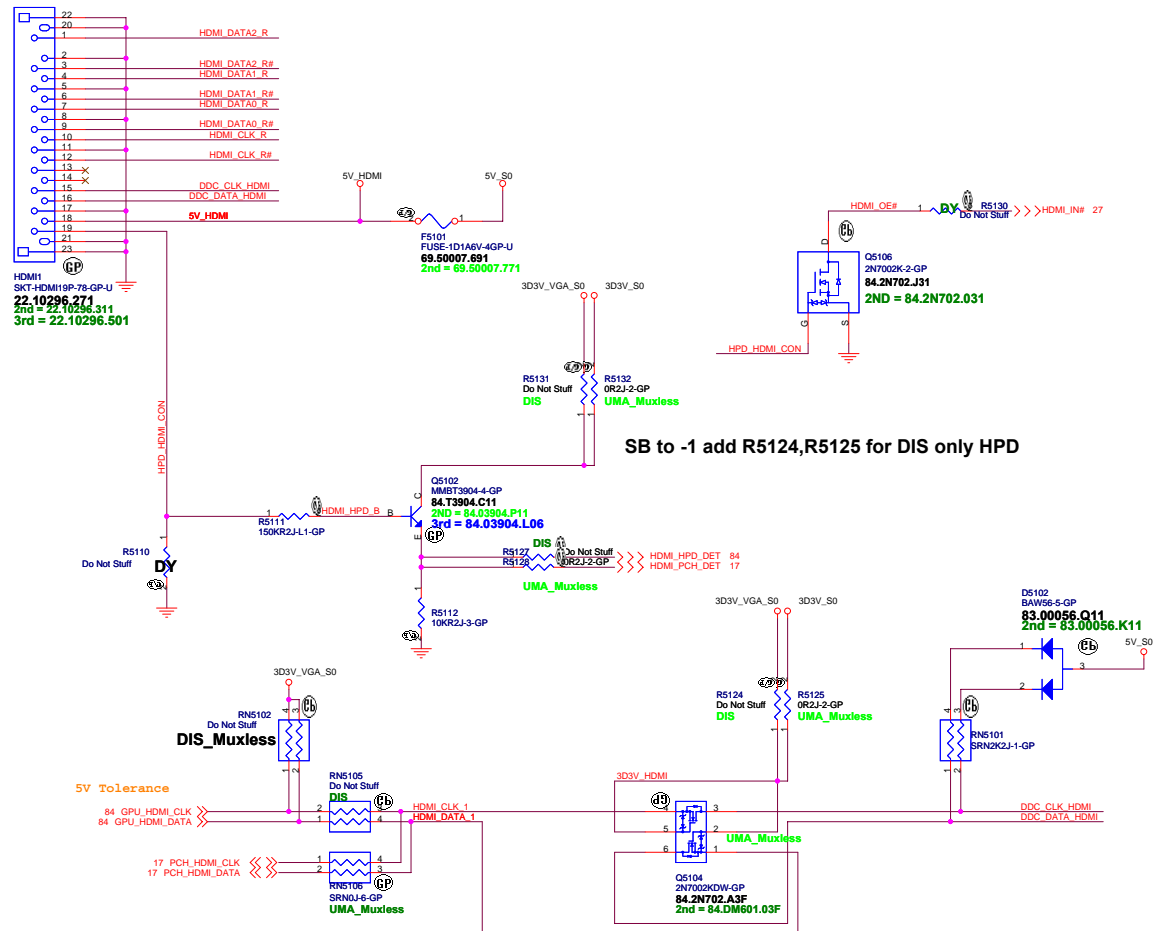
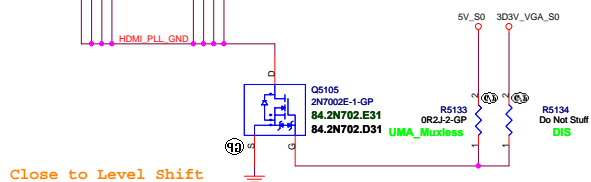
0806 SB Cap change schematic to Page 84



Close to HDMI Connector



SB to -1 for vendor suggest

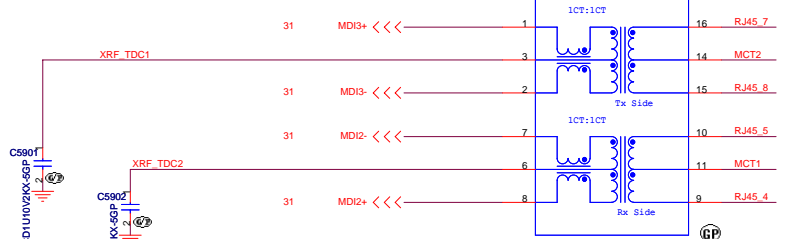


Title	
Size	Document Number
Date	Sheet

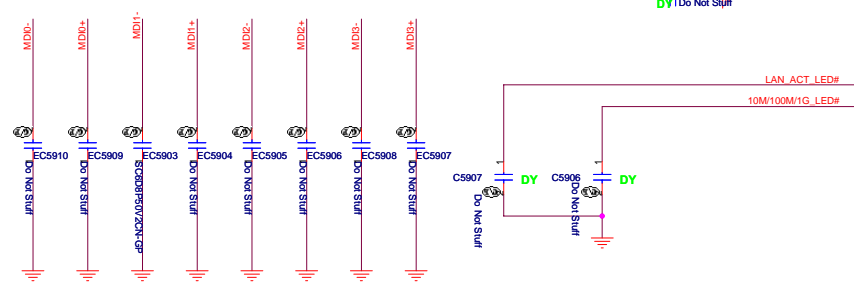
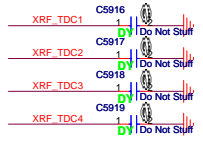
GIGA Lan Transformer

XF5901
XFORM-12P-36-GP
68.HD081.30B
Change: 68.68160.30B
2nd = 68.HD081.30B

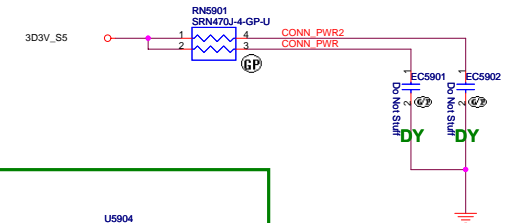
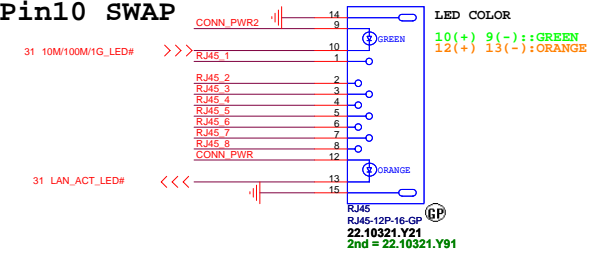
LAN MDI Off-Page



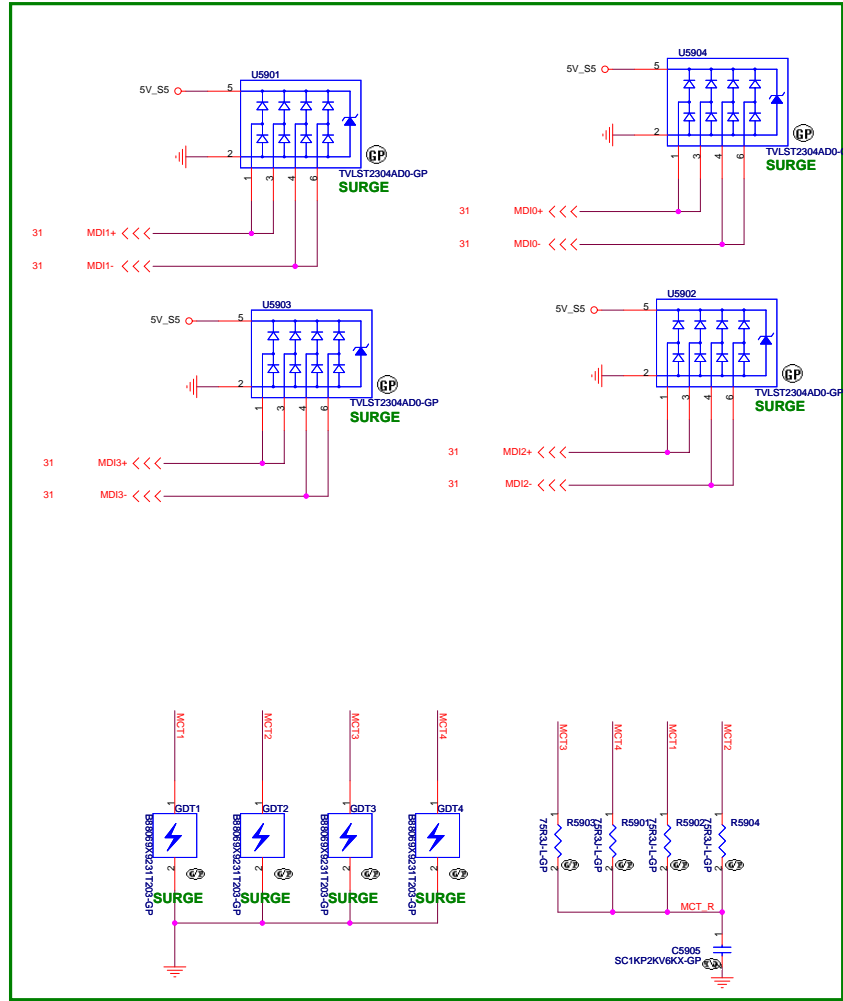
XF5902
XFORM-12P-36-GP
68.HD081.30B
Change: 68.68160.30B
2nd = 68.HD081.30B



SB modifyf Pin9 Pin10 SWAP

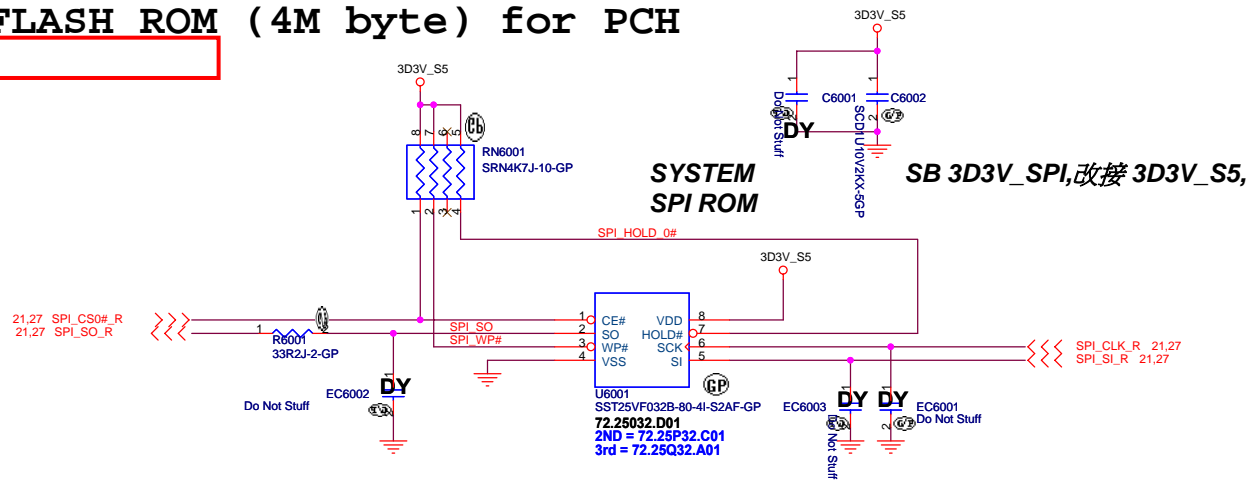


SB modify For EMI



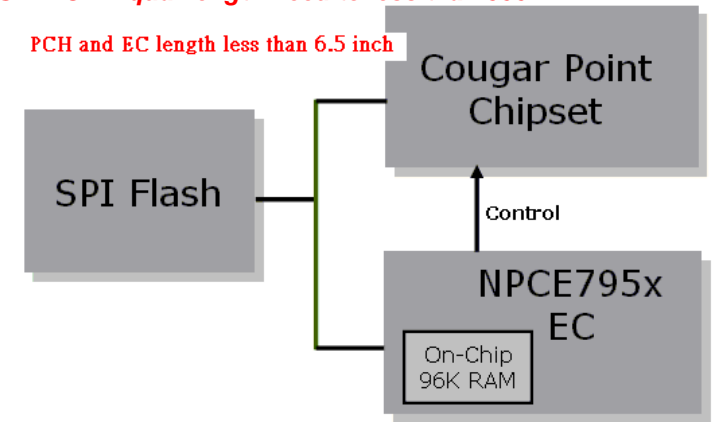
Title		
Size	Document Number	Rev
Date:		Sheet

SPI FLASH ROM (4M byte) for PCH

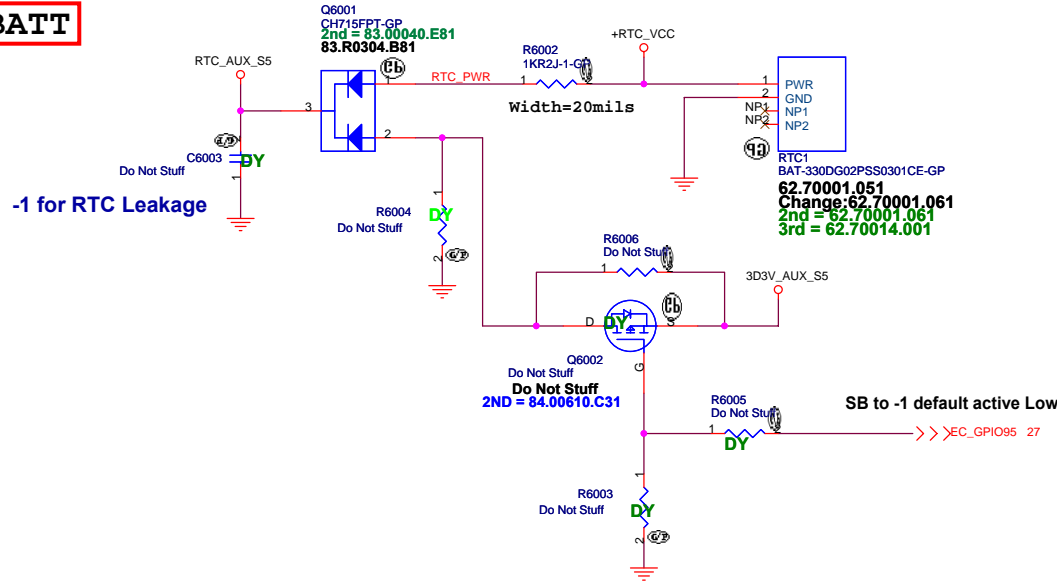


SPI ROM Equal length need to less than 500mil

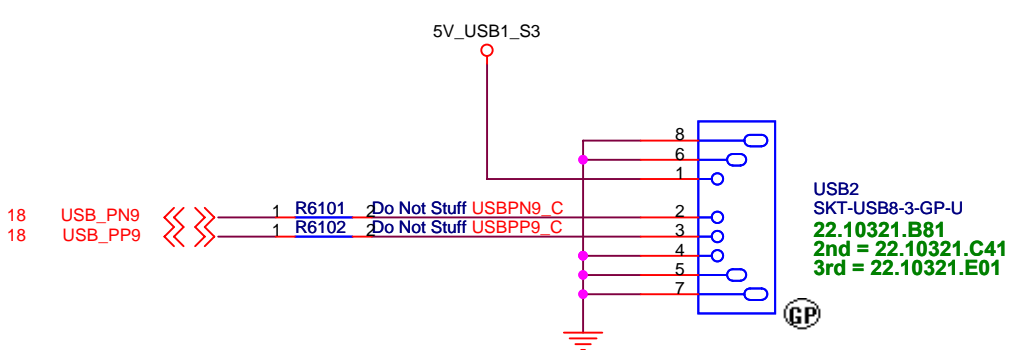
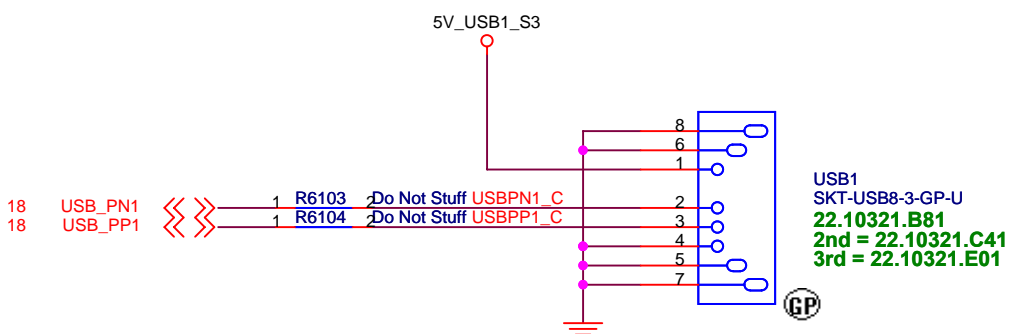
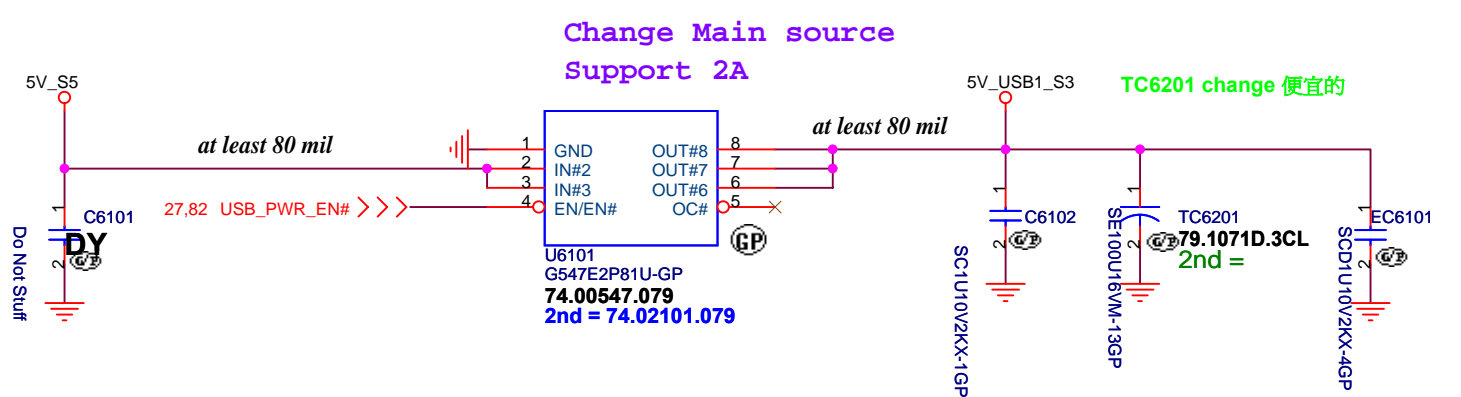
PCH and EC length less than 6.5 inch



SSID = RBATT



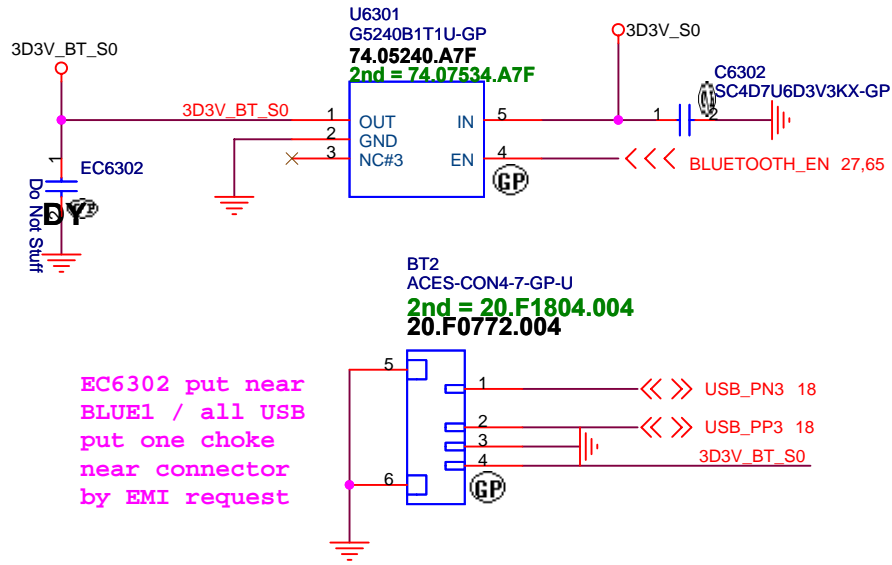
Title		
Size	Document Number	Rev
Date:	Sheet	



Title		
Size	Document Number	Rev
Date	Sheet	

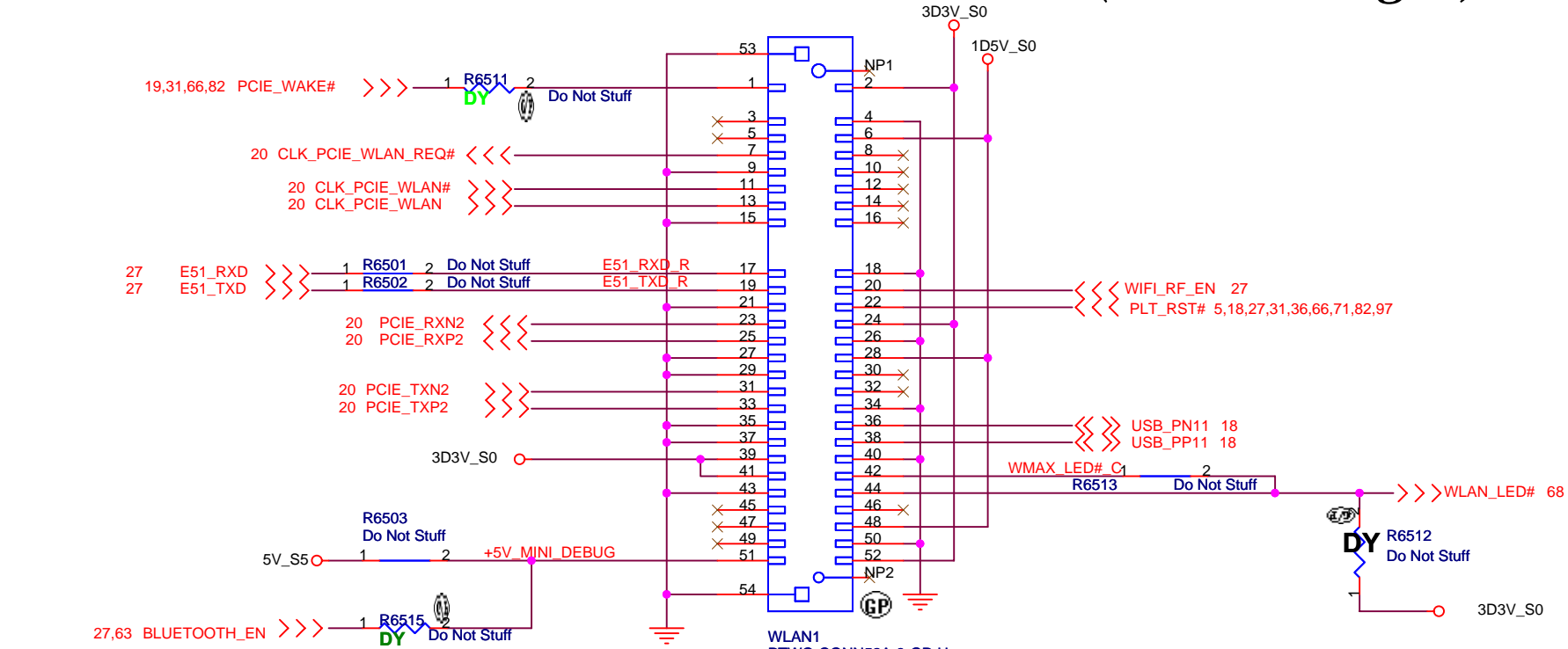
Bluetooth Module conn.

ANNIE Bluetooth Module



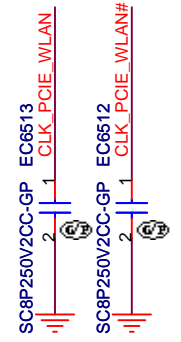
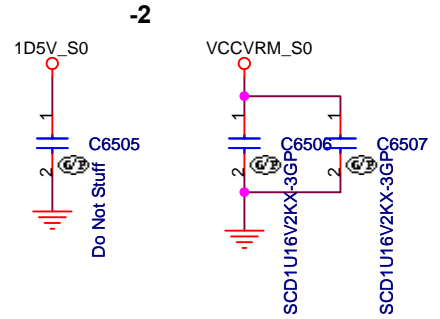
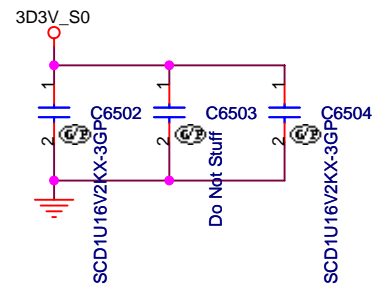
Title		
Size	Document Number	Rev
Date:	Sheet	

Mini Card Connector(802.11a/b/g/n)

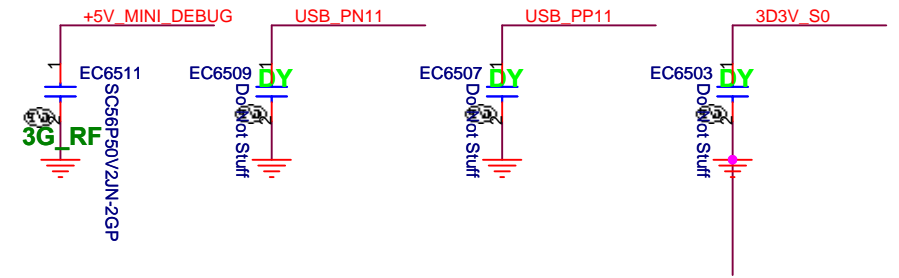


WLAN1
 BTWO-CONN52A-9-GP-U
20.F1519.052
 2nd = 62.10043.A51
 3rd = 20.F1693.052
 4th = 20.F1743.052

SB modify for SIV



RF suggestion

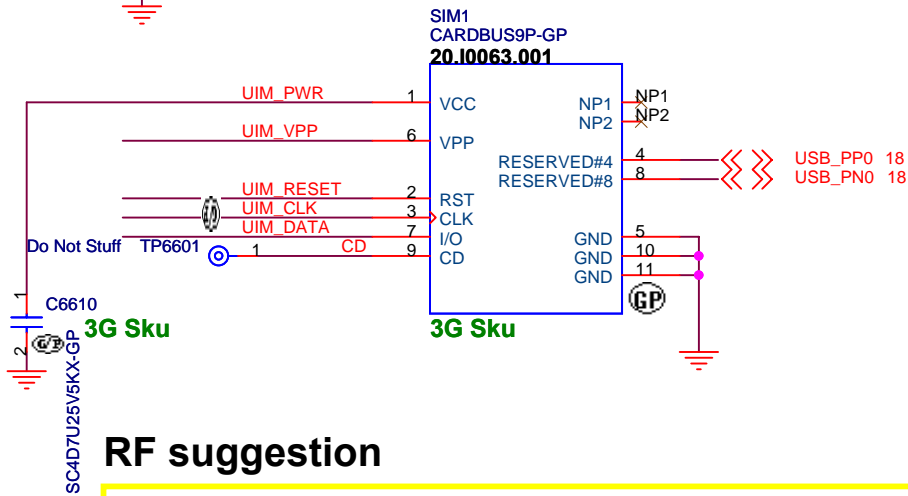
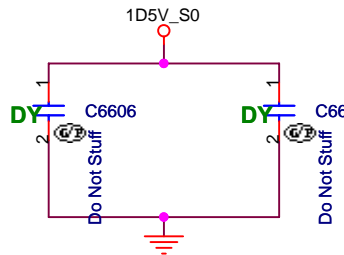
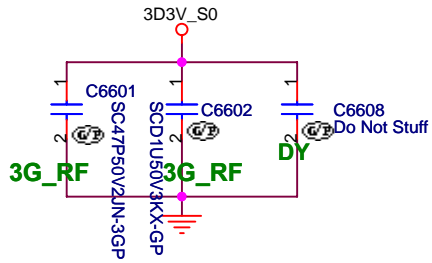


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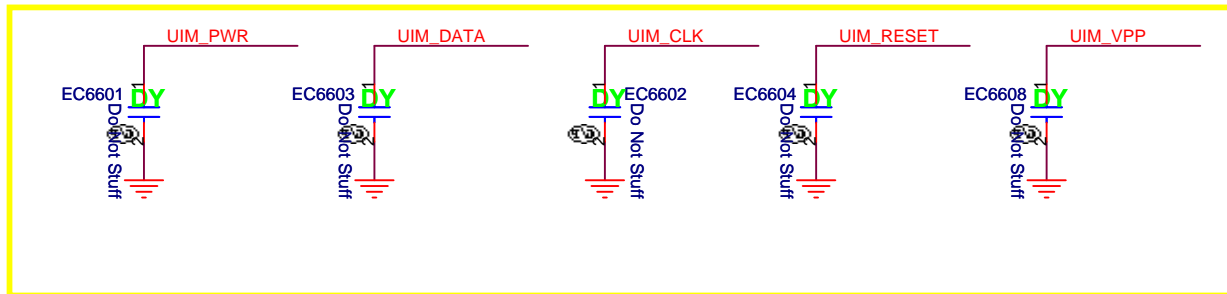
Mini Card Connector(WWAN)

20100712 V1.5

Place near MINI Card CONN

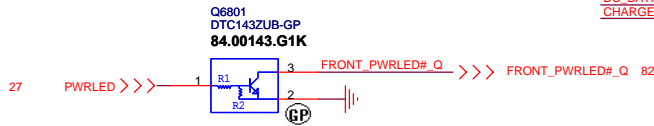


RF suggestion

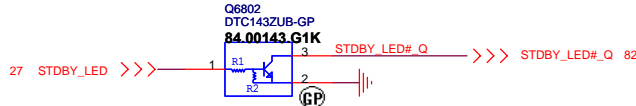


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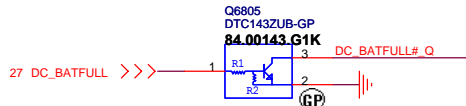
Power button LED



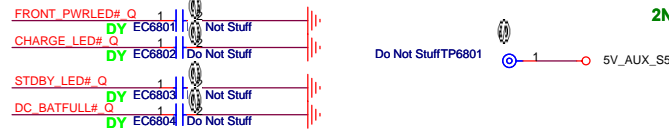
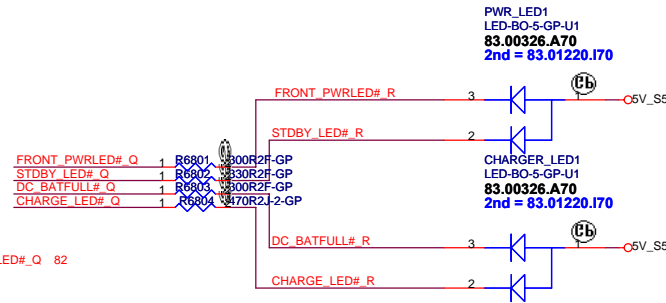
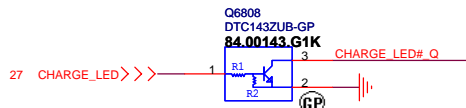
Power STDBY_LED



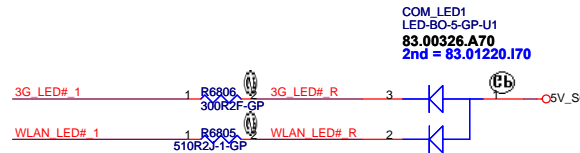
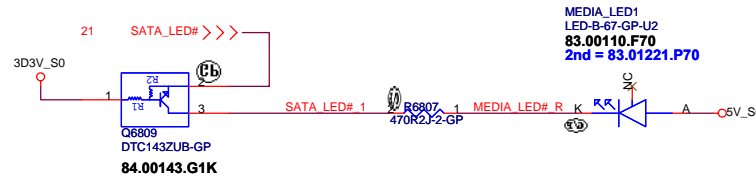
Battery LED2 (DC_BATFULL)



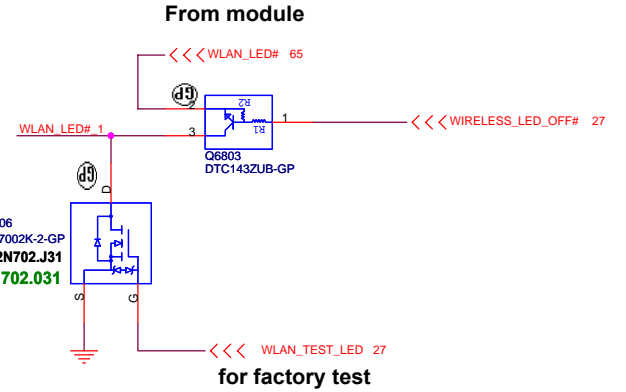
Battery LED1 (CHARGE)



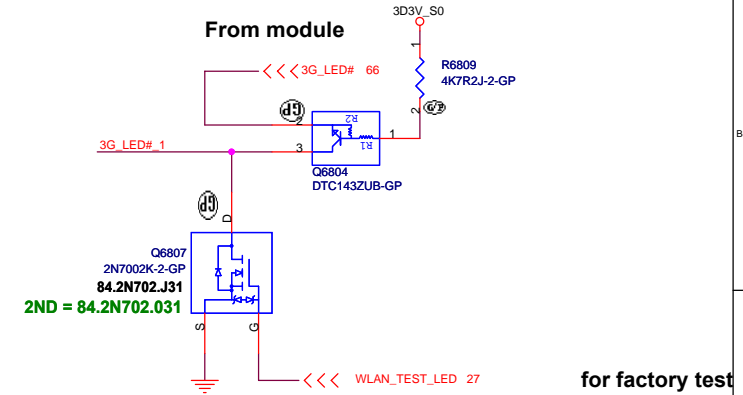
SATA HDD LED



WLAN_LED



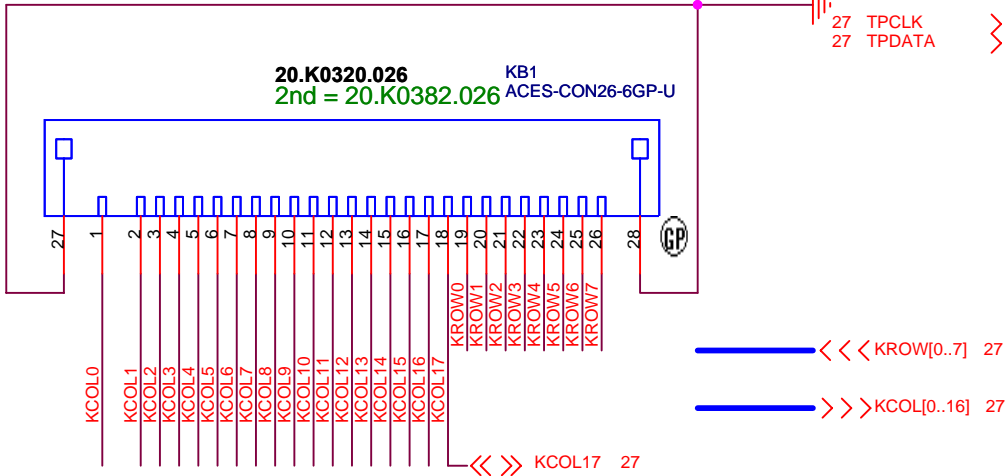
3G LED



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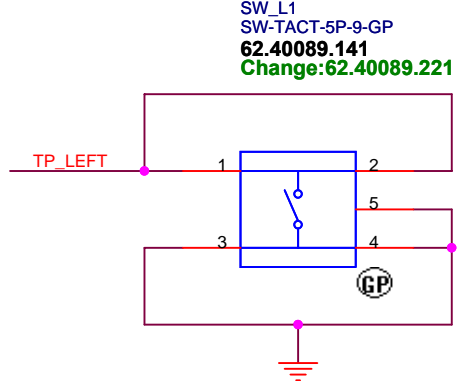
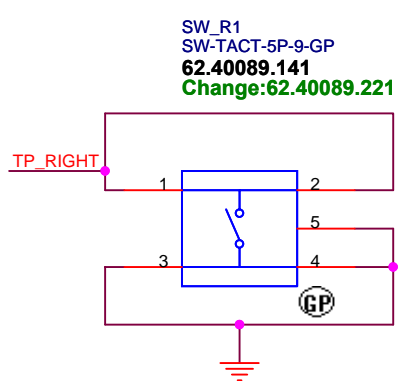


Internal KeyBoard Connector



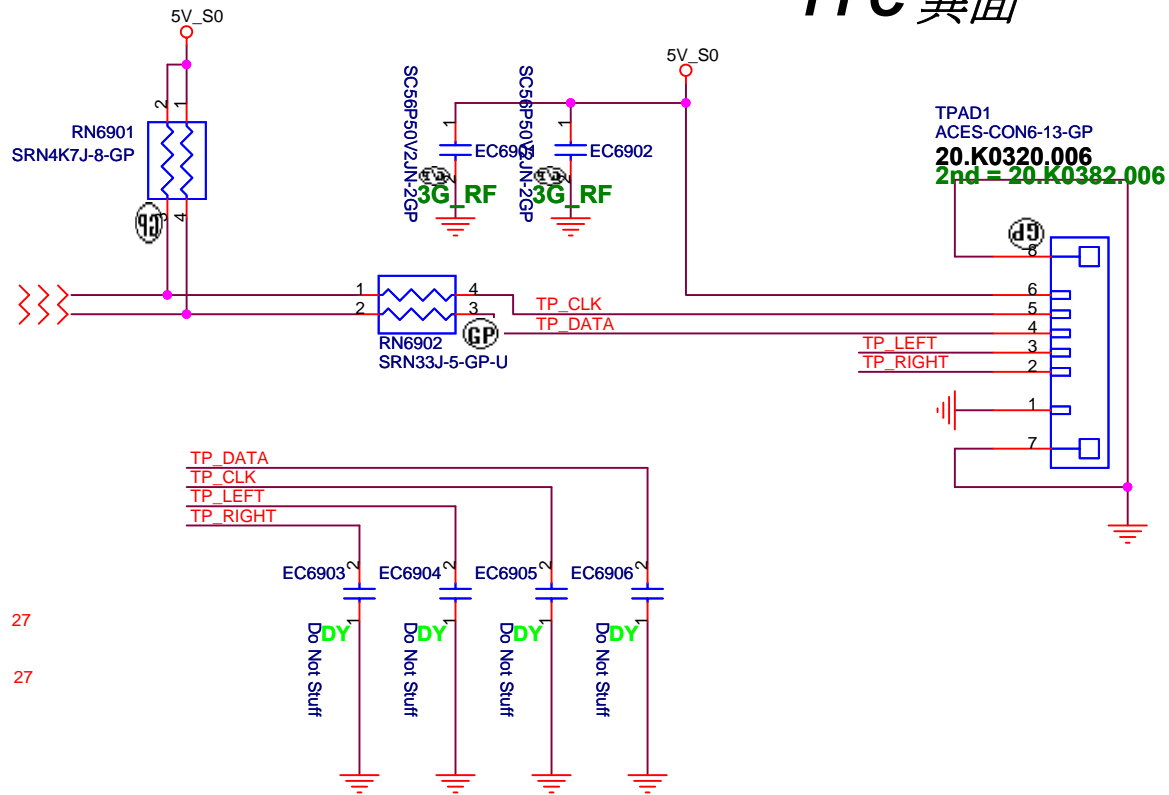
MB PIN DEFINE 26 25 24 23 22 21 20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1
 KB PIN DEFINE 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26

26 **K/B** 1 **SB to -1 modify Part number**

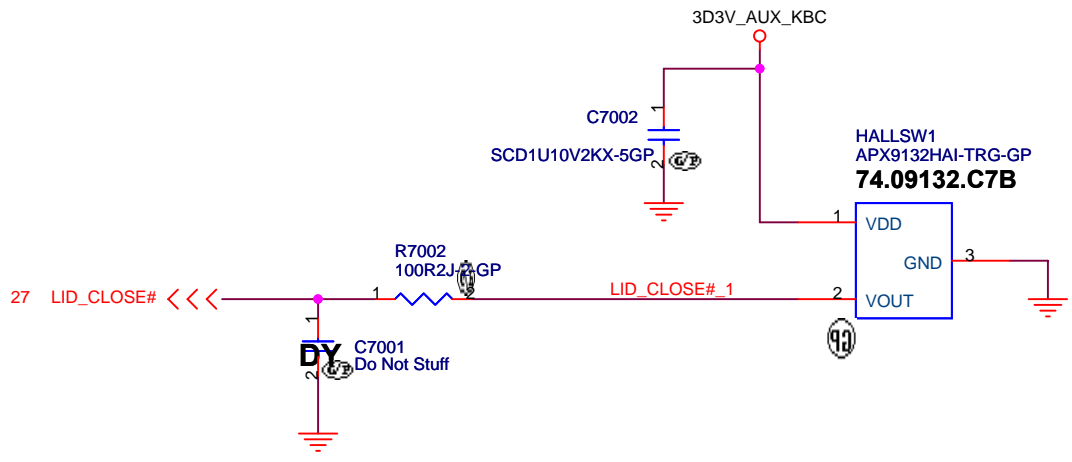


TOUCH PAD

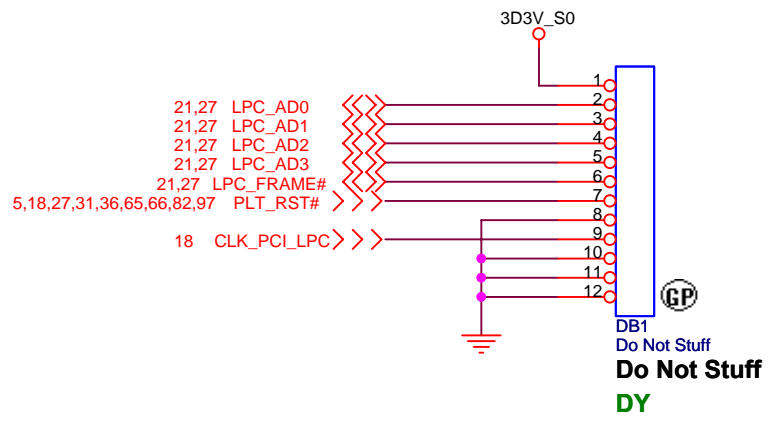
FFC 異面



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SD/XD/MS Card Reader

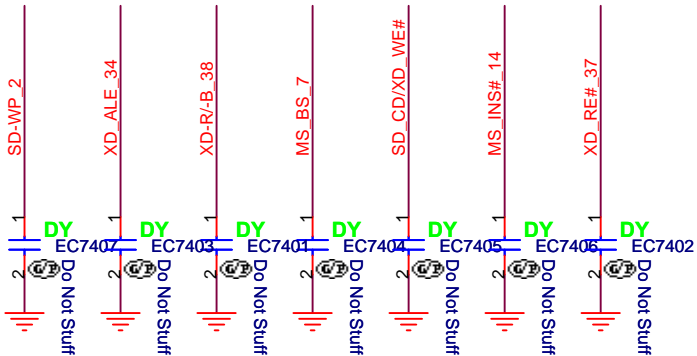
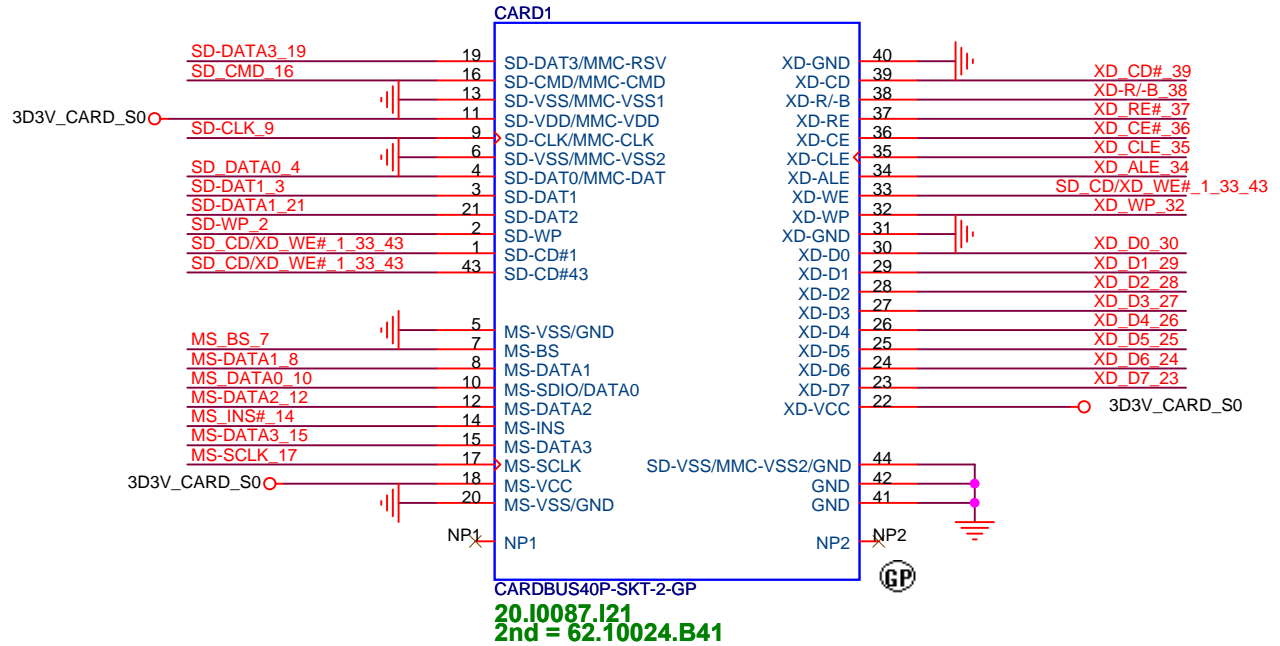


- 32 SD-DATA3_19
- 32 SD_CMD_16
- 32 SD-CLK_9
- 32 SD_DATA0_4
- 32 SD-DAT1_3
- 32 SD-DATA1_21
- 32 SD-WP_2
- 31,32 SD_CD/XD_WE#

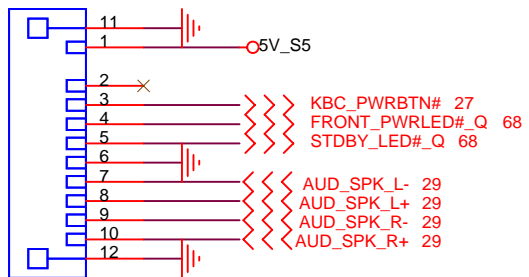
- 32 MS_BS_7
- 32 MS-DATA1_8
- 32 MS_DATA0_10
- 32 MS-DATA2_12
- 32 MS_INS#_14
- 32 MS-DATA3_15
- 32 MS-SCLK_17

- 32 XD_CD#_39
- 32 XD-R/-B_38
- 32 XD_RE#_37
- 32 XD_CE#_36
- 32 XD_CLE_35
- 32 XD_ALE_34
- 32 SD_CD/XD_WE#_1_33_43
- 32 XD_WP_32

- 32 XD_D0_30
- 32 XD_D1_29
- 32 XD_D2_28
- 32 XD_D3_27
- 32 XD_D4_26
- 32 XD_D5_25
- 32 XD_D6_24
- 32 XD_D7_23

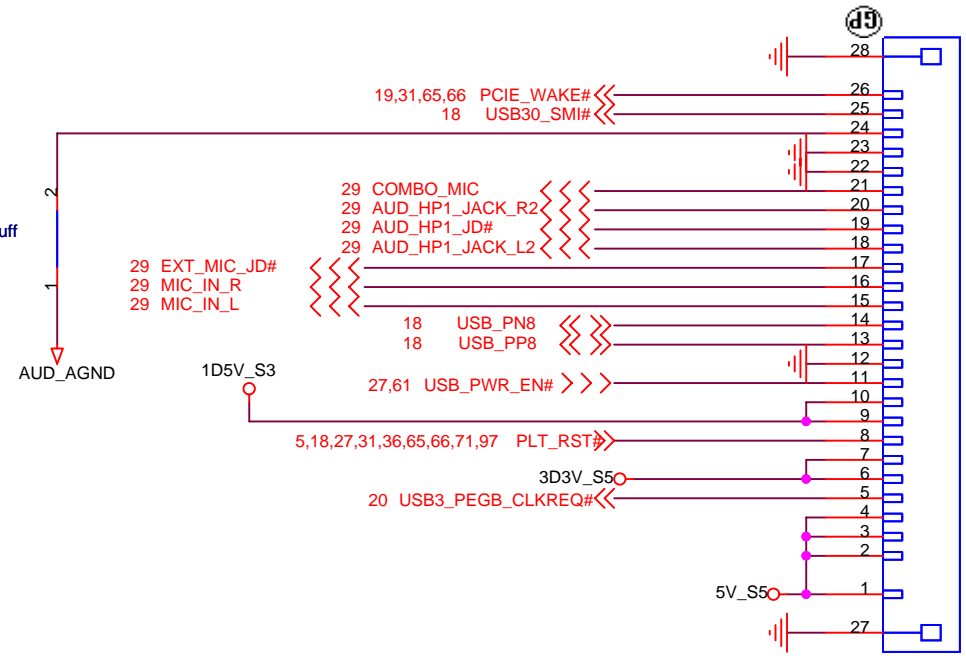


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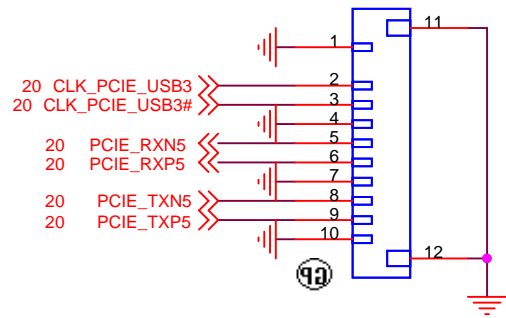
PWRCN1
 ACES-CON10-20-GP
20.K0422.010
 2nd = 20.K0382.010

R8105
D6 Not Stuff



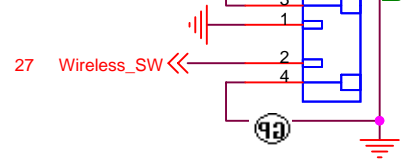
USBCN1
 ACES-CON26-11-GP
20.K0315.026
 2nd = 20.K0370.026

USBCN2
 ACES-CON10-18-GP
20.K0315.010
 2nd = 20.K0392.010



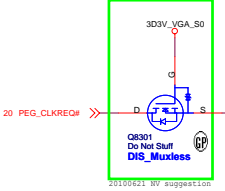
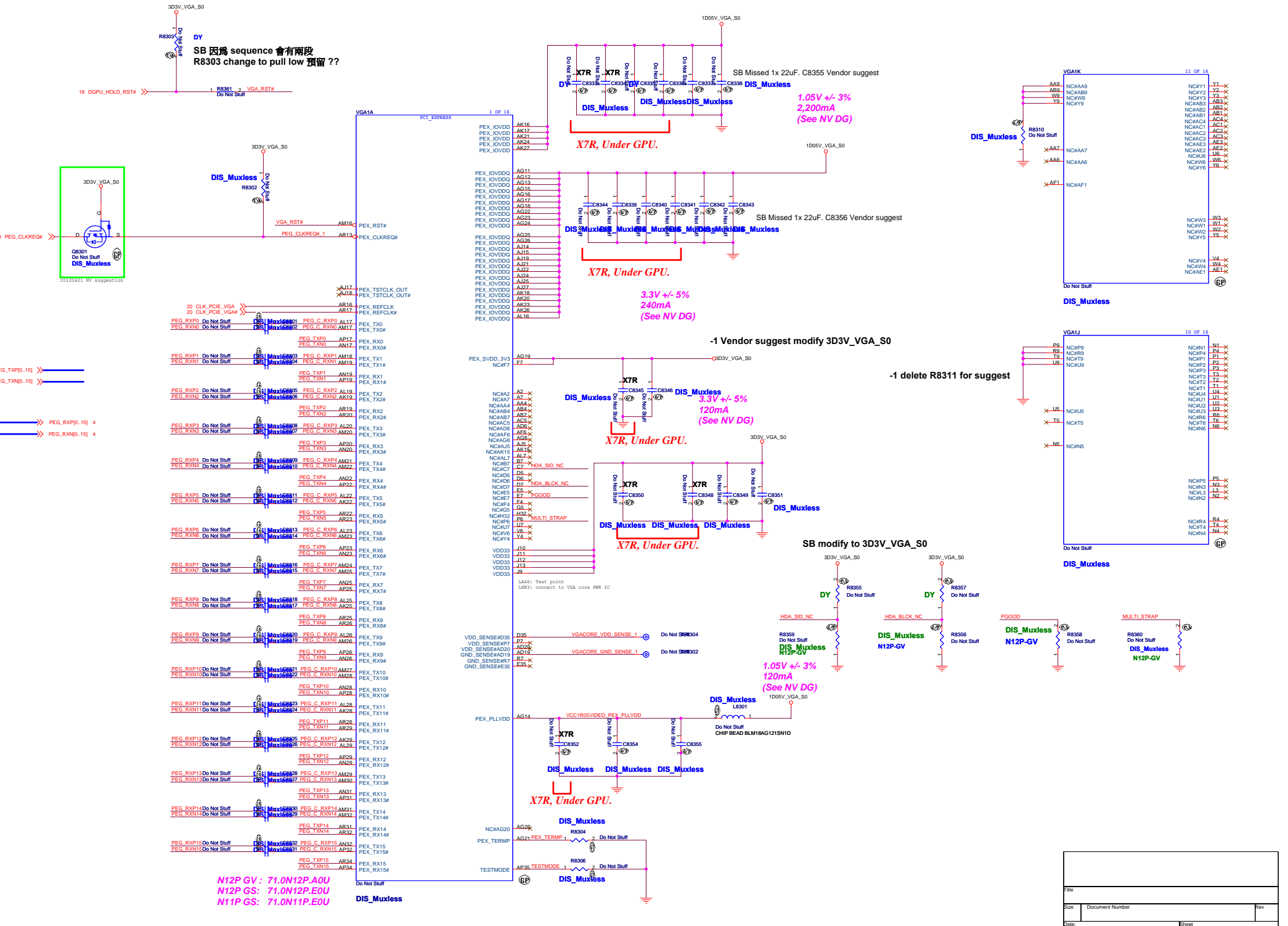
RF_CN1
 ACES-CON2-11-GP
20.F0772.002

BAE40



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SB 因為 sequence 會有兩段
R8303 change to pull low 預留??



LA44: Test point
I203: connect to VGA core PWR IC

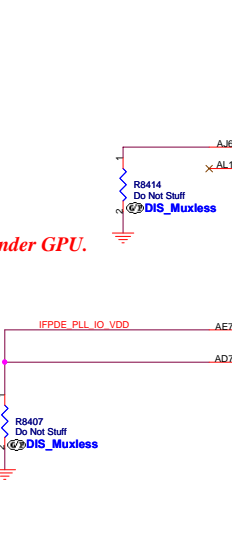
AG14: VCC1R5VIDEO_PEX_PLLVDD

LVDS Interface

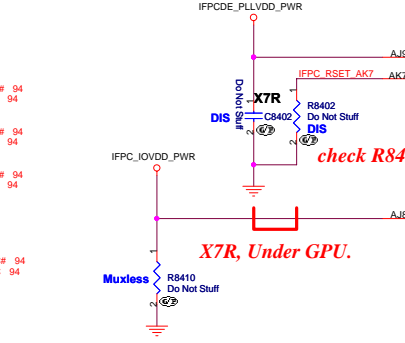
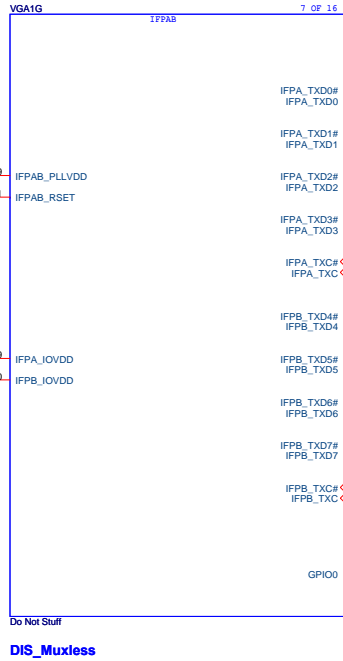
1.05V +/- 3%
220mA
(See NV DG)

3.3V +/- 5%
220mA
(See NV DG)

DG requires X7R for 1uF and 4.7uF as well.



X7R, Under GPU.



SB modify connector to IFPCDE_PLLVDD_PWR

Under GPU.

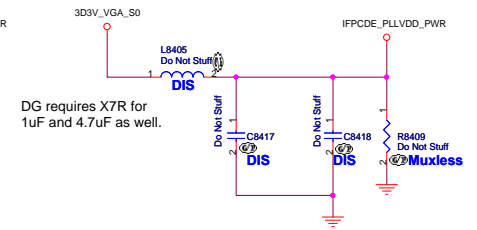
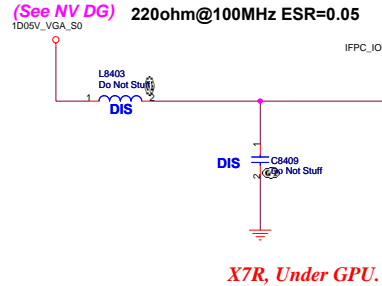
SB modify connector to IFPC_IOVDD_PWR

SA R8412, R8413 change DY
SB R8412, R8413 change delete

HDMI Interface

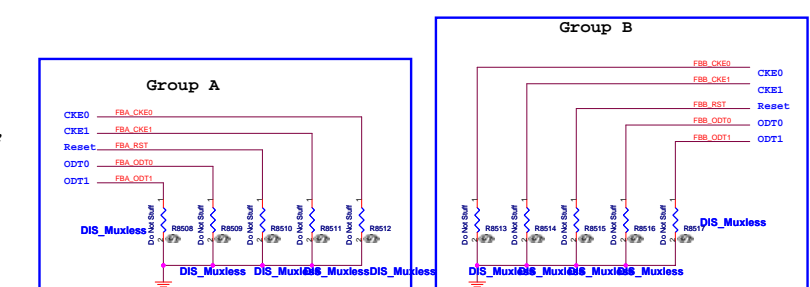
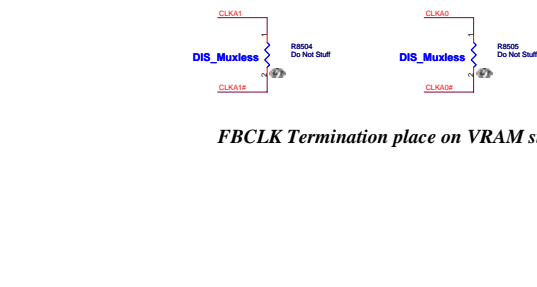
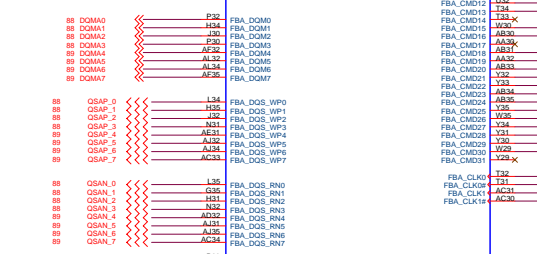
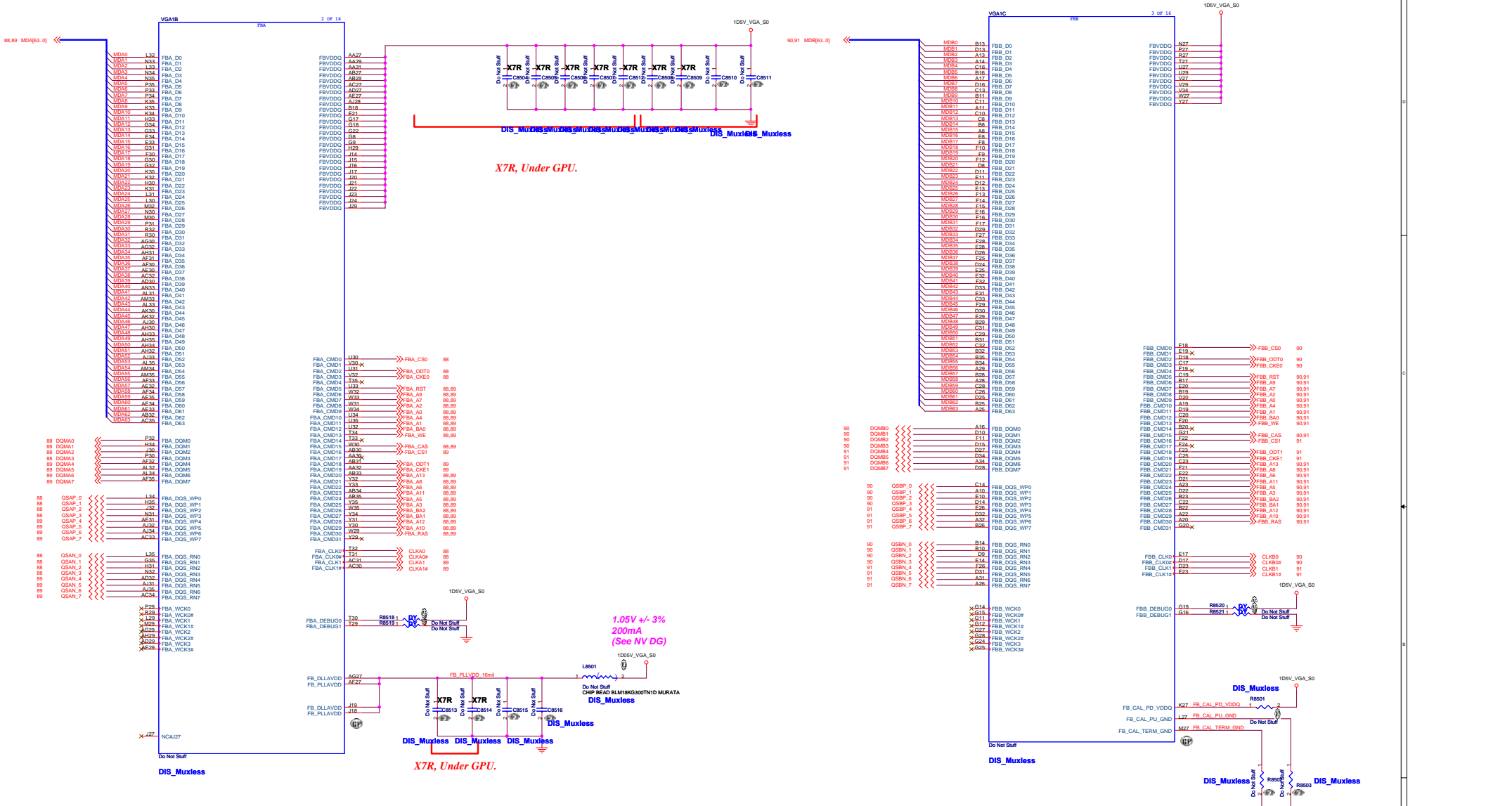
1.05V +/- 3%
285mA
(See NV DG)

3.3V +/- 5%
440mA (220mA each, max 2 links)
(See NV DG) 300ohm@100MHz ESR=0.25



DG requires X7R for 1uF and 4.7uF as well.

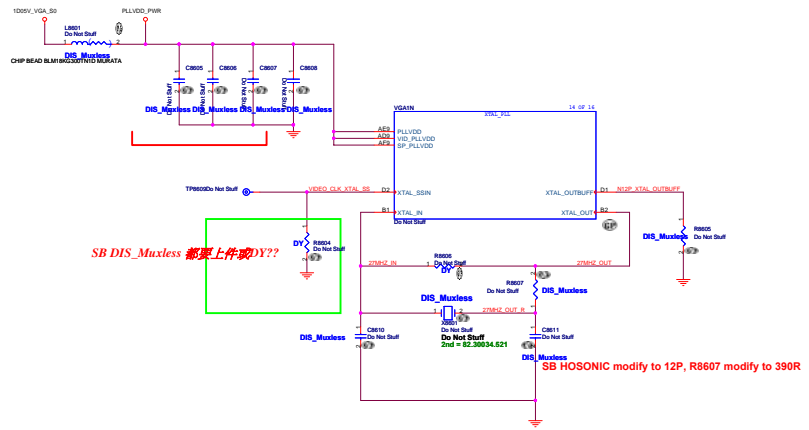
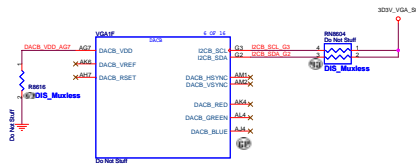
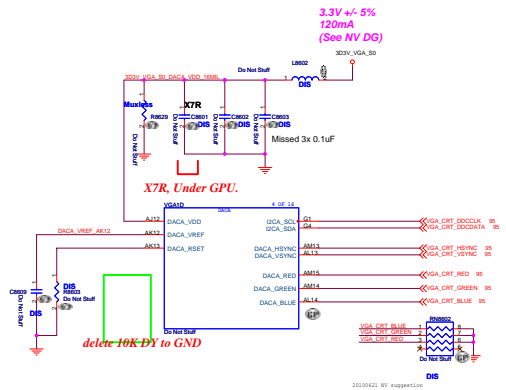
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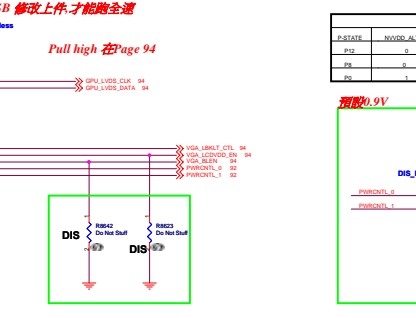
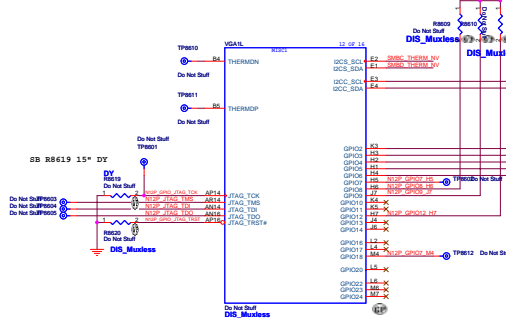
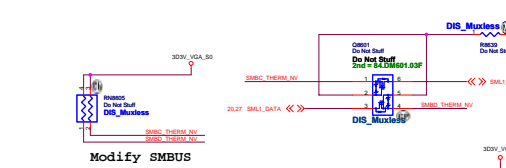
FBCLK Termination place on VRAM side

FBCLK Termination place on VRAM side

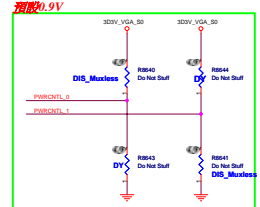
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VGA Thermal sensor P2800



SIM50-CP SUPPORT							
STATE	NVVID_ALTV	NVVID_ALTV0	N11MSEL	N11MSEP	N11MGP1	N12P-GS1	N12P-GS1_Fermi
P10	0	0	0.85V	0.85V	0.85V	0.85V	0.85V
P8	0	1	0.85V	0.85V	0.85V	0.85V	0.85V
D0	1	0	1.00V	1.00V	1.00V	0.85V	0.85V

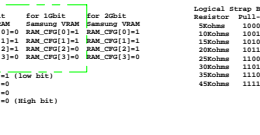
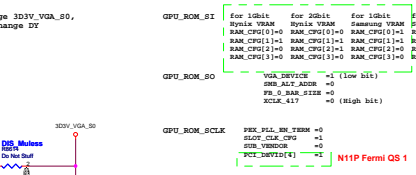
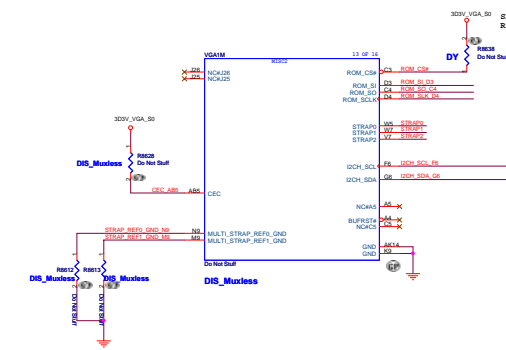


NVIDIA TABLE

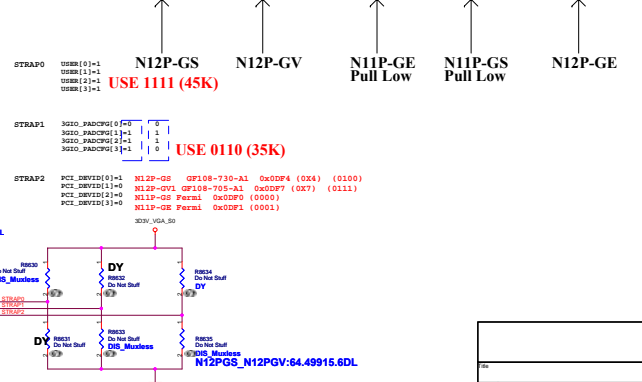
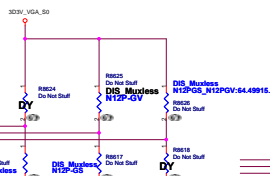
	Hynix 2G 0110 128*16*8 800MHZ	Hynix 1G 0000 64*16*8 800MHZ	Samsung 1G 0011 64*16*8 800MHZ	Samsung 512 64*16*4 800MHZ	Samsung 2G 0111 128*16*8 800MHZ
RO M_SIPD R8627	34.8Kohm 64.34825.6DL	5Kohm 64.49915.6DL	20Kohm 64.20025.6DL	20Kohm 64.20025.6DL	45Kohm 64.45325.6DL

TABLE -1 modify N12P GV setting

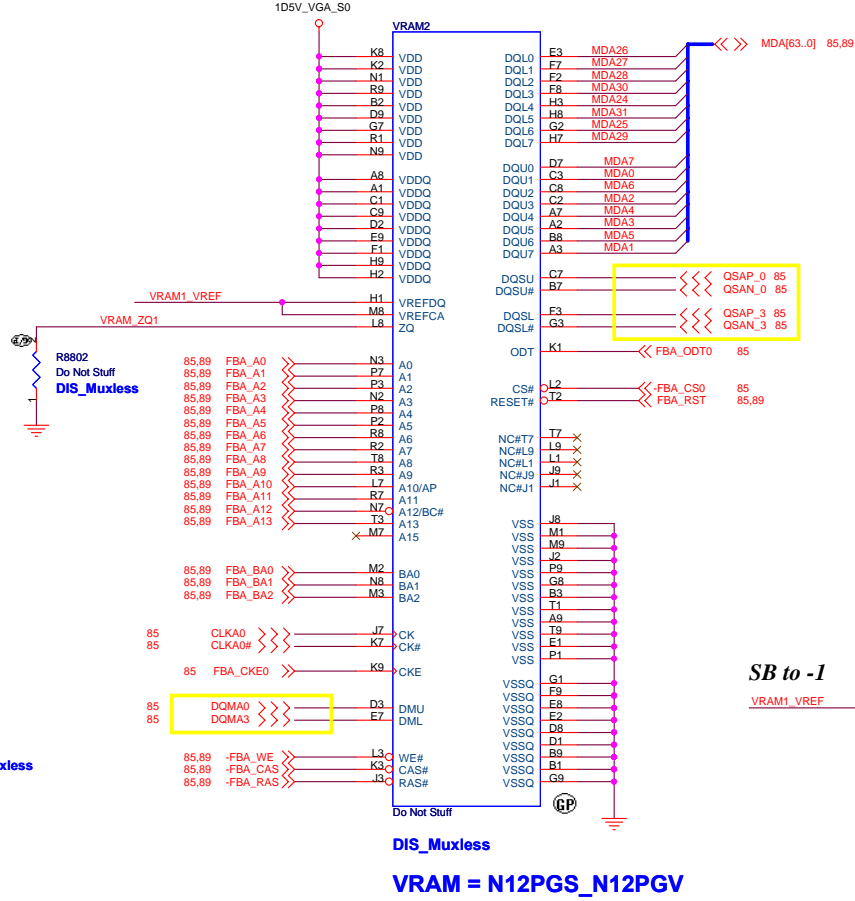
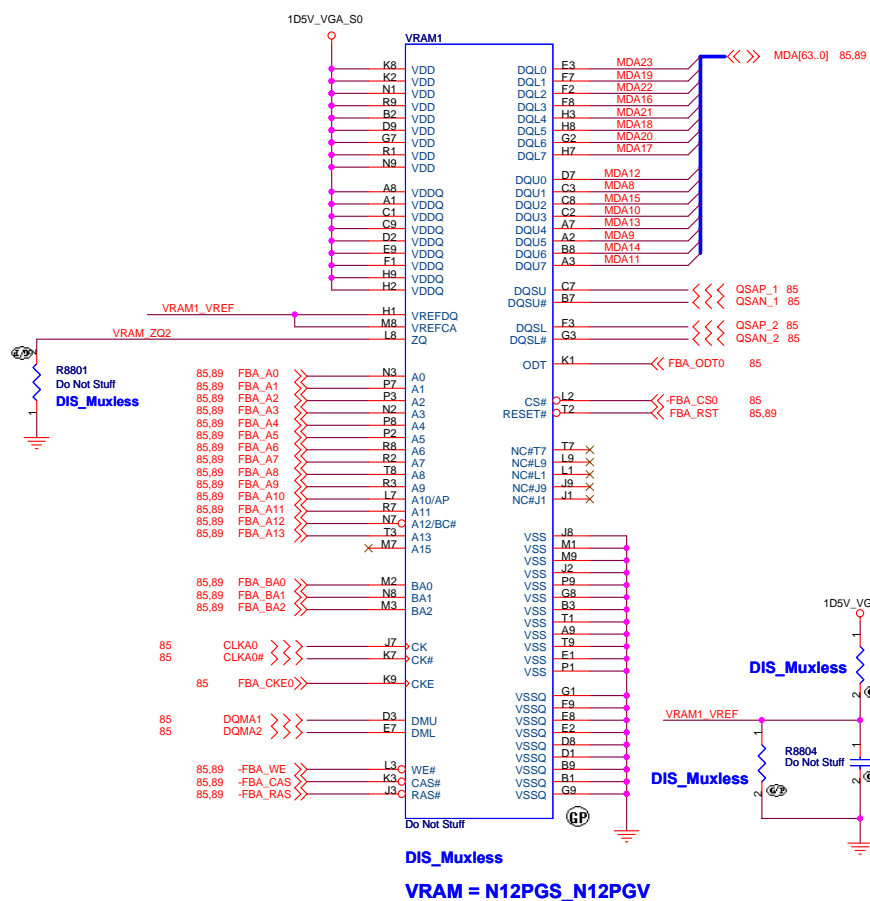
NVIDIA	71.0N12P.E0U	71.0N12P.A0U			
	N12P-GS DEV ID: 0x0DF4	N12P-GV DEV ID: 0x1050	N11P-GE Fermi DEV ID: 0x0DF1 (0001)	N11P-GS Fermi DEV ID: 0x0DF0 (0000)	N12P-GE DEV ID: 0x0DF5 (0101)
STRAP2 PU	25Kohm 64.24925.6DL	45Kohm ES 45K QS 5K 64.49915.6DL	10Kohm 63.10334.1DL	5Kohm 64.49915.6DL	30Kohm 64.30025.6DL



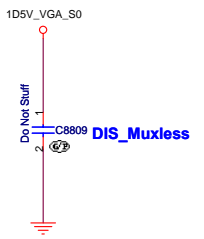
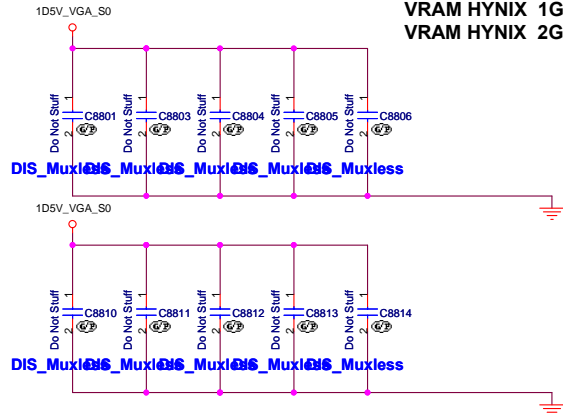
GPU_ROM_SI	For 1Gbit	for 2Gbit	for 1Gbit	for 2Gbit	Logical Strap Bit Mapping
GPU_ROM_SI	Synix VRAM	Synix VRAM	Samsung VRAM	Samsung VRAM	15kohm 1000 0000
GPU_ROM_BO	RAM_CPG[0]=0	RAM_CPG[0]=0	RAM_CPG[0]=1	RAM_CPG[0]=1	15kohm 1001 0000
	RAM_CPG[1]=0	RAM_CPG[1]=1	RAM_CPG[1]=1	RAM_CPG[1]=1	15kohm 1010 0010
	RAM_CPG[2]=0	RAM_CPG[2]=1	RAM_CPG[2]=1	RAM_CPG[2]=1	20kohm 1101 0010
	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	25kohm 1100 0100
	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	30kohm 1101 0100
	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	35kohm 1110 0110
	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	RAM_CPG[3]=0	45kohm 1111 0111



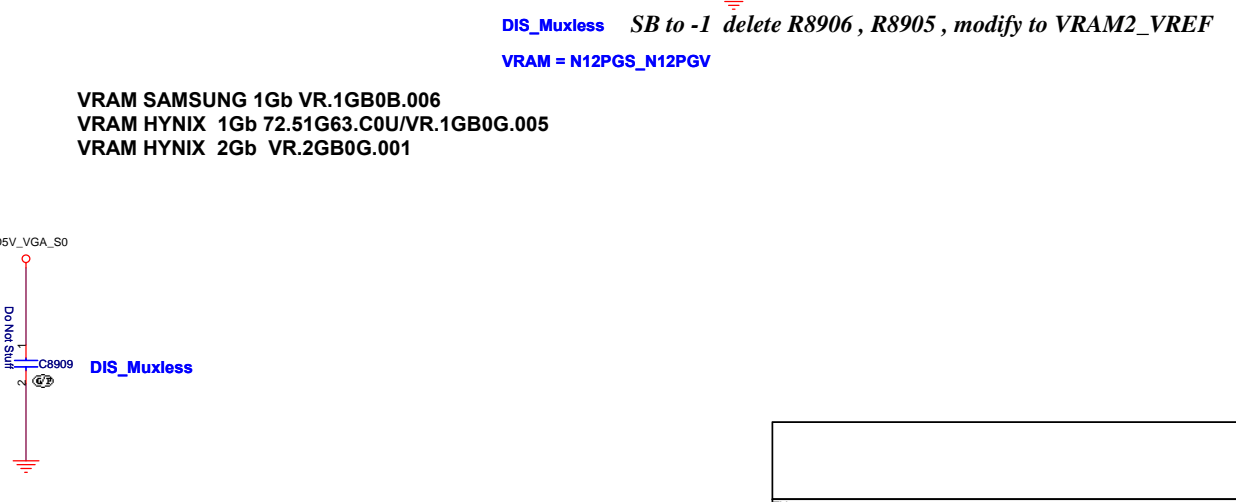
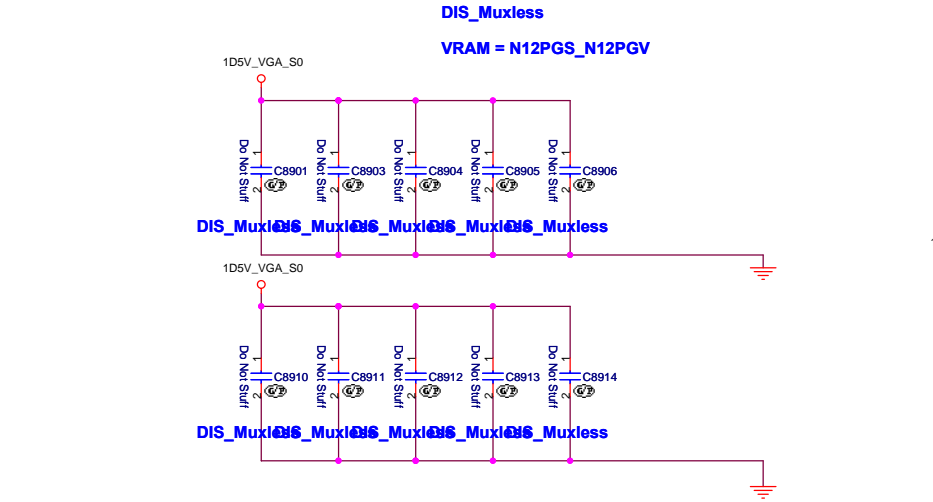
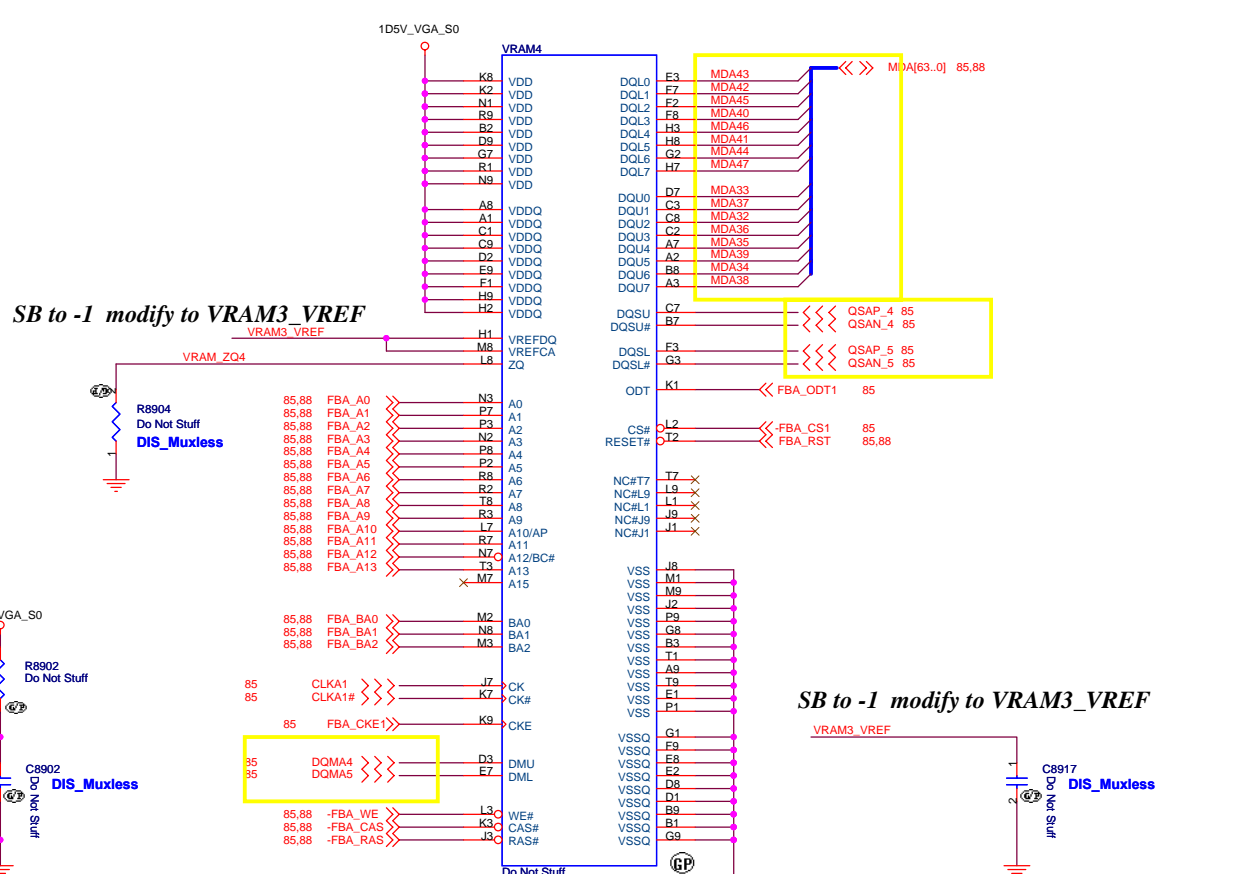
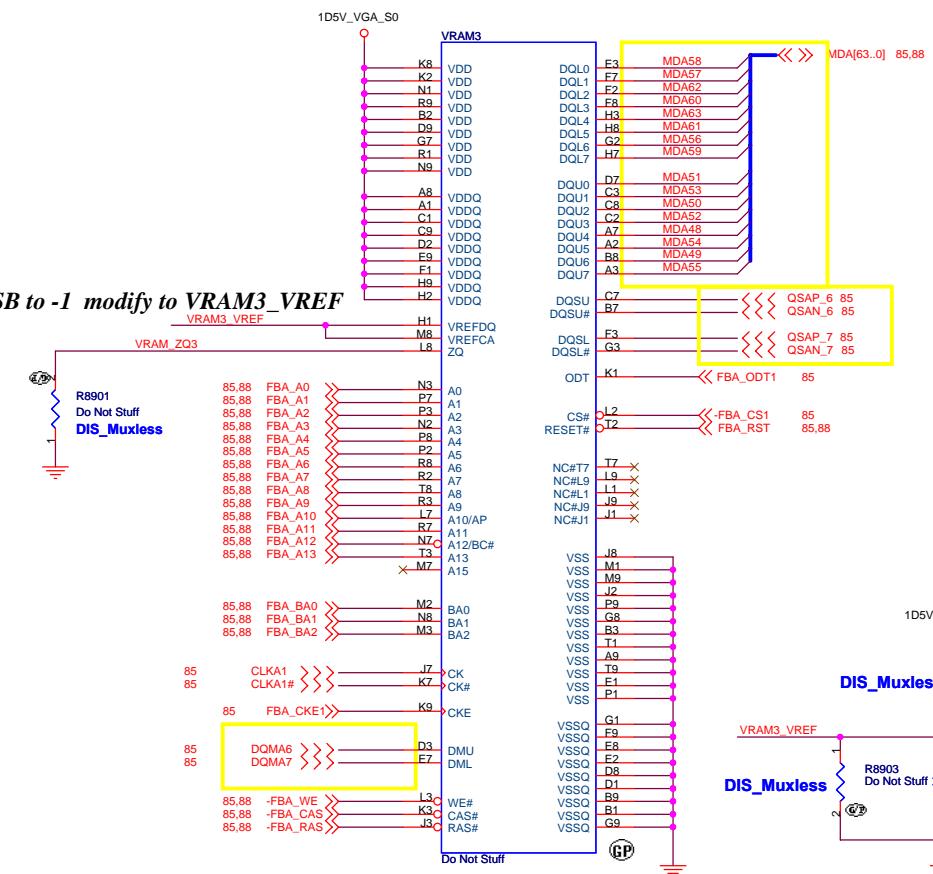
Hy2G_64.34825.6DL, Hy1G_64.15025.6DL, Sam1G512M_64.20025.6DL, Sam2G_64.45325.6DL



VRAM SAMSUNG 1Gb VR.1GB0B.006
 VRAM HYNIX 1Gb 72.51G63.C0U/VR.1GB0G.005
 VRAM HYNIX 2Gb VR.2GB0G.001

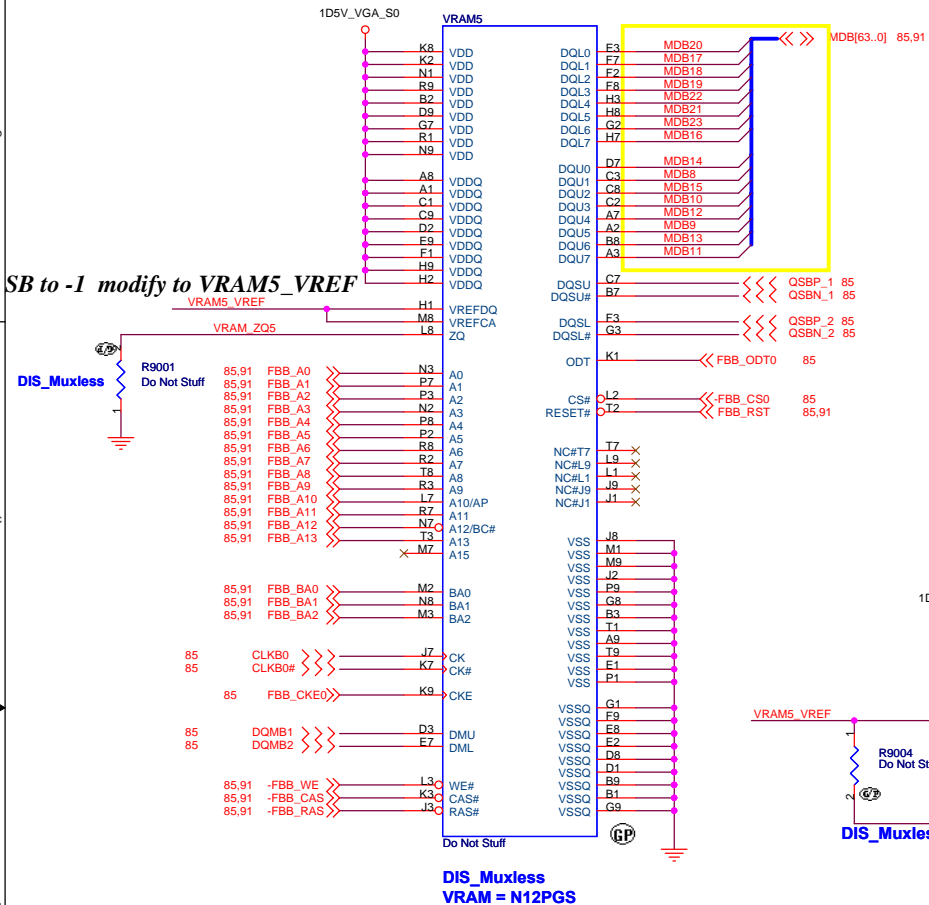


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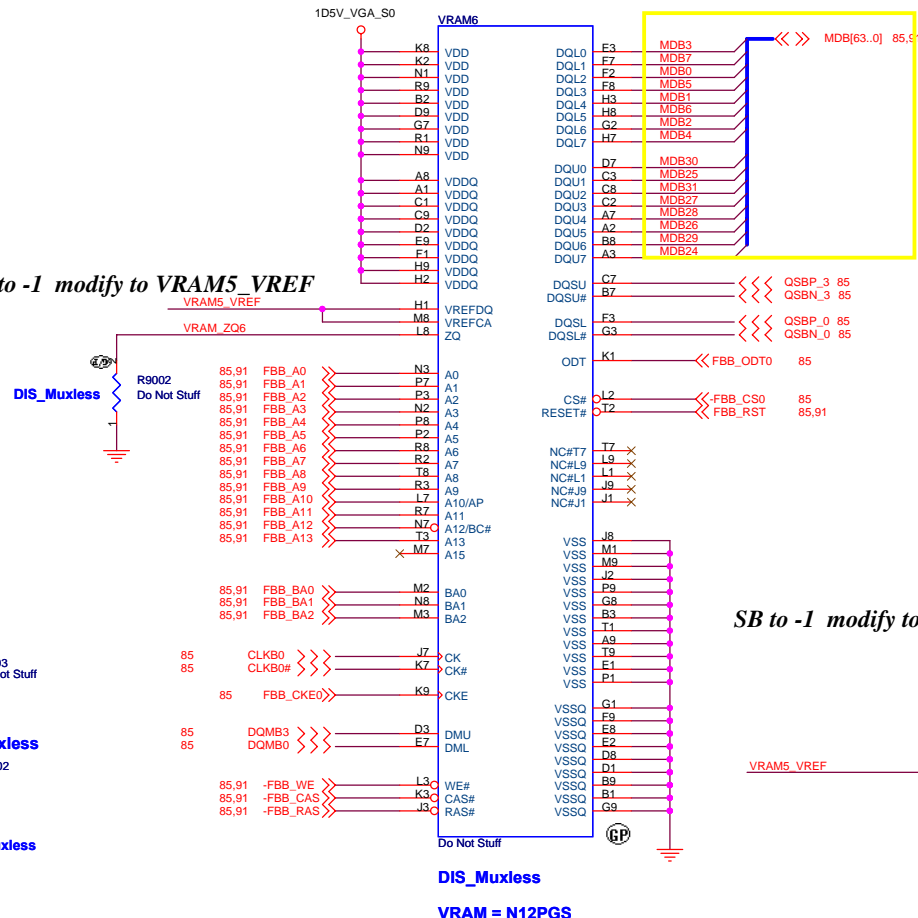


VRAM SAMSUNG 1Gb VR.1GB0B.006
 VRAM HYNIX 1Gb 72.51G63.C0U/VR.1GB0G.005
 VRAM HYNIX 2Gb VR.2GB0G.001

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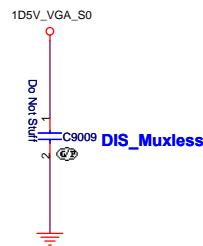
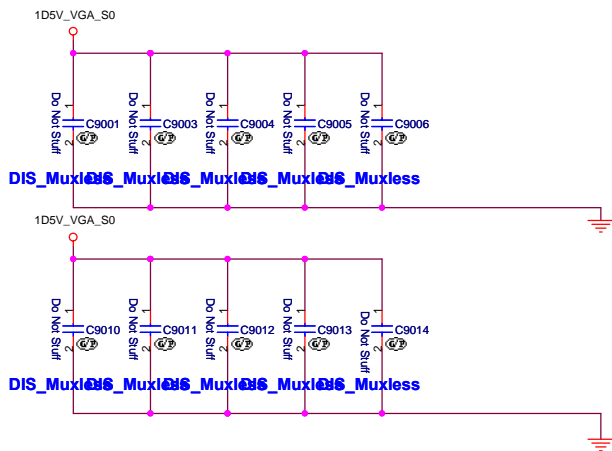


SB to -1 modify to VRAM5_VREF

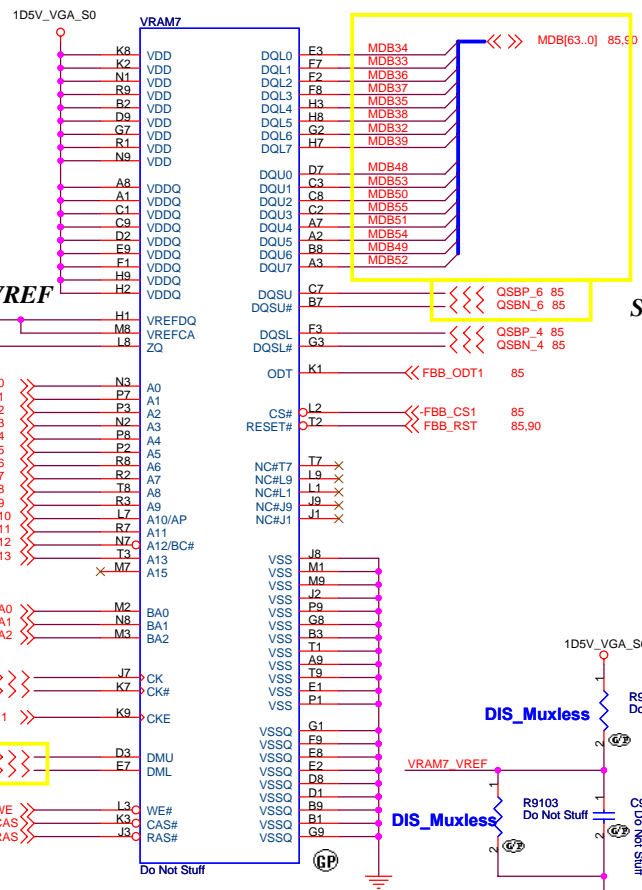


SB to -1 modify to VRAM5_VREF

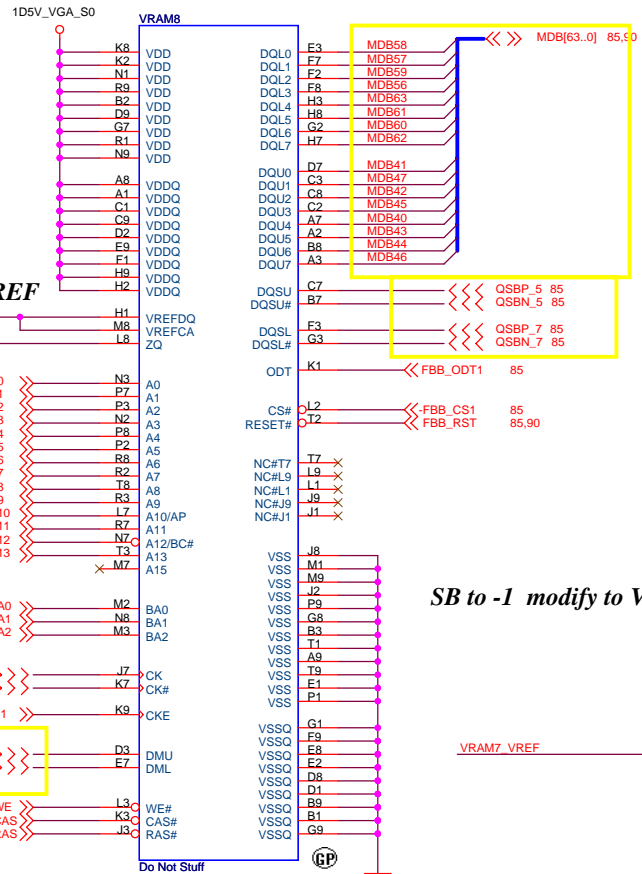
VRAM SAMSUNG 1Gb VR.1GB0B.006
VRAM HYNIX 1Gb 72.51G63.C0U/VR.1GB0G.005
VRAM HYNIX 2Gb VR.2GB0G.001



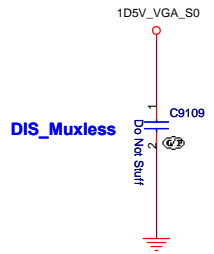
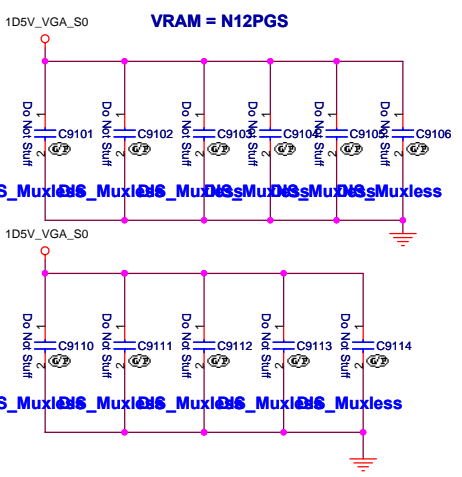
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SB to -1 modify to VRAM7_VREF



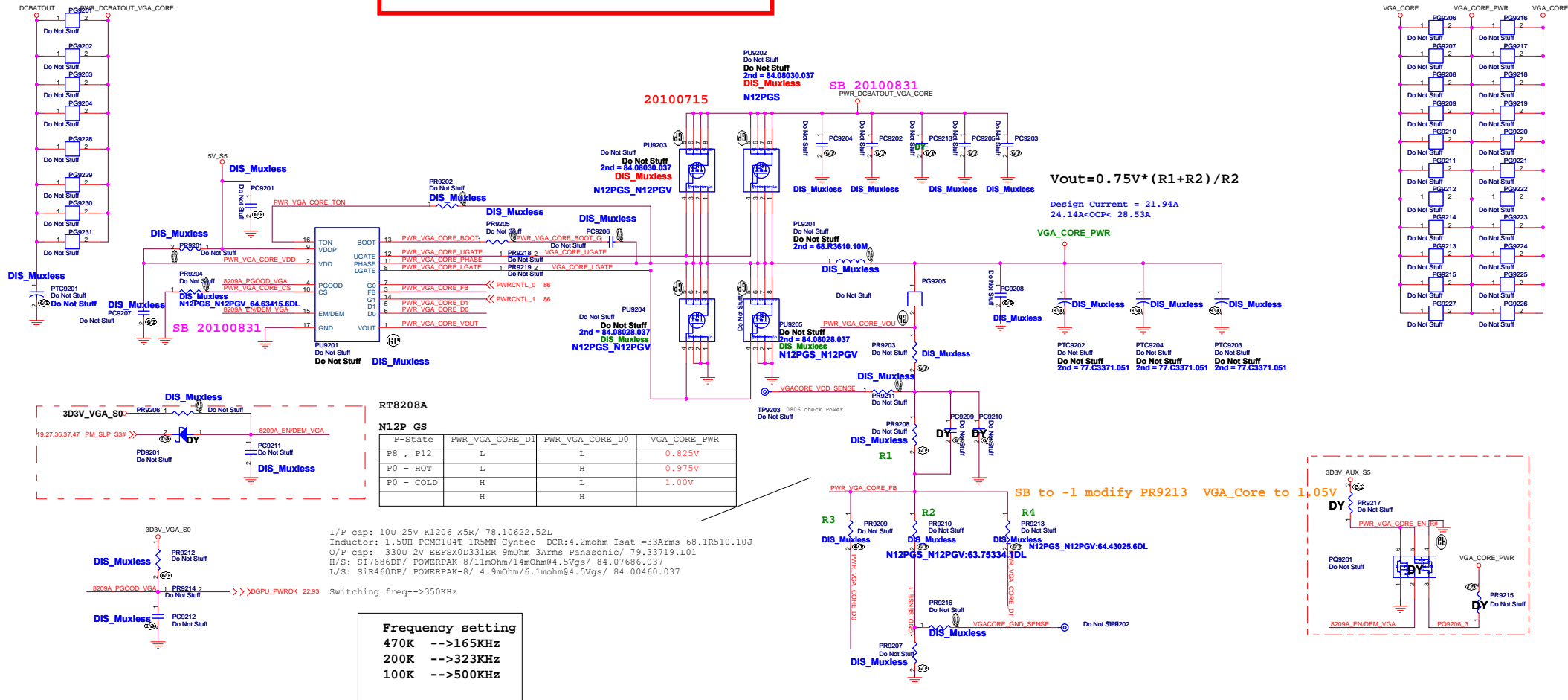
SB to -1 modify to VRAM7_VREF



DIS_Muxless
 VRAM = N12PGS
 VRAM SAMSUNG 1Gb VR.1GB0B.006
 VRAM HYNIX 1Gb 72.51G63.C0U/VR.1GB0G.005
 VRAM HYNIX 2Gb VR.2GB0G.001

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SSID = PWR.Plane.Regulator_GFX



$V_{out} = 0.75V * (R1 + R2) / R2$

Design Current = 21.94A
24.14A < OCP < 28.53A

VGA_CORE_PWR

RT8208A

P-State	PWR_VGA_CORE_D1	PWR_VGA_CORE_D0	VGA_CORE_PWR
P8 , P12	L	L	0.825V
P0 - HOT	L	H	0.975V
P0 - COLD	H	L	1.00V
	H	H	

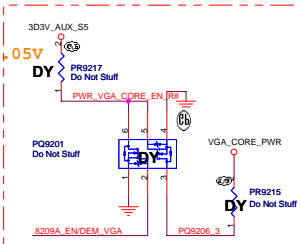
I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
 Inductor: 1.5UH PCMC104T-1R5MN Cyntec DCR:4.2mohm Isat =33Arms 68.1R510.10J
 O/P cap: 330U 2V EEFSX0D331ER 9mOhm 3Arms Panasonic/ 79.33719.L01
 H/S: SI7686DP/ POWERPAK-8/11mOhm/14mOhm@4.5Vgs/ 84.07686.037
 L/S: S1R460DP/ POWERPAK-8/ 4.9mOhm/6.1mohm@4.5Vgs/ 84.00460.037
 Switching freq-->350KHz

Frequency setting
 470K -->165KHz
 200K -->323KHz
 100K -->500KHz

N12P GV

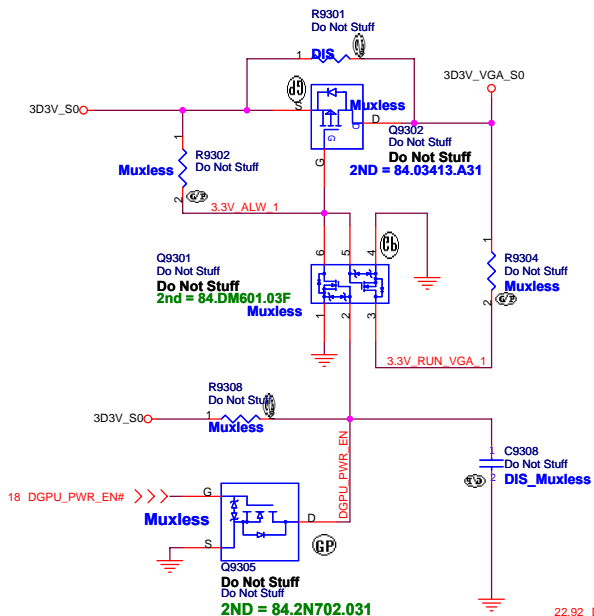
P-State	PWR_VGA_CORE_D1	PWR_VGA_CORE_D0	VGA_CORE_PWR
P8 , P12	L	L	0.85V
P0 - HOT	L	L	1.00V
P0 - COLD	H	L	1.025V
	H	H	

$V_{out} = 0.75V * (R1 + R2) / R2$

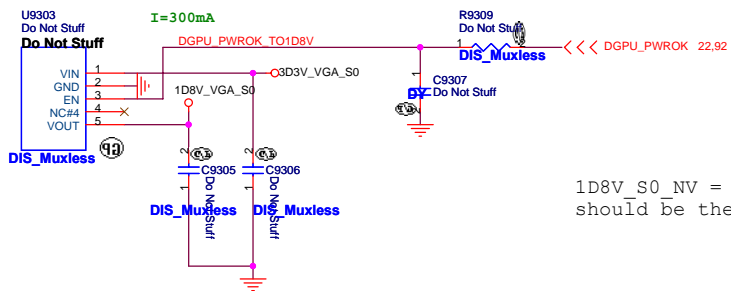


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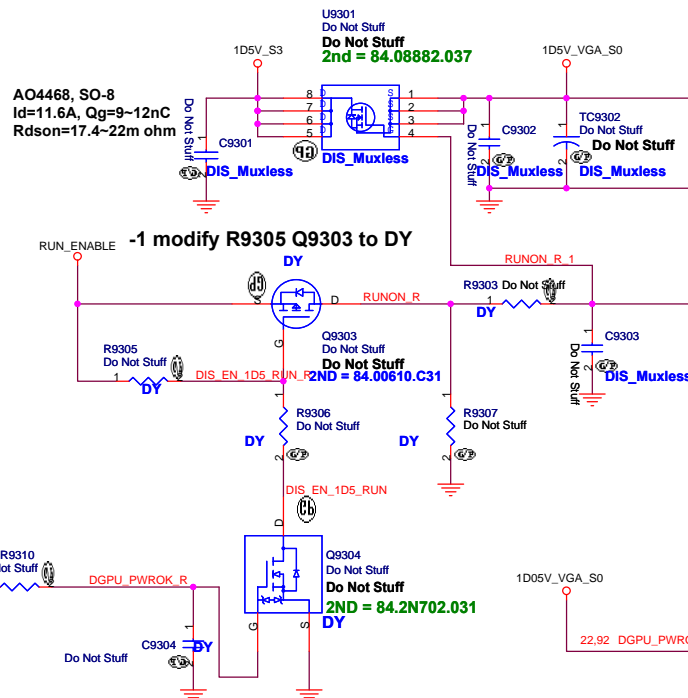
+3VS to 3.3V_DELAY Transfer



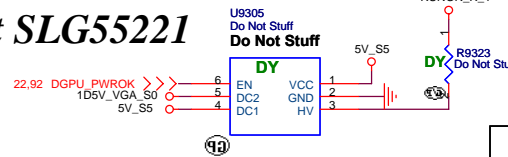
+3VS to 1.8V Transfer



1D5V_VGA_S0

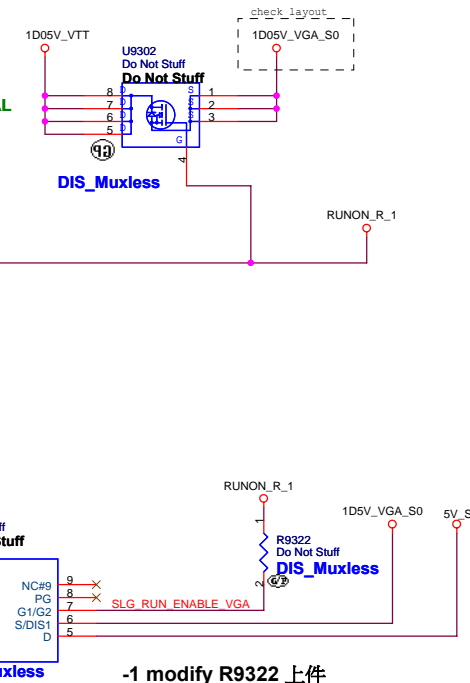


-1 co-layout SLG55221

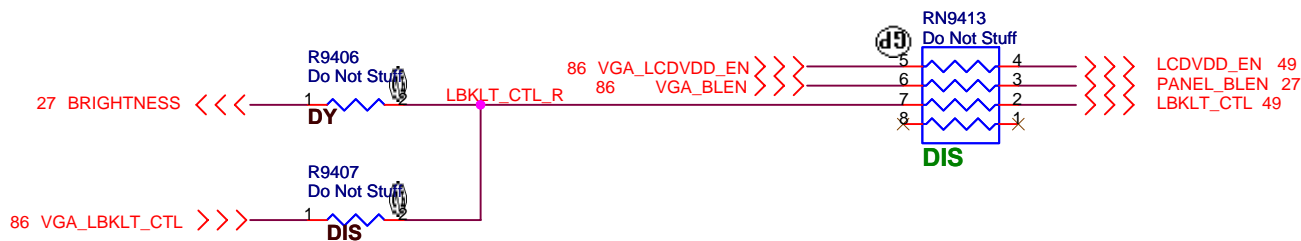
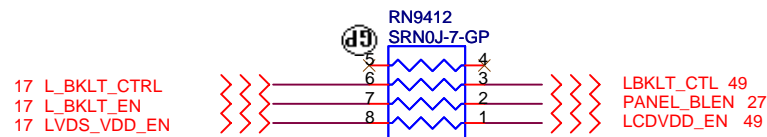
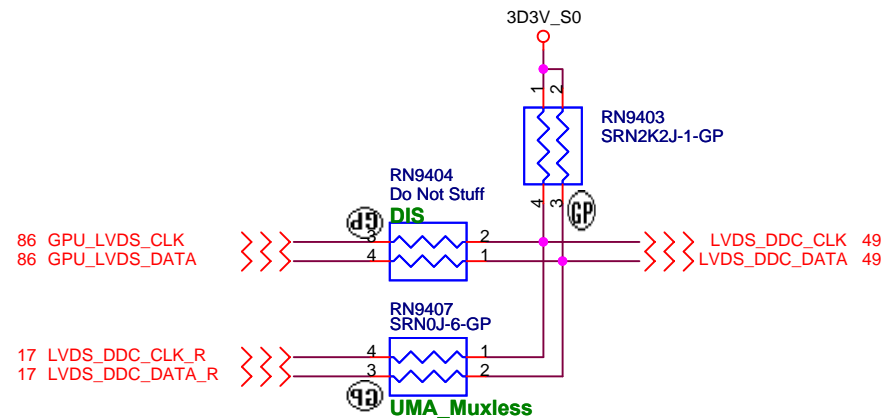
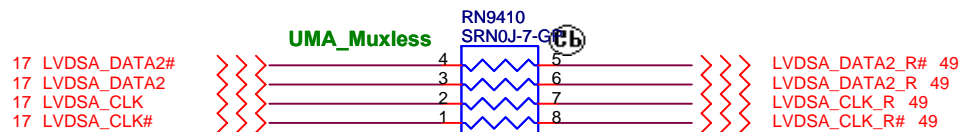
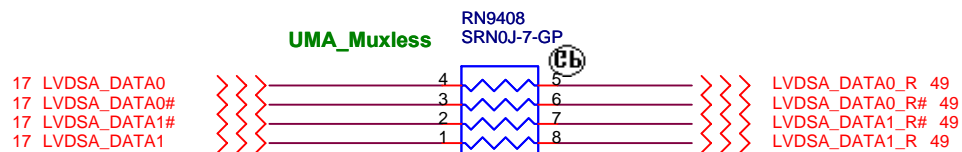
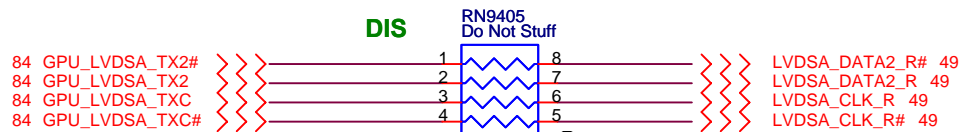
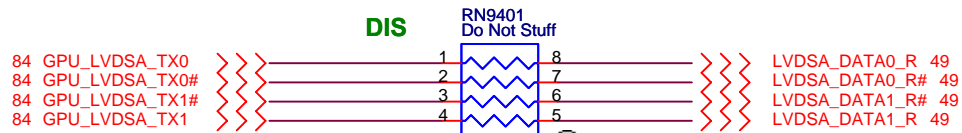


SB modify to 84.03006.A37

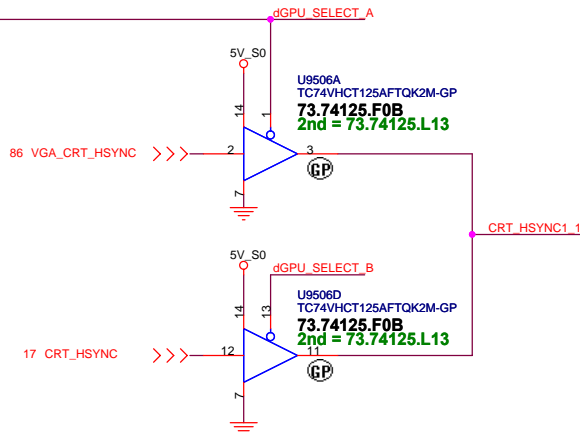
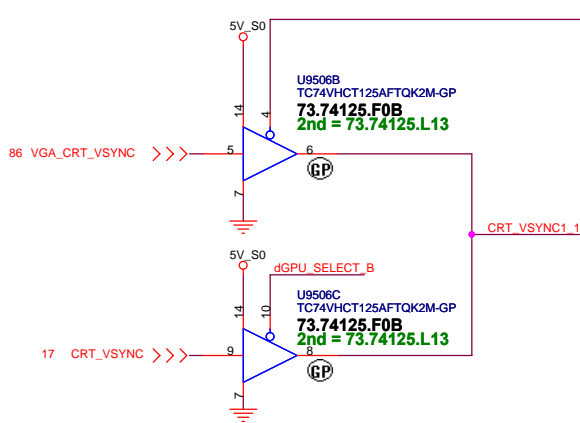
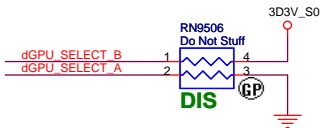
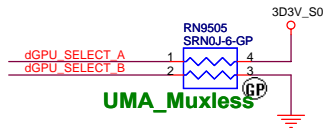
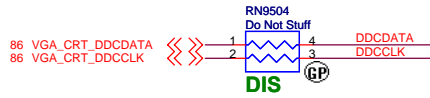
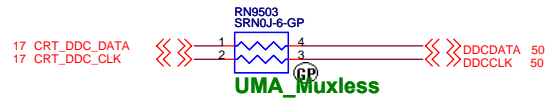
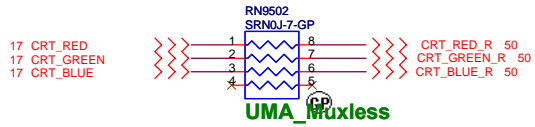
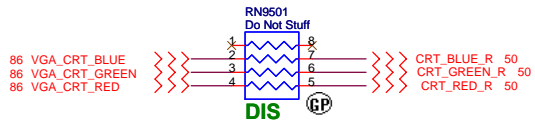
1.05V to 1.05V_VGA_S0 Transfer



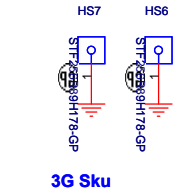
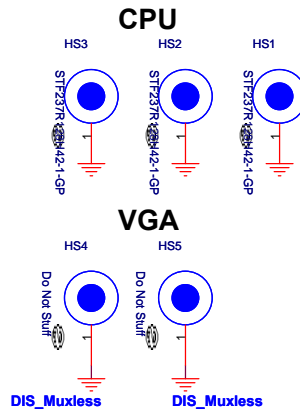
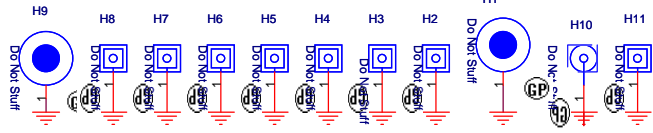
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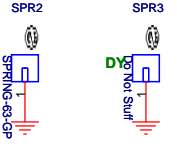
Check test point



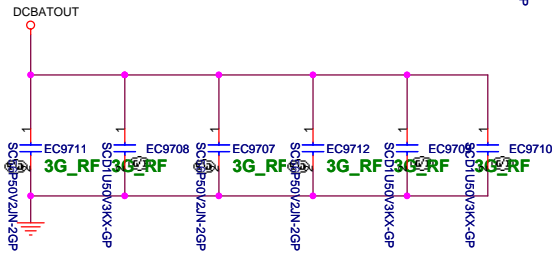
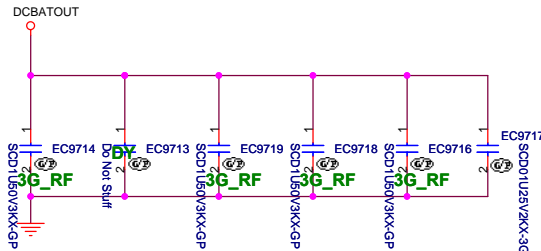
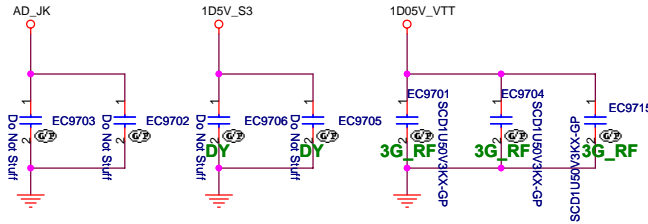
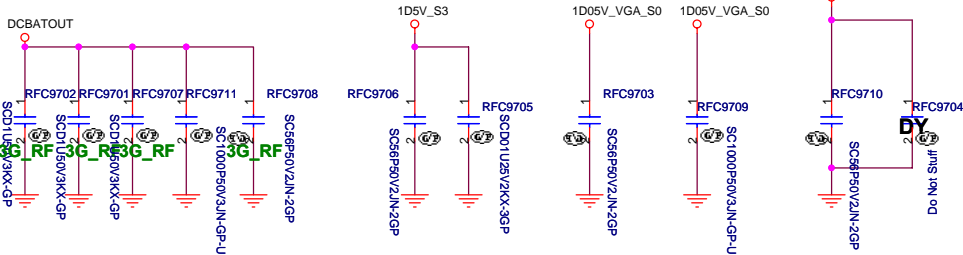
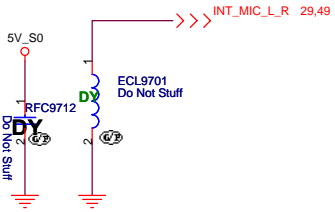
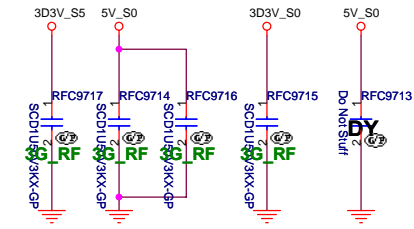
Test Point放在Dimm Door打開可量測處

SB to -1 BOM add SPR2

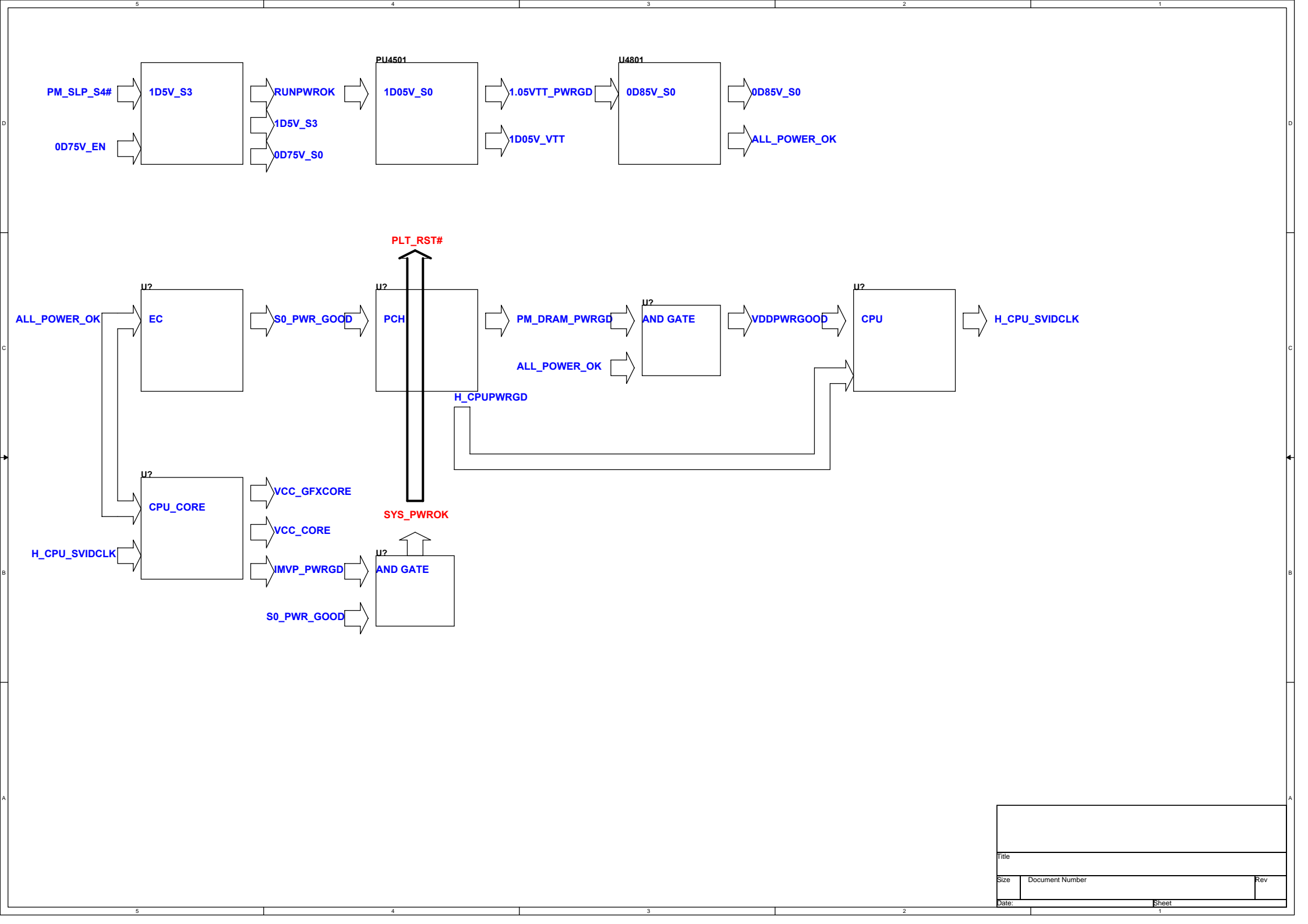
-2 delete SPR5



Change:34.40V16.001



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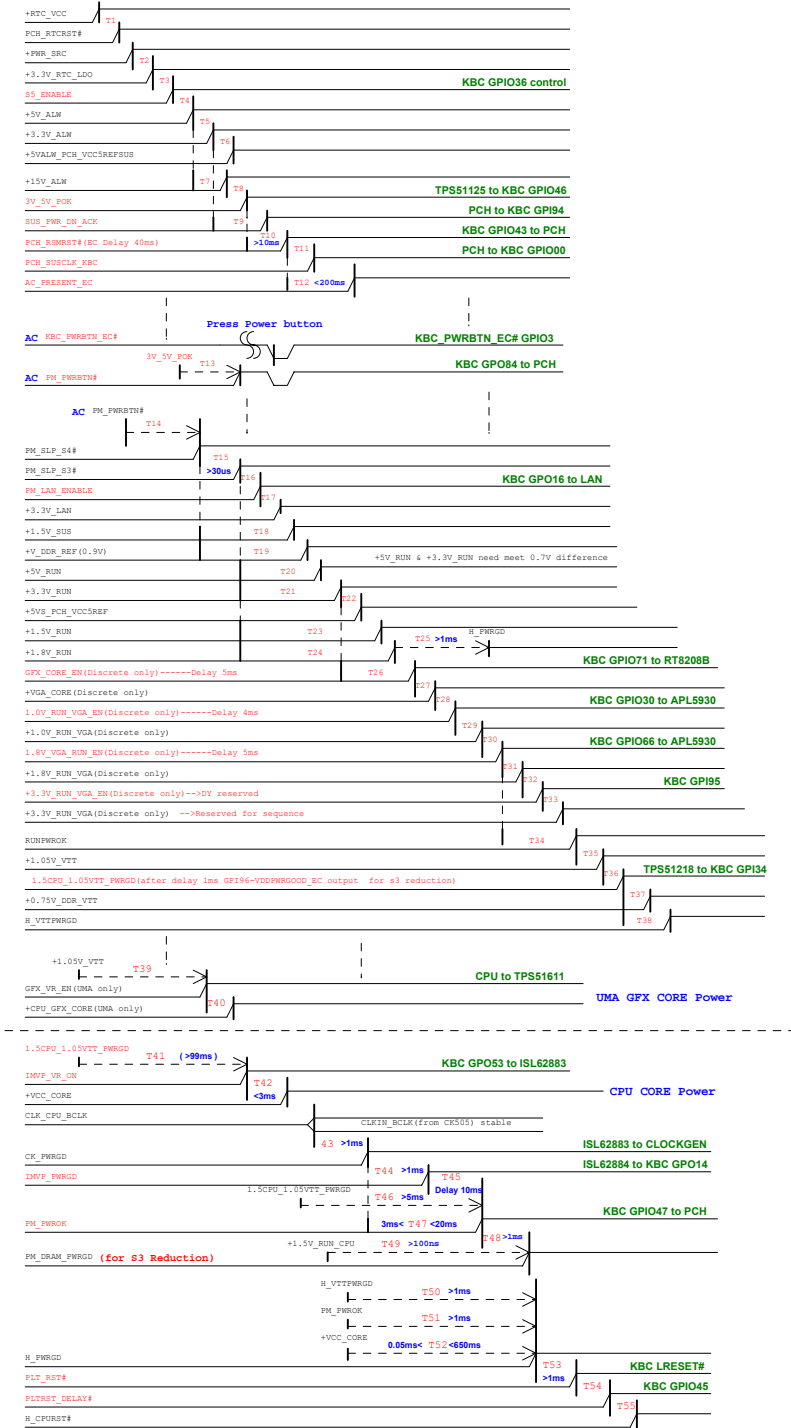


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Intel-Power Up Sequence

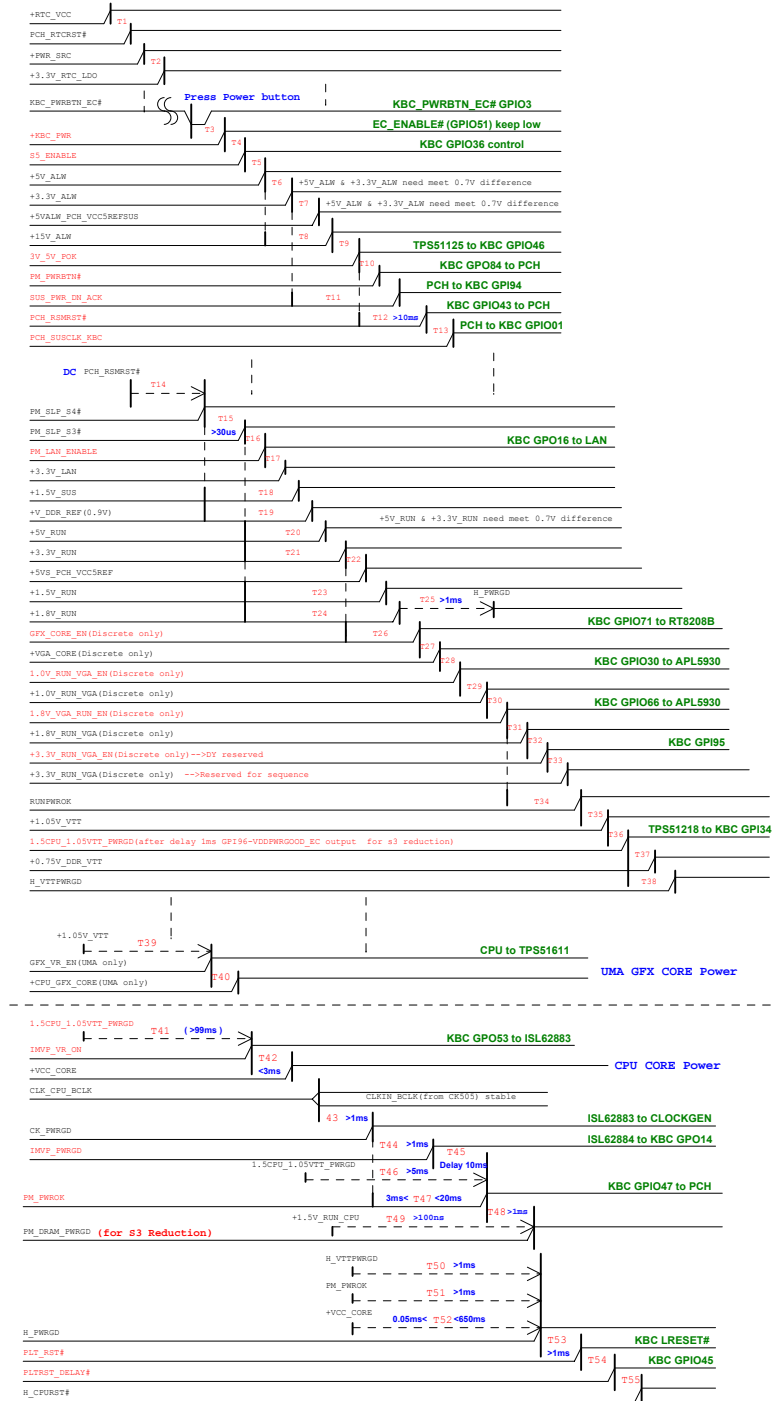
(AC mode)

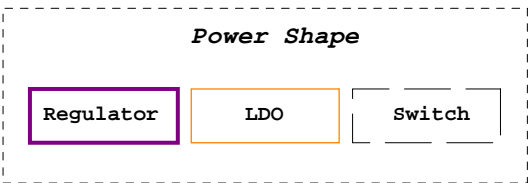
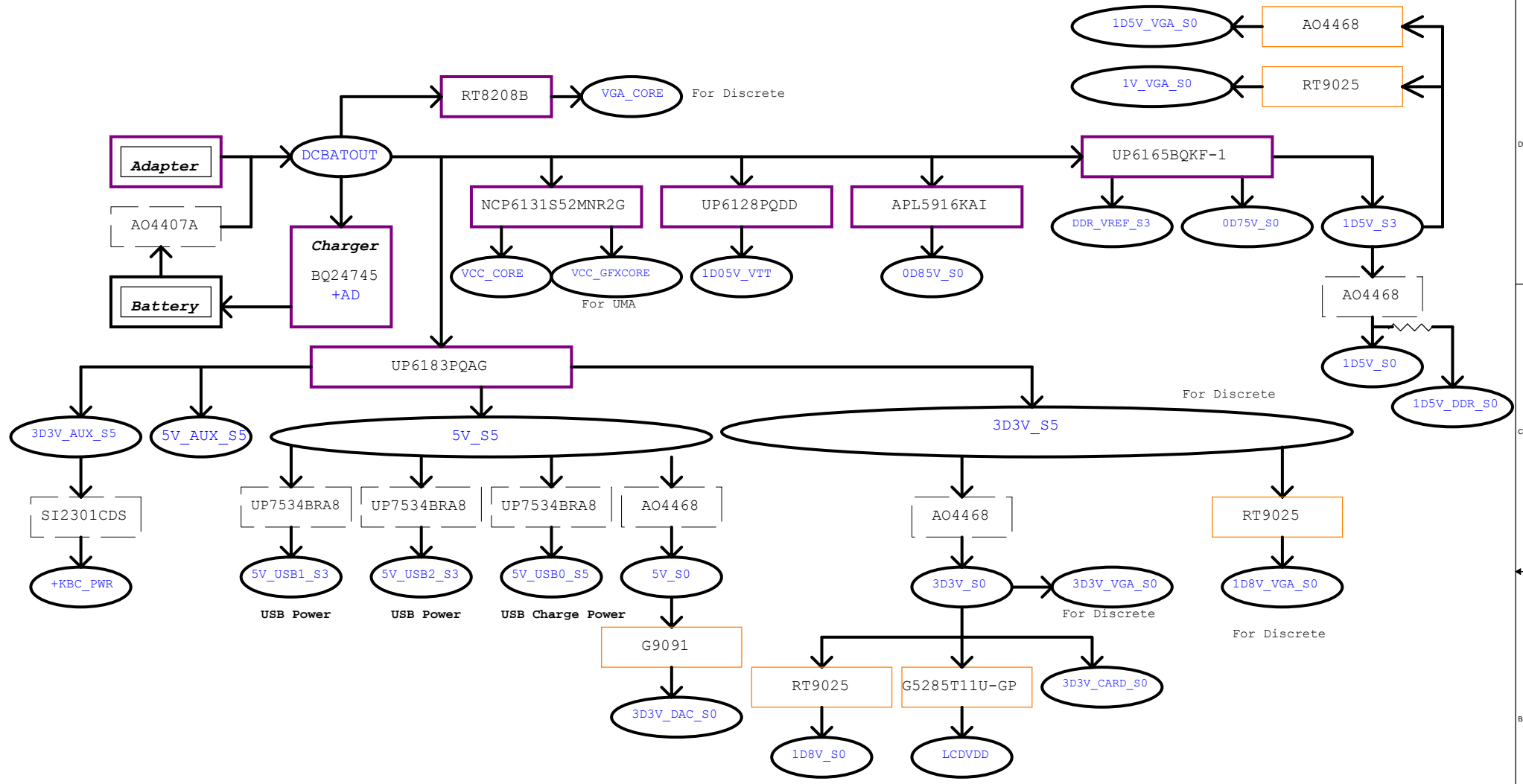
red word: KBC GPIO



(DC mode)

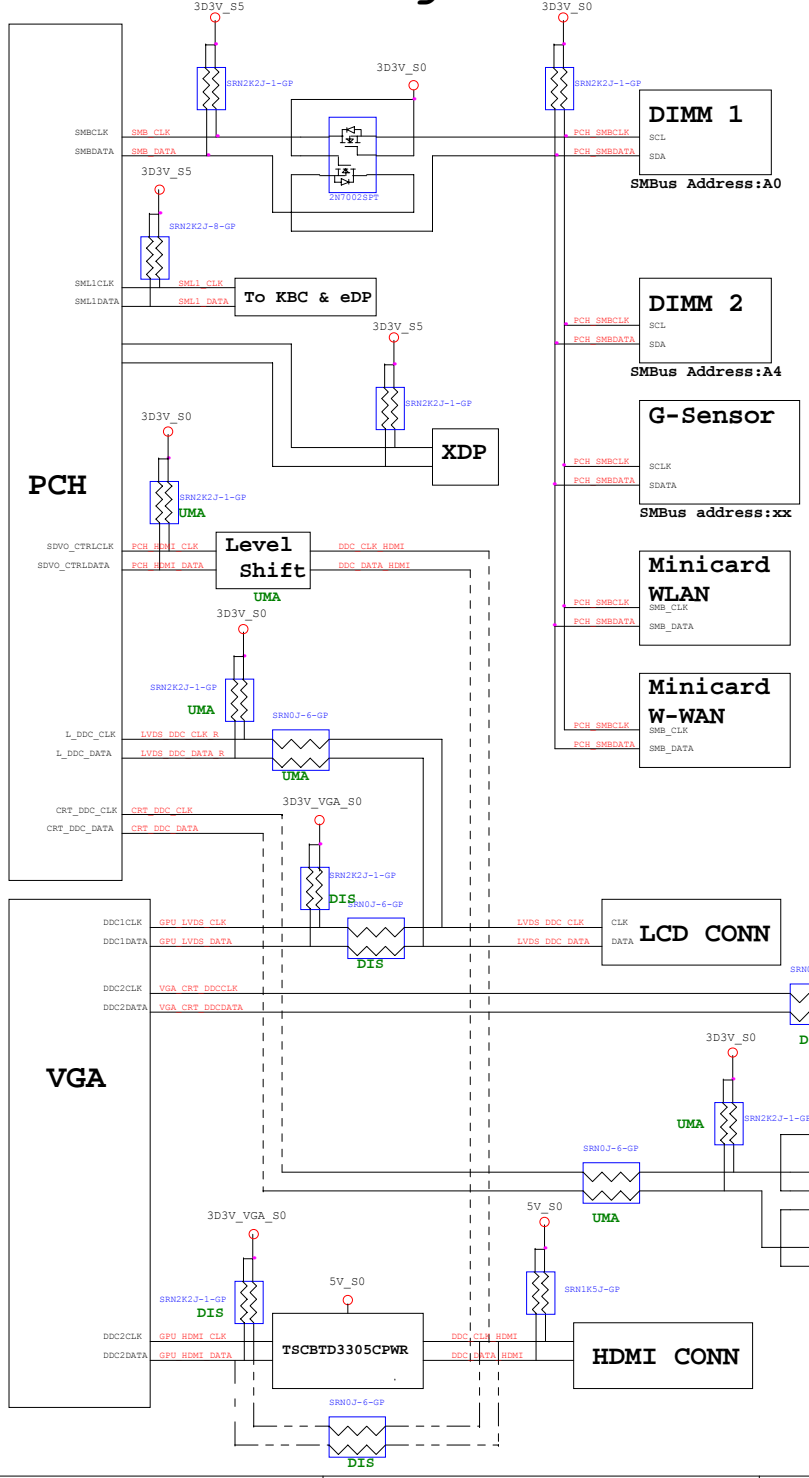
red word: KBC GPIO



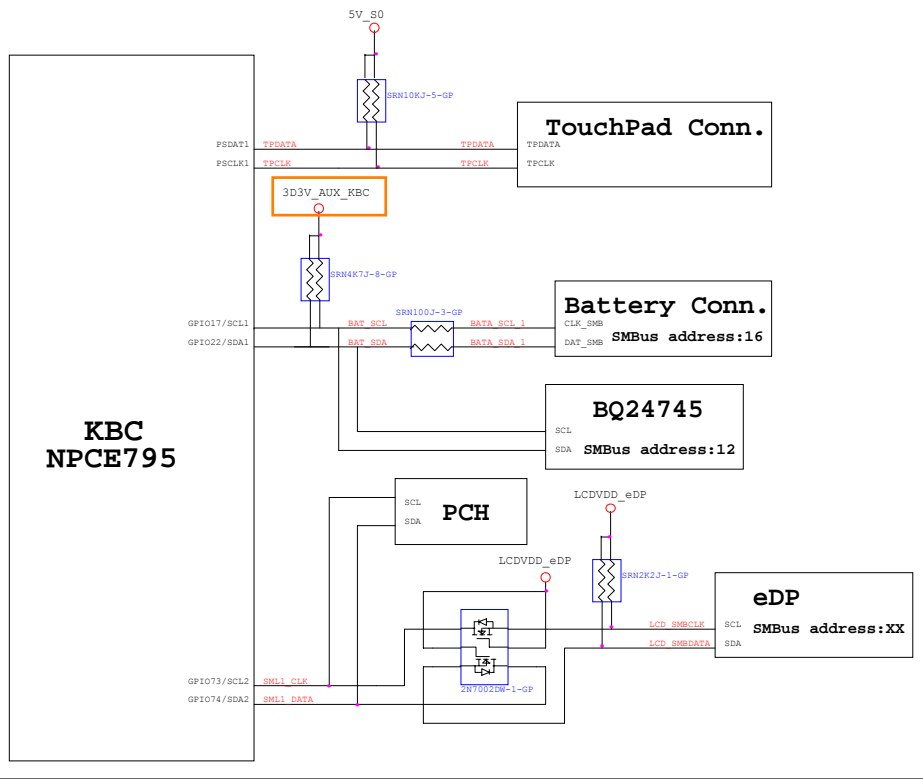


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PCH SMBus Block Diagram



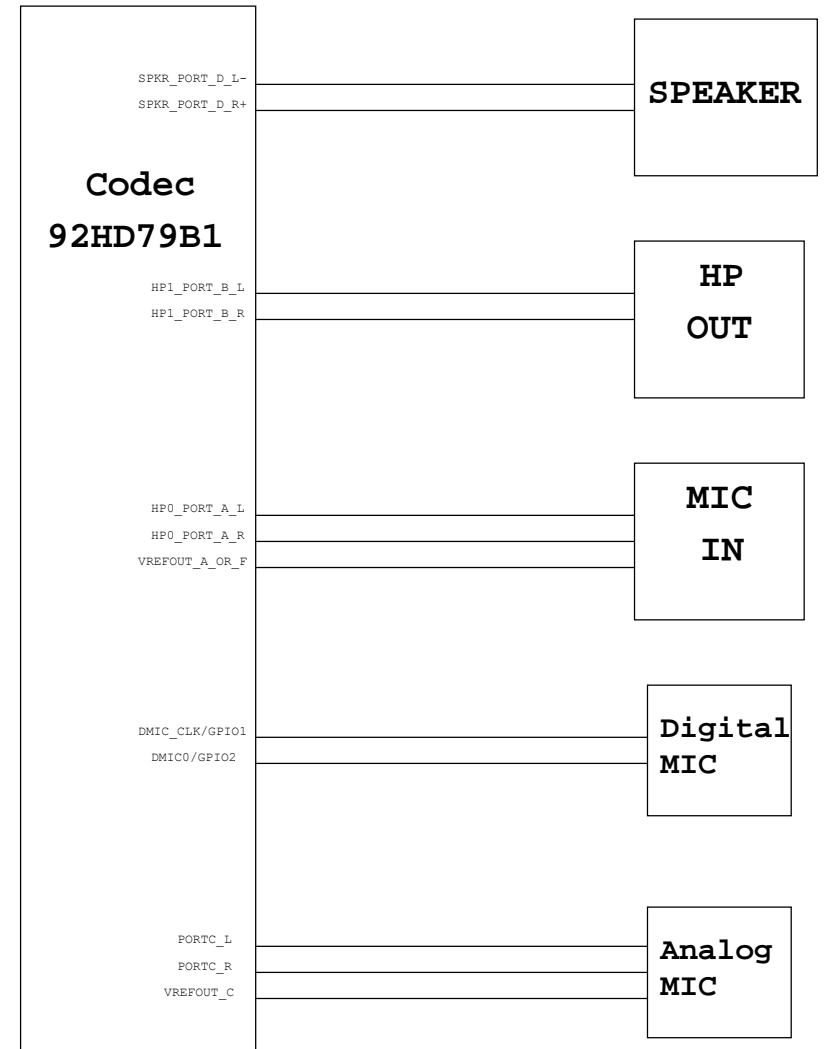
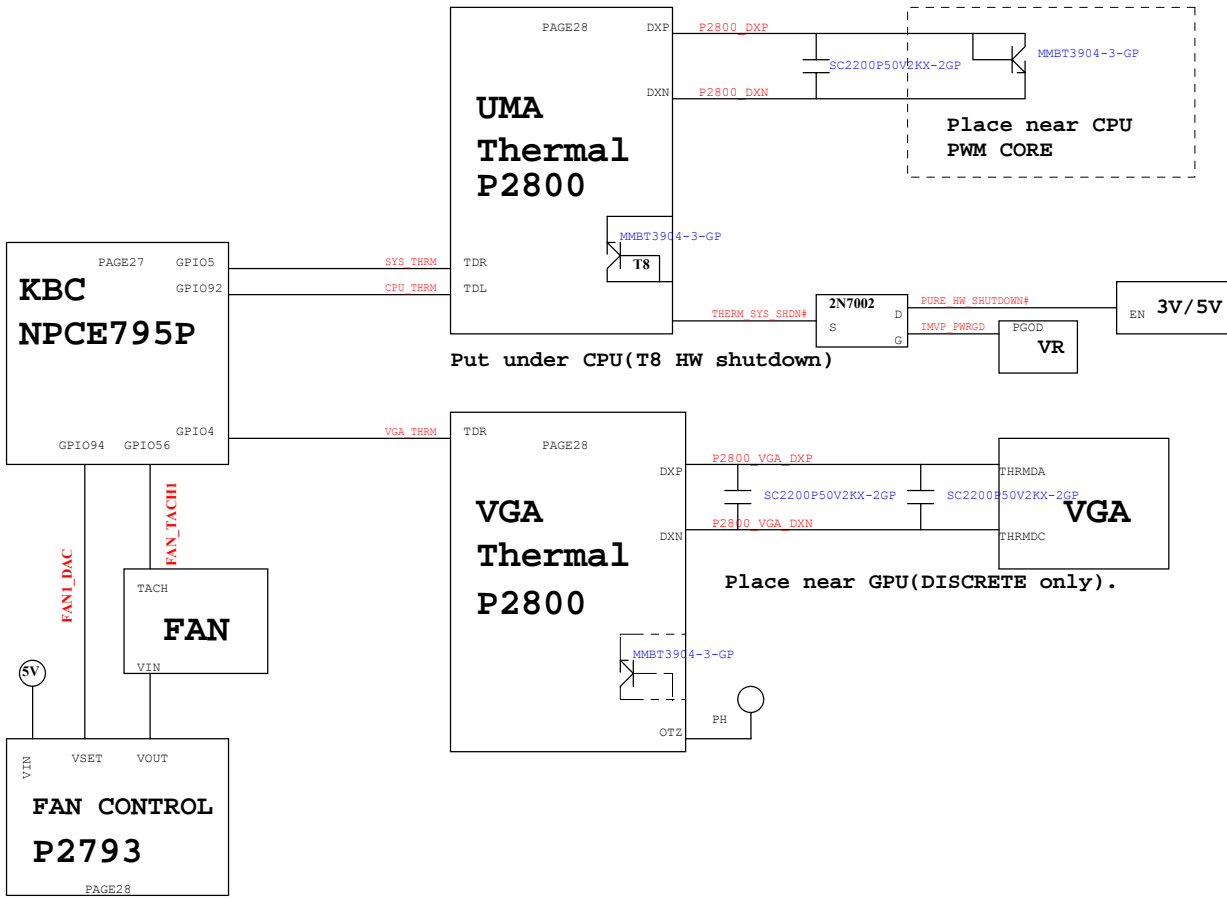
KBC SMBus Block Diagram



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Thermal Block Diagram

Audio Block Diagram



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